

**LOW POWER SAR ADC DESIGNS FOR SENSING
APPLICATIONS**

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List of Abbreviations

ECG	Electrocardiography
EEG	Electroencephalography
EMG	Electromyography
ADC	Analog-to-Digital Converter
DAC	Digital-to-Analog Converter
SAR	Successive Approximation Register
MSB	Most Significant Bit
LSB	Least Significant Bit
SNDR	Signal-to-Noise and Distortion Ratio
ENOB	Effective Number of Bits
FOM	Figure-of-Merit
DNL	Differential Nonlinearity
INL	Integral Nonlinearity
MOM	Metal-Oxide-Metal
MIM	Metal-Insulator-Metal
HVBS	High Voltage Bootstrapped Switch
DFF	D-Flip-Flop
LMS	Least Mean Square
FPGA	Field-Programmable Gate Array
ASIC	Application-Specific Integrated Circuit

Abstract

In sensing systems, ADCs are widely used in sensor interface circuits to convert analog signals to digital signals. Many of the sensing systems require ultra-low power consumption because of their limited power budget. Therefore, the design of ultra-low power ADC that meets the intended performance is a key design challenge for low power sensing applications, such as in healthcare monitoring (e.g., ECG, EEG, neural signal, etc.) and environment monitoring. Besides, a moderate sampling frequency and resolution can meet the requirement of these sensing applications. Compared to Flash ADC, Pipelined ADC and Delta-Sigma ADC, SAR ADC provides a good compromise among energy efficiency, sampling frequency and conversion accuracy for these sensing applications. In this thesis, SAR ADC is chosen as the main architecture to develop low power SAR ADC and four different designs of SAR ADC are proposed.

The first version SAR ADC consists mainly of clock boosting circuit, a subtraction and an addition capacitor array, a time-domain comparator, switching logic, output latches, level shifters and some buffers. To achieve ultra-low power, the proposed ADC operates at 0.5 V, deploying a single-ended structure and top plate sampling technique. In order to improve the linearity of the sampling circuit at ultra-low supply voltage, clock boosting circuit with gate signal swinging from 0 to $2V_{DD}$ is proposed. A non-binary redundant algorithm is applied to correct the inevitable decision errors in the first few conversion steps. From the chip measurement results, it consumes only 16-nW of power

and achieves a SNDR of 50.4 dB, which is equivalent to an 8.08 ENOB, with 1 kS/s sampling rate at 0.5-V supply voltage.

The second version SAR ADC was designed to optimize on power efficiency, for sparse signals such as the neural spike. Sparse signals have slow varying or flat characteristic across most of the duty cycle, such that the MSBs are the same if variation between two consecutive samples is small. A novel ADC deploying M-bit ADC, N-bit DAC to realize (M+N-3) bits ADC while reducing the power consumption and area is designed. The adaptive sampling scheme has also been adopted to allow selection of either a higher or lower sampling rate in event of sharp and gradual transitions, respectively. Adaptive sampling not only ensures no overflow of input signal to the M-bit ADC but can further reduce the power consumption. This 8-bit SAR ADC consists mainly of a slope detector, 6-bit ADC capacitor array, 5-bit DAC capacitor array, switching logic, dynamic comparator, latches and 8-bit full adder. The measurement results show that it can realize a SNDR of 45.7 dB, which is equivalent to a 7.3 ENOB, with 125 kS/s sampling rate at 1-V supply voltage. When the input signals are neural spikes, the total power consumption of the proposed ADC (at 2 kHz and 20 kHz sampling rates) is able to save about 88% power compared to the conventional ADC (operating at 20 kHz sampling rate).

The third version SAR ADC was designed to optimize on power efficiency in terms of system. A reference-voltage regulator-free SAR ADC with self-timed pre-charging for wireless-powered implantable medical devices was designed. Assisted by a self-timed pre-charging technique, the proposed SAR ADC eliminates the power-hungry reference-voltage regulator and the area-consuming decoupling capacitor while maintaining insensitivity to the supply

voltage fluctuation. Furthermore, with internally generated sampling clock and asynchronous SAR logics, this SAR ADC can operate at a fully asynchronous mode without any external clock source. Fabricated in the 0.18- μm CMOS technology, the proposed SAR ADC achieves a SNDR of 53.32 dB at 0.8 V with 50 mV_{pp} supply voltage fluctuation, while consuming a total power of 2.72 μW at 300 kS/s sampling rate. The total FOM is 23.9 fJ/conversion-step and the total area occupied is 0.105 mm².

The fourth design is a wide input 12-bit SAR ADC with low power and fast convergence digital background calibration. This SAR ADC is able to convert input signal with a range of 0~4.8 V, operating at 1.2-V supply. By omitting the calibration of 3 LSBs' weights, the number of multipliers or product is reduced to lower the power consumption. Besides, in order to accelerate the convergence of digital background calibration, 10 LSB offset is injected to the first 10000 samples, followed by 15 LSB offset. The ADC is designed and simulated with a 65 nm CMOS technology, and the digital background is implemented in Matlab. With background calibration, the SNDR of the ADC is improved from 59.6 dB to 65.3 dB, operating at 500 kS/s. and power consumption is 8.39 μW .

Chapter 1

Introduction

1.1 Background

The sensor nodes have been widely used in daily lives in personal telehealth [1] and tire monitoring systems [2, 3]. For the personal telehealth systems as shown in Fig. 1.1, it can acquire and process biopotential such as electrocardiography (ECG), electroencephalography (EEG), electromyography (EMG), blood pressure and so on. Thanks to the sensor nodes that are able to communicate with the outside network using standard telecommunication infrastructure [1], patients are able to carry these telehealth systems to monitor their body in real-time, anywhere and at any time. These telehealth systems have enabled the diagnosis and therapy to be a lot easier and also more efficient.

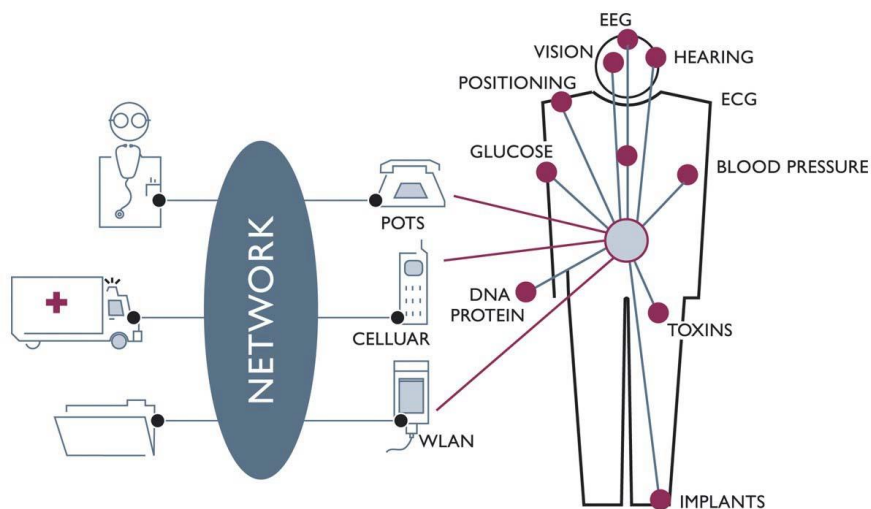


Fig. 1.1. Sensor nodes application in personal telehealth systems [1].

Also, it can possibly help reduce the overall cost of healthcare monitoring and diagnosis. In order to allow those sensor nodes to be wearable or even implantable, many efforts have been made to reduce the size and power consumption of the biomedical sensor nodes [4-8].

Another application of the sensor nodes is in the tire monitoring systems. Fig. 1.2 shows a tire monitoring system developed by Continental [2]. The tire monitoring systems have been widely used in cars to improve on safety as well as to extend the life of tires. Typically, the tire monitoring systems integrate sensors, a data processor and communication system into one device, and have the device attached to in the inner tire. The integrated sensors are able to acquire important physical parameters such as air pressure and temperature, which are used for monitoring the conditions of the tire. In some battery-less tire monitoring systems, the power are provided by the energy harvesters like the piezoelectric module [9], electromechanical transducer [10] and thermoelectric device [11]. Therefore, sensor nodes which consume low power are desirable in these monitoring systems.



Fig. 1.2. Tire monitoring system developed by Continental [2].

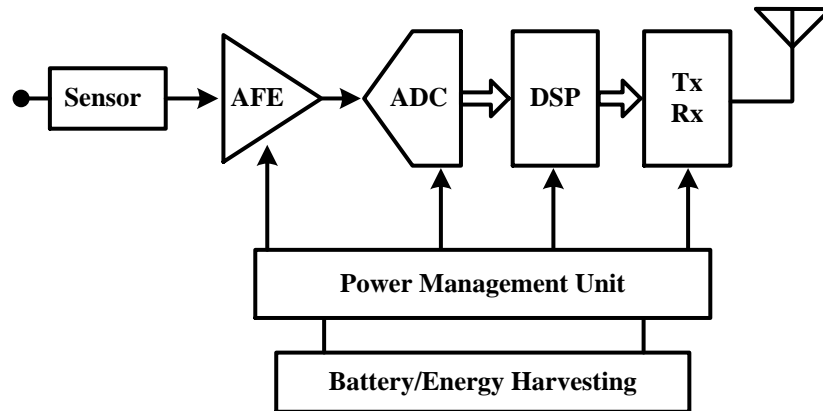


Fig. 1.3. Simplified block diagram of an intelligent sensor node.

Fig. 1.3 is a simplified block diagram of an intelligent sensor node that comprises sensor, analog front-end (AFE) block, an analog-to-digital converter (ADC), digital signal processing (DSP), transceiver/receiver, antenna, power management unit and battery/energy harvesting. The analog signals generated by the sensor will be firstly amplified and filtered by the analog front-end block. Thereafter, the ADC converts the analog output signals of the analog front-end to digital signals. The digital signal processing unit performs some signal analysis based on the digitized data output from the ADC. The transceiver/receiver and antenna transmit the analysis results to an external network. The power management unit then converts and regulates the energy from the battery/energy harvesting, to provide power for all the rest of circuits. Thanks to the complementary metal–oxide–semiconductor (CMOS) technology, all the circuit blocks, except for the battery, can be easily integrated into one monolithic integrated circuit. Such single monolithic integrated circuit not only reduces the cost of the sensor nodes but brings about massive applications of the sensor nodes.

1.2 Motivation

As mentioned in Section 1.1, the power consumption of the sensor nodes should be low but ADC is one of its most power consuming building blocks. It is therefore a major challenge to design a low power ADC for the sensor nodes, especially for those powered by battery or energy harvesting, such as the biomedical sensors and tire monitoring systems. The frequencies of those sensor signals span from DC to a few kilohertz (Hz) [12, 13]. Besides, the normal requirement of the ADC resolution is moderate, i.e., from 8 bits to 12 bits, for these sensor nodes applications [7, 8, 13-21]. This thesis therefore focuses on the design of low power ADCs with modest sampling frequency and accuracy.

The ADC architecture should be chosen based on the requirements as discussed previously, which are low power consumption, moderate sampling frequency and medium accuracy. Over the past few years, various ADC architectures, such as the delta-sigma ADC, SAR ADC, pipeline ADC, folding and interpolating ADC, and flash ADC, have been developed to minimize the power consumption for different sampling frequencies and resolutions. Fig. 1.4 shows the region where common ADCs are most energy efficiency in both bandwidth and resolution space [22]. Delta-sigma ADC consists of delta-sigma modulator, digital filter and decimator. Delta-sigma modulator shifts quantization noise to higher frequency domain, and low pass digital filter is used to filter the shaped noise. Thanks to the noise shaping techniques, delta-sigma ADC can realize extremely high resolution, typically more than 12 bits [23]. Since delta-sigma ADCs operate at oversampling rate, it is normally used to convert low frequency analog signals. The SAR ADC architecture is ideally

suited for moderate speed and medium resolution ADCs due to its simplicity and highly digital nature. With proper calibration techniques, SAR ADC can also achieve 16 bits [24]. Although pipeline ADCs can achieve high resolution, one operational amplifier is required in each pipeline stage. Also, the operational amplifier working in closed-loop must have wide bandwidth and high gain. The pipeline ADCs are therefore relatively power hungry [25]. For medium resolution and high sampling frequency applications, the folding and interpolating ADCs can offer high energy efficient. This is because they are based on nonlinear analog preprocessing where high linearity circuits are not required. The flash ADCs with high speed and low resolution are typically used for application such as radar detection, wide band radio receivers and flash memory. As the number of comparator grows exponentially with its resolution, flash ADC becomes unattractive for applications that require more than 8 bits [25].

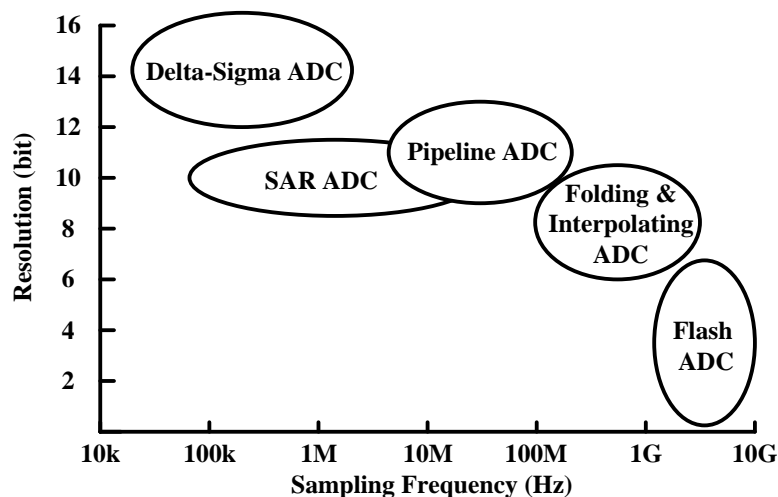


Fig. 1.4. Energy efficiency of various ADC architectures in the bandwidth-resolution space.

As discussed above, SAR ADC is the most attractive architecture for the targeted application, which is the sensor nodes application. This thesis will describe several novel SAR ADC designs, both on circuit and at the system level, to achieve high energy efficiency.

1.3 Contribution

This thesis focuses on low power SAR ADC designs for sensor nodes applications. Literature has shown that SAR ADC has higher energy efficiency than other ADC architectures for moderate speed and medium resolution applications. By exploring novel designs to minimize power consumption, a number of contributions have been achieved:

- A non-binary redundant SAR ADC operating at ultra-low supply voltage, i.e., 0.5 V, is proposed. In order to improve the linearity of sampling circuit at 0.5 V supply voltage, a clock boosting circuit with gate signal swinging from 0 to 1 V is designed.
- Adaptive delta-sampling ADC is designed to achieve high power efficiency for sparse signals such as the neural spike. By sampling only the incremental value of the input signal and adaptively adjusting the sampling frequency, the proposed ADC can achieve the same resolution and conversion range with less number of bits than the conventional ADC, and thus the power consumption can be significantly reduced.
- Reference-voltage regulator free SAR ADC is designed for wireless-powered implantable medical devices. Assisted by a self-timed pre-charging

technique, the proposed SAR ADC eliminates the power-hungry reference-voltage regulator and the area-consuming decoupling capacitor while maintaining insensitivity to the supply voltage fluctuation. This SAR ADC achieves higher FOM than other state-of-art designs in terms of system.

- A wide-input range 12-bit SAR ADC with low power and fast convergence digital background calibration is designed for sensor nodes when battery voltage measurement is required. This SAR ADC is able to convert input signal with a range of $9.6 V_{pp}$, operating at 1.2 V supply voltage. In order to sample such high input voltage, a high-voltage sampling switch is proposed. Low power and fast convergence digital background calibration is realized by omitting the calibration of 3 LSBs' weights and injecting different analog offset during calibration.

1.4 Organization

This thesis is organized as follows. Chapter 1 provides the background of this research and presents an overview of various ADC architectures for different sampling rates and resolutions applications, leading to the motivation of this work. The contributions of this work are also listed.

Chapter 2 provides a literature review of the state-of-the-art low power SAR ADCs both in circuit and at system levels. Besides, the calibration of capacitor mismatch in SAR ADC is also reviewed.

Chapter 3 presents an ultra-low power SAR ADC designs. A 9-bit SAR ADC design with non-binary generalized redundant algorithm, operating at 0.5

V supply voltage is described. Further to that, two sensor nodes using the proposed SAR ADC as their analog to digital interface circuits are presented.

Chapter 4 presents an adaptive delta-sampling ADC that utilizes the characteristics of the sparse signal. The characteristic of sparse signals including EEG and neural spikes are analyzed. The measurement result verifying the ADC's conversion of pre-recorded neural signal is also given in Section 4.7 .

Chapter 5 presents a reference-voltage regulator-free SAR ADC with self-timed pre-charging for wireless-powered implantable medical devices. The effect of reference voltage fluctuation on SAR ADC is also evaluated. Thereafter, a SAR ADC without the power-hungry reference-voltage regulator and the area-consuming decoupling capacitor is proposed. The design is able to remain insensitive to the supply voltage fluctuation.

Chapter 6 presents a wide input 12-bit SAR ADC with low power and fast convergence digital background calibration. A high-voltage sampling switch is then described. Simulation results are also provided to validate the proposed low power and fast convergence digital background calibration.

Lastly in Chapter 7, the conclusions are drawn. Some future works on the design of low power SAR ADC for sensing applications are then discussed.

Chapter 2

Background and Literature Review

As discussed in the previous chapter, SAR ADC is the most energy efficient architecture for sensing application. This begins first by reviewing the conventional SAR ADC. A brief discussion on several low power design considerations in conventional SAR ADC is then given. Based on the conventional SAR ADC, some energy efficient ADC architectures for sparse signals acquisitions are described. These ADC architectures utilize some characteristics of the input signals to reduce the power consumption. Following which, some ADC designs look with focusses on optimizing the peripheral circuits blocks that provide supply voltage and clock source to the ADC core are described. In the last section, some calibration techniques for capacitor mismatch in SAR ADC are detailed.

2.1 Conventional SAR ADC

The architecture and operation of the conventional SAR ADC [26] is described in this section. Fig. 2.1 shows the block diagram of a 3-bit SAR ADC. It consists of a sample and hold (S/H) circuit, a 3-bit capacitor array, a comparator and successive approximately logic. An example of the bit cycling waveforms is illustrated in Fig. 2.2, where by its reference voltage V_{ref} is 1 V and input signal is of 0.4 V. The operation of the conventional SAR ADC is described as follows. During the sampling phase, the input signal is sampled and stored in the S/H circuit. In practice, the S/H circuit is usually combined

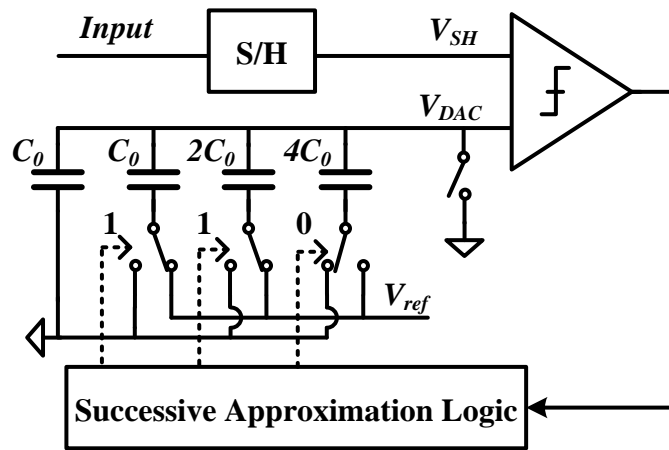


Fig. 2.1. Block diagram of a 3-bit conventional SAR ADC.

with a capacitor array through sampling the input signal into the capacitor array. During the bit cycling period, the digital output bits are determined serially from MSB to LSB. In the first bit cycle, the MSB b_2 is set to '1', while b_1 and b_0 are both set to '0'. Thus, the MSB capacitor and the rest of the capacitors are connected to V_{ref} and ground. Consequently, the voltage of the capacitor array V_{DAC} is 0.5 V. Since V_{DAC} is larger than the sampled and held voltage V_{SH} , b_2 is returned and latched to '0'. After the first approximation, b_1 and b_0 are set to '1' and '0', respectively, generating $V_{DAC} = 0.25$ V. Since V_{DAC} is less than V_{SH} , b_1

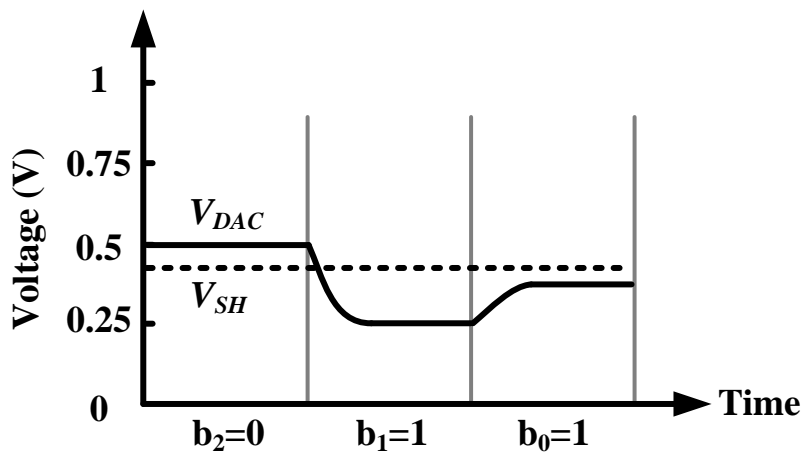


Fig. 2.2. Waveforms of V_{DAC} and V_{SH} during the bit cycling period.

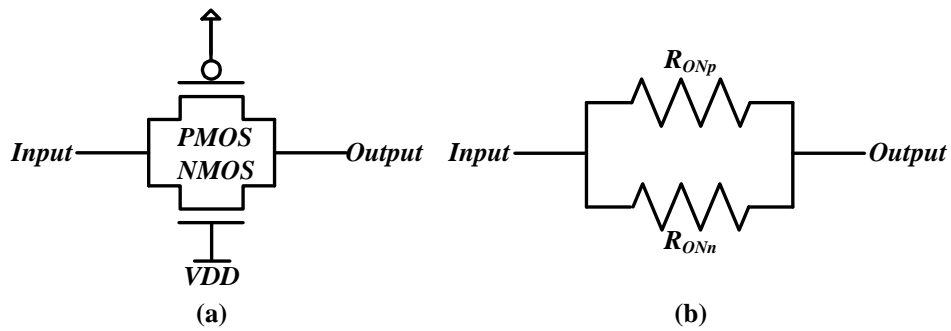


Fig. 2.3. (a) CMOS transmission gate. (b) Model for effective resistance of a transmission gate.

is latched to '1'. The approximation process is continued in this way until all bits are determined. The final output code is $b_2b_1b_0 = 011$.

2.2 Ultra-Low Power Design Considerations in Typical SAR ADC

The power dissipation of conventional SAR ADC mainly includes the power consumed by successive approximation logic, capacitor switching, and the comparator. Therefore, the ADC power consumption benefits from the scaling down of the operating voltage and by adopting an energy efficient capacitor switching method.

2.2.1 Clock Boosting

In the ideal sampling circuit, the on-resistance is zero and off-resistance is infinite, respectively. However, for the single MOS transistor switch, the on-resistance, given by Equation (2.1) depends on the gate-to-channel voltage V_{GS} minus the threshold voltage V_{th} , with a transistor size ratio W/L .

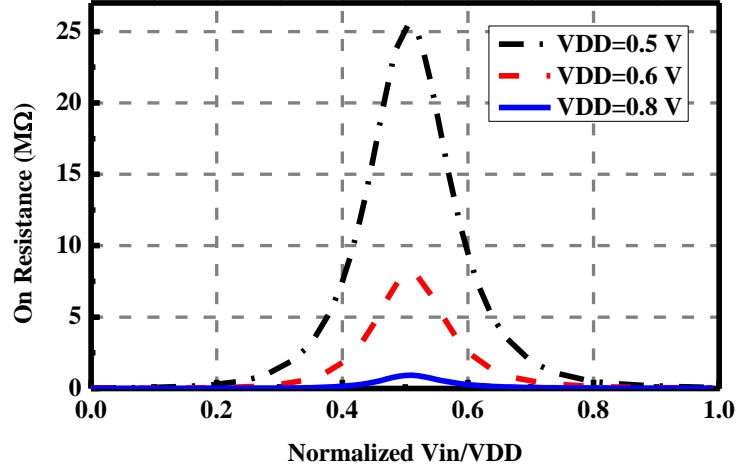


Fig. 2.4. On-resistance of transmission gate for input range from 0 to VDD for VDD from 0.5 V to 0.8 V.

$$R_{ON} = \frac{\partial V_{DS}}{\partial I_{DS}} = \frac{1}{\mu C_{ox} \frac{W}{L} (V_{GS} - V_{th})} \quad (2.1)$$

Also, the single NMOS and PMOS switch is conductive only when input voltage is larger than a threshold voltage below the gate voltage and larger than a threshold above the ground, respectively. In sampling circuit, the transmission gate whose effective resistance is $R_{ONn} \parallel R_{ONp}$, combination of NMOS and PMOS, is commonly used to compensate the weaknesses of NMOS and PMOS (see Fig.

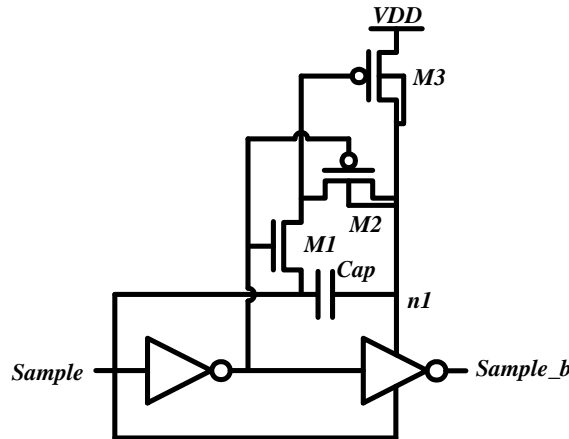


Fig. 2.5. Voltage boosting circuit.

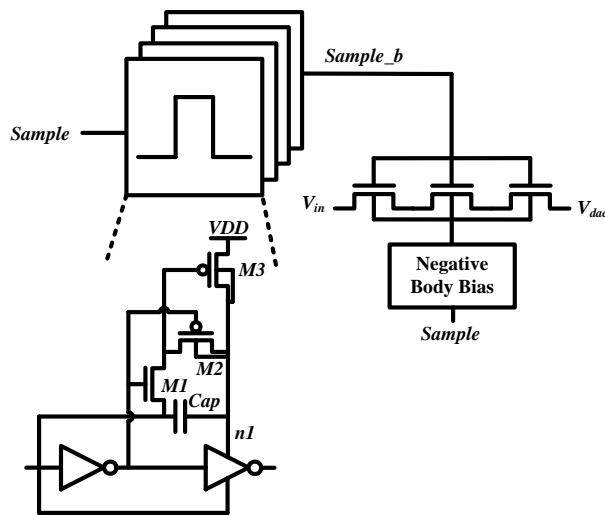


Fig. 2.6. Modified sampling switch.

2.3). Without special clarification, the transistors used in this thesis are zero body bias, i.e., the body of the NMOS and PMOS are connected to ground and supply voltage, respectively. And the triple-well is not used by default. Unfortunately, the transmission gate settling time becomes large at ultra- low supply voltage, due to large on-resistance, and given in Fig. 2.4 is the simulated on-resistance of the transmission gate. As can be seen, the on-resistance increases dramatically when VDD drops from 0.8 V to 0.5 V. Without improving the switch performance, it will be impossible to archive an ultra-low voltage SAR ADC.

To improve the linearity of sampling switch, one can use resistor-based sampling techniques [27], constant bootstrapping techniques [28] and the reduction of the on-resistance [29]. However, the resistor-based sampling techniques and the constant bootstrapping techniques for extreme voltage and frequency scaling conditions are extremely challenging. Fig. 2.5 shows the circuit implementation for reduction of on-resistance of the sampling switch and with improved linearity [29]. When sampling clock signal $Sample$ is at low, $M1$

and $M3$ are turn on, and $M2$ is turn off. Consequently, the voltage of the node $n1$ is charged to VDD . During the next phase, when $Sample$ is high, Cap is charged with a potential difference, VDD . At the same time, $M2$ is turn on while $M1$ and $M3$ are turn off. As a result, the voltage of $Sample_b$ is ideally boosted to $2VDD$. Because the voltage of the boosted signal $Sample_b$ depends on the ratio between Cap and the parasitic capacitance associated with the node $n1$. The size of the capacitor can be either several times of the parasitic capacitance or the minimum capacitor available in the process, whichever is smaller. Based on this design, [30] the novel sampling switch of Fig. 2.6, employing 4-stage voltage boosting, device stacking and negative body bias, is designed with 160 mV supply voltage. It is proved by increasing the number of cascaded voltage boosting circuit, one that can improve the sampling switch linearity; but when more than four stages are cascaded the improvement is limited. A 3-stacked NMOS transistors biased by negative body voltage is therefore employed to minimize switch leakage, reducing leakage introduced error. The SAR ADC employing this sampling switch can achieve 7.3 ENOB under 160-mV power

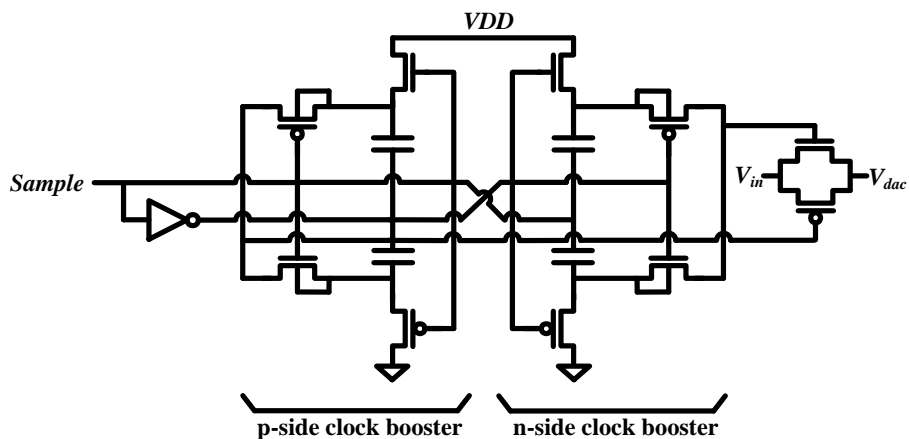


Fig. 2.7. The schematic of LRBS.

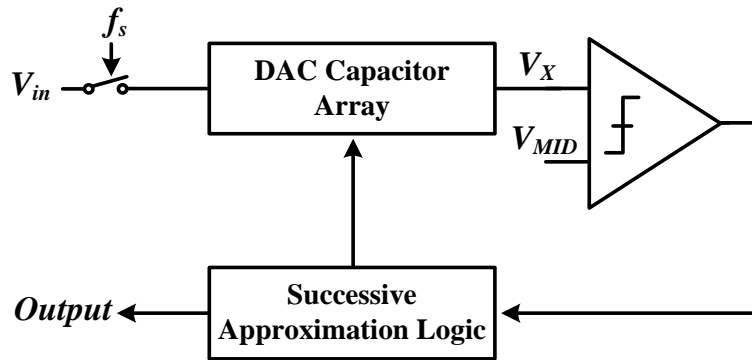


Fig. 2.8. Block diagram of SAR ADC.

supply with 40 kS/s sampling rate, while consuming 670 nW power [30].

The voltage boosting circuit of Fig. 2.5 exists static power consumption. A leakage reduction bootstrapped switch (LRBS), as shown in Fig. 2.7, was then proposed [31]. The p-side clock and n-side clock booster are used to generate boosted high voltage and boosted low voltage, respectively. These clock boosters are not only able to reduce the transmission gate on-resistance but also increase the off-resistance to eliminate subthreshold voltage.

2.2.2 Energy Efficient Capacitor Array Switching Method

The switching of capacitor array and comparator are the two dominant sources of power consumption in SAR ADC. [32] discusses four different switching methods in SAR ADC (see Fig. 2.8): 1-step switching, 2-step switching, charge sharing, and capacitor splitting. One of a 2-bit capacitor array is shown in Fig. 2.9 (a). Here, we define “up” transition when C_2 remains connected to V_{ref} (i.e., the first comparison is low) and with C_1 connected to V_{ref} for next conversion step. On the contrary, “down” transition is when C_2

returned to ground (i.e., the first comparison is high) and C_1 connected to V_{ref} for next conversion step. During each conversion step, either the “up” or “down” transition occurs. All four switching methods behave identical during the “up” transition and consume the same energy, which can be express as:

$$E_{up} = 4C_0 \left(\frac{V_{ref}}{2} \right)^2 + 4C_0 \left(\frac{3}{4}V_{ref} - \frac{V_{ref}}{2} \right)^2 = \frac{5}{4}C_0V_{ref}^2 \quad (2.2)$$

But they differ for the “down” transition and so does energy efficiency. Fig. 2.9 (a) shows a 2-bit capacitor array for the 1-step and 2-step switching methods. While (b) and (c) indicate “down” transition energy calculation models for the 1-step and 2-step switching methods, respectively. In 1 step switching method, the energy drawn from V_{ref} is $E_{1-2,1 step}$, where

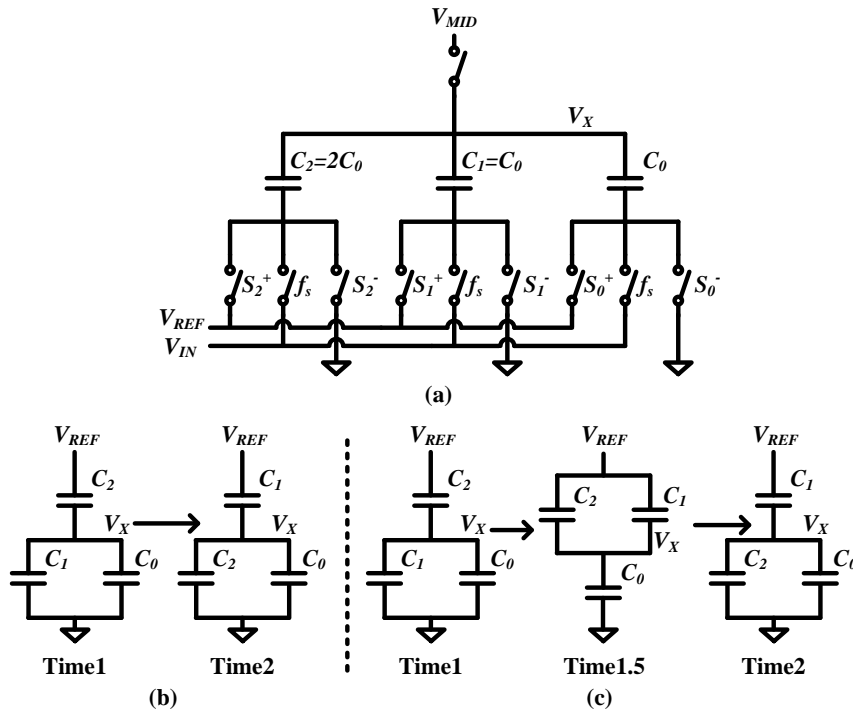


Fig. 2.9. (a) 2-bit capacitor array for 1-step and 2-step switching methods. (b) “Down” transition for 1-step switching. (c) “Down” transition for 2 step switching method.

$$\begin{aligned}
E_{1-2,1 \text{ step}} &= \int_T^{2T} i_{ref}(t) V_{ref} dt = V_{ref} \int_T^{2T} i_{ref}(t) dt = -V_{ref} \int_T^{2T} \frac{dQ_{C1}}{dt} dt = -V_{ref} \int_{Q_{c1}(T)}^{Q_{c1}(2T)} dQ_{C1} \\
&= -V_{ref} (Q_{c1}(2T) - Q_{c1}(T)) \quad (T \text{ is capacitor settling time and assumed as } 1) \\
&= -V_{ref} C_0 \left((V_X [2] - V_{ref}) - V_X [1] \right) \\
&= -V_{ref} C_0 \left(\left(V_{MID} - V_{IN} + \frac{V_{ref}}{4} - V_{ref} \right) - \left(V_{MID} - V_{IN} + \frac{V_{ref}}{2} \right) \right) \\
&= \frac{5}{4} C_0 V_{ref}^2
\end{aligned} \tag{2.3}$$

For the 2-step switching method, the energy drawn from V_{ref} be $E_{1-1.5,2 \text{ step}}$ from Time1 to Time1.5, and $E_{1.5-2,2 \text{ step}}$ from Time1.5 to Time2.

$$\begin{aligned}
E_{1-1.5,2 \text{ step}} &= -V_{ref} \left((Q_{C2}(1.5) - Q_{C2}(1)) + (Q_{C1}(1.5) - Q_{C1}(1)) \right) \\
&= -V_{ref} \left(2C_0 \left((V_X [1.5] - V_{ref}) - (V_X [1] - V_{ref}) \right) + C_0 \left((V_X [1.5] - V_{ref}) - V_X [1] \right) \right) \\
&= -V_{ref} 2C_0 \left(\left(V_{MID} - V_{IN} + \frac{3V_{ref}}{4} - V_{ref} \right) - \left(V_{MID} - V_{IN} + \frac{V_{ref}}{2} - V_{ref} \right) \right) \\
&\quad - V_{ref} C_0 \left(\left(V_{MID} - V_{IN} + \frac{3V_{ref}}{4} - V_{ref} \right) - \left(V_{MID} - V_{IN} + \frac{V_{ref}}{2} \right) \right) \\
&= \frac{1}{4} C_0 V_{ref}^2
\end{aligned} \tag{2.4}$$

Thus, the total switching energy of 2 step switching method is:

$$\begin{aligned}
E_{1-2,2 \text{ step}} &= E_{1-1.5,2 \text{ step}} + E_{1.5-2,2 \text{ step}} \\
&= \frac{1}{4} C_0 V_{ref}^2 + \frac{1}{2} C_0 V_{ref}^2 \\
&= \frac{3}{4} C_0 V_{ref}^2
\end{aligned} \tag{2.5}$$

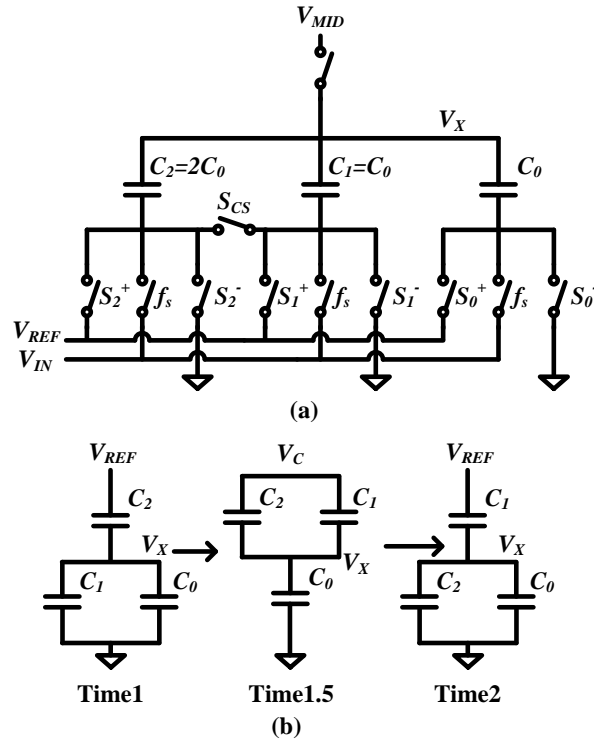


Fig. 2.10. (a) 2-bit capacitor array. (b) “Down” transition for charge sharing switching method.

The switching energy of 2-step is less than 1-step switching method. This is because some of the charges from the largest capacitor are used to charge up the second capacitor [32]. Charge sharing is an extension of this energy saving method, as depicted in Fig. 2.10. During the first switching phase, C_2 and C_1 are disconnected from both V_{ref} and ground. Instead, these two capacitors are connected each other through switch S_{CS} . According to charge retribution, the node voltage V_C at Time1.5 is:

$$V_C [1.5] = \frac{2}{3} V_{ref} \quad (2.6)$$

From Time1 to Time1.5, no energy is drawn from V_{ref} , but C_1 voltage is charge to $V_C(1.5)$. In the second switching phase, C_2 and C_1 are connected to

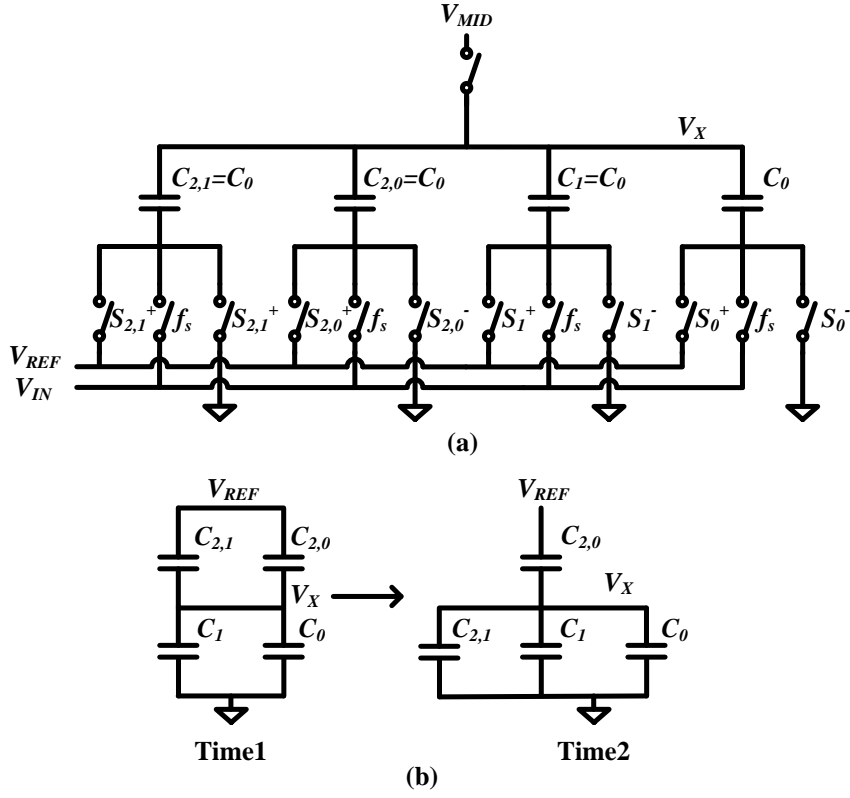


Fig. 2.11. (a) 2-bit capacitor array, (b) “Down” transition for capacitor splitting switching method.

V_{ref} and ground, respectively. Therefore, the total energy dissipated in charge sharing switching method is $E_{1-2,CS}$:

$$\begin{aligned}
 E_{1-2,CS} &= -V_{ref} (Q_{C1}(2T) - Q_{C1}(T)) \\
 &= -V_{ref} C_0 \left((V_X[2] - V_{ref}) - (V_X[1] - V_C[1.5]) \right) \\
 &= -V_{ref} C_0 \left(\left(V_{MID} - V_{IN} + \frac{V_{ref}}{4} - V_{ref} \right) - \left(V_{MID} - V_{IN} + \frac{V_{ref}}{2} - \frac{2}{3} V_{ref} \right) \right) \quad (2.7) \\
 &= \frac{7}{12} C_0 V_{ref}^2
 \end{aligned}$$

Even though charge sharing is more energy efficient than the previous two switching methods, i.e. 1-step and 2-step switching method, energy are still to be drawn from V_{ref} for charging C_1 since $V_C(1.5)$ is less than V_{ref} . The capacitor splitting approach proposed by [32], as shown in Fig. 2.11, can avoid charging

Table 2.1 Switching Method Comparison

Method	Energy consumed by “up” transition	Energy consumed by “down” transition	Number of switches
1 step	$\frac{5}{4} C_0 V_{ref}^2$	$\frac{5}{4} C_0 V_{ref}^2$	3
2 step	$\frac{5}{4} C_0 V_{ref}^2$	$\frac{3}{4} C_0 V_{ref}^2$	3
Charge sharing	$\frac{5}{4} C_0 V_{ref}^2$	$\frac{7}{12} C_0 V_{ref}^2$	4
Splitting	$\frac{5}{4} C_0 V_{ref}^2$	$\frac{1}{4} C_0 V_{ref}^2$	4

of any capacitor to V_{ref} in the “down” transition. The MSB capacitor C_2 is split into two capacitors, $C_{2.1}$, $C_{2.2}$. During “up” transition, both $C_{2.1}$ and $C_{2.2}$ are connected to V_{ref} . But during “down” transition, instead of connecting C_1 to V_{ref} , $C_{2.1}$ is simply connected directly to ground. Therefore, the energy dissipated in “down” transition is $E_{1-2,split}$:

$$\begin{aligned}
 E_{1-2,split} &= -V_{ref} (Q_{C1}(2T) - Q_{C1}(T)) \\
 &= -V_{ref} C_0 \left((V_X[2] - V_{ref}) - (V_X[1] - V_{ref}) \right) \\
 &= -V_{ref} C_0 \left(\left(V_{MID} - V_{IN} + \frac{V_{ref}}{4} - V_{ref} \right) - \left(V_{MID} - V_{IN} + \frac{V_{ref}}{2} - V_{ref} \right) \right) \quad (2.8) \\
 &= \frac{1}{4} C_0 V_{ref}^2
 \end{aligned}$$

The capacitor splitting method dissipates only one fifth of energy for the conventional 1-step switching method during “down” transition. In terms of overall switching energy, the capacitor splitting consumes the least energy among the previously discussed switching approaches, saving 37% of energy compared to the conventional 1-step switching method [32].

Table 2.1 summarizes the power consumption and the number of switches required in the four capacitor switching methods for a 2-bit SAR ADC as

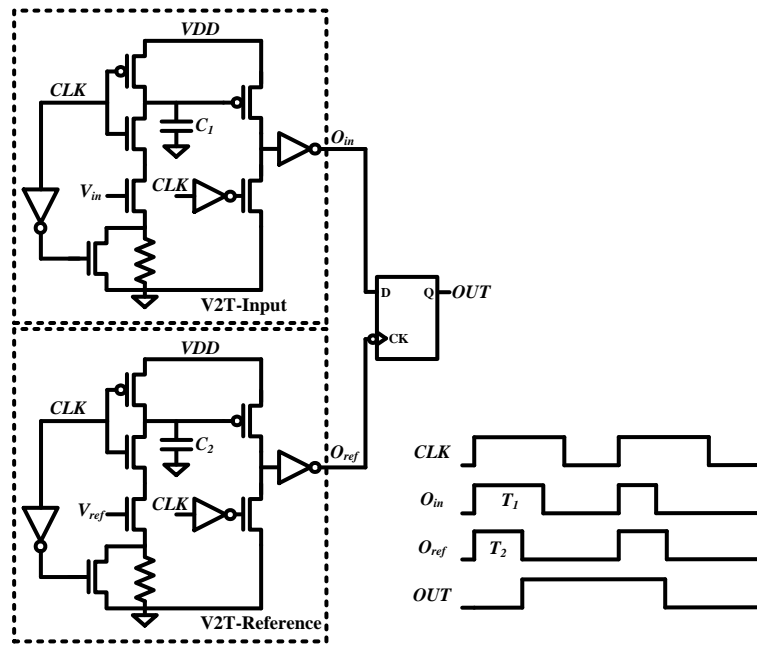


Fig. 2.12. Schematic and timing diagram of the time-domain comparator with flip-flop based phase detector.

described above. It can be seen that the split switching method is the most energy efficient switching method.

2.2.3 Low Voltage Comparator

The power consumption and accuracy of comparator very much determine the overall SAR ADC performance. Time-domain comparator with highly digital architecture, proposed by [33], benefits from lowering supply voltage and sampling rate. Fig. 2.12 shows the schematic of time-domain comparator with flip-flop based phase detector. When signal Φ_C is low, C_1 and C_2 are charged to VDD and equally. When CLK rises, C_1 and C_2 are discharged with different amount of current each controlled by the input and reference voltage, respectively. Consequently, the voltage across C_1 and C_2 drops and generated two pulses with duration T_1 and T_2 .

However, this time-domain comparator with flip-flop based phase detector is sensitive to the setup and hold time uncertainties of the flip-flop and is not suitable for ultra-low voltage operation. [34] developed a time-domain comparator, consisting of two highly digital differential voltage-controlled delay lines (VCDL) and an offset-free binary phase detector, as shown in Fig. 2.13. Because this time-domain comparator deploys highly digital differential delay architecture and offset-free binary phase detector, it is suitable for SAR ADC operating at ultra-low voltage.

2.3 Signal-based Low Power SAR ADC

In previous section, some low power circuits for SAR ADC designs have been reviewed. In this section, low power ADC designs with novel architecture are presented. According to the Nyquist–Shannon sampling theorem, the sampling rate of an ADC is restricted to at least two times the input bandwidth. However, when the ADC is employed to convert burst-like or sparse signals such as neural spike, ECG and accelerometer waveforms, the sampling rate can change according to the shape of the signals [5, 18, 35]. By deploying the signals’ frequency and amplitude features, the ADCs proposed in [5, 18, 35] were able to achieve high energy efficiency.

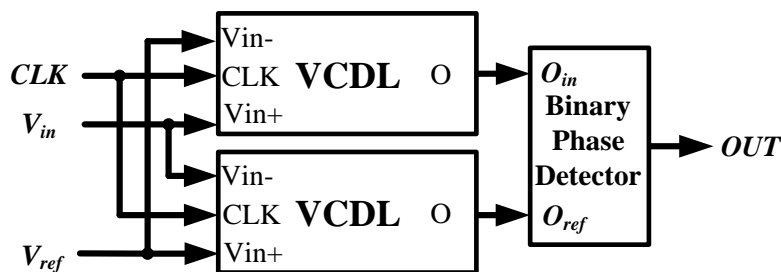


Fig. 2.13. Block diagram of time-domain comparator.

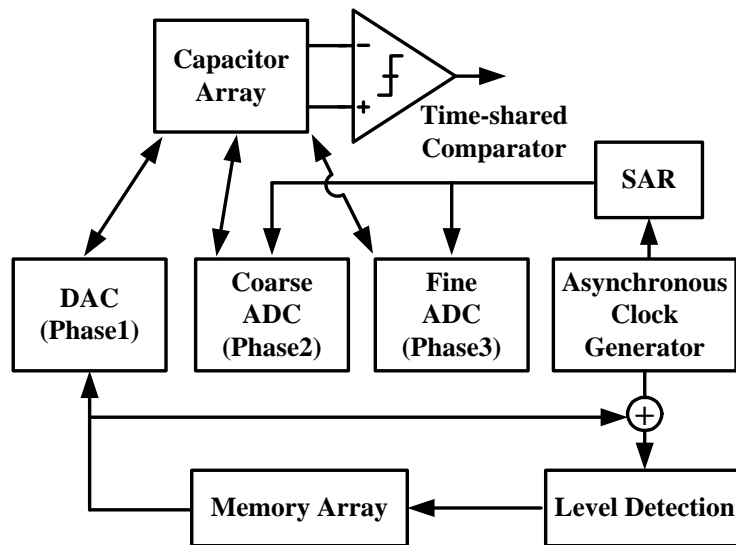


Fig. 2.15. The architecture of DMSAR ADC.

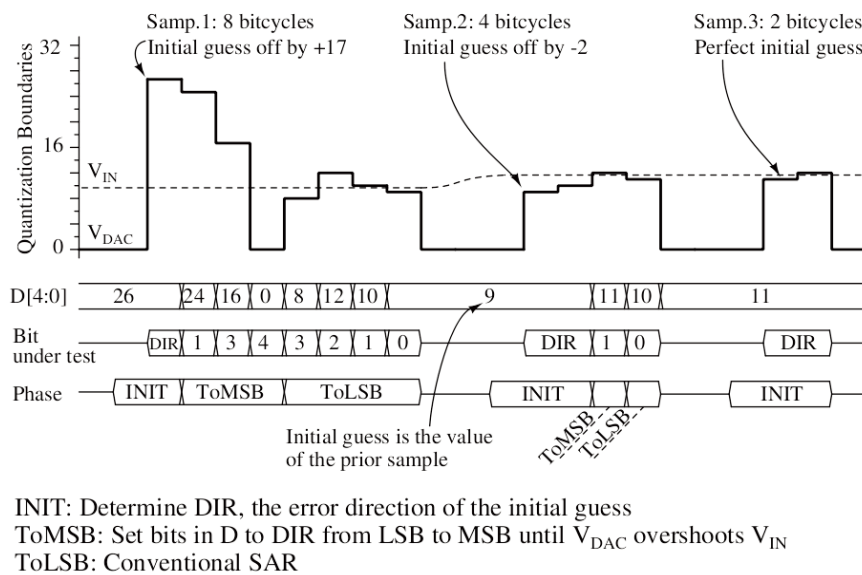


Fig. 2.16. Example of 5 bit conversions using LSB-first successive approximation.

voltage difference between two consecutive samples so as to reduce the number of conversion steps to achieve low power consumption is proposed by [17]. The architecture of the DMSAR ADC is given in Fig. 2.15. The ADC completes the conversion in three phases. During the first phase, the DAC sample the input

signal and the previous sample stored in the memory. Also, the DAC generates a voltage difference between these consecutive samples. Then, the coarse ADC decides the range of this generated voltage difference. The LSBs are determined during the third phase. Even though the conversion step is reduced, the circuit needs to ensure oversampling at all time, which makes it not energy-efficient.

A LSB-first SAR ADC that made use of its previous sample as an initial guess for its current sample is proposed in [35, 36]. Fig. 2.16 shows an example of a 5-bit conversion using LSB-first successive approximation algorithm. The conversion completes in three phases, i.e., INIT, ToMSB and ToLSB. In the INIT phase, the previous sample is set as the initial guess. DIR is the error direction of the initial guess, indicating the initial guess is larger or smaller than the current sample, i.e., V_{IN} . During the ToMSB phase, V_{DAC} is moved to approximate V_{IN} until V_{DAC} overshoots the target value V_{IN} . The DAC step size is set from LSB to MSB, which is inverted in conventional successive approximation algorithm. In the ToLSB phase, the algorithm performs the same bitcycling proceeds as in conventional successive approximation algorithm. The bitcycles of the LSB-first successive approximation algorithm is from 2

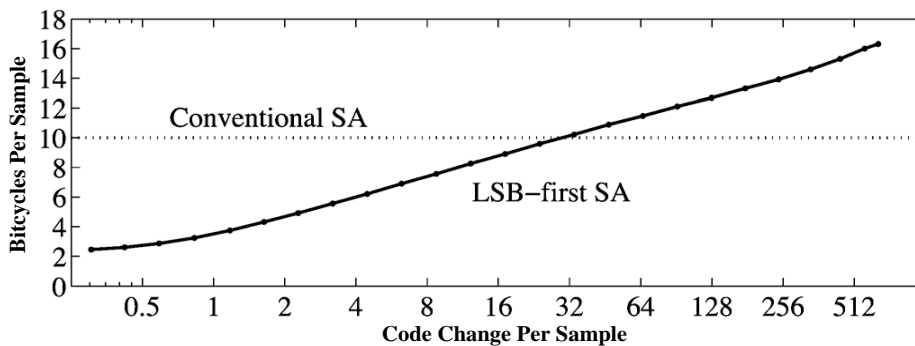


Fig. 2.17. Bitcycles per sample as a function of code charge per sample for a 10-bit LSB-first SAR ADC.

bitcycles to $2N+1$ bitcycles for an N -bit SAR ADC. Fig. 2.17 indicates the bitcycles required for each complete conversion as a function of code change per sample. It can be seen that if the code change per sample is larger than 32, the LSB-first SAR ADC will require more conversion steps than the conventional SAR ADC.

2.4 System Level Design Considerations of Low Power ADC

As reviewed in Section 2.2 and Section 2.3, much emphasis has been on designing energy-efficient circuit blocks in the ADC, including operating at ultra-low voltage [27-30], the energy-efficient switching capacitor method [32, 37-40], low power comparator [33, 34, 41], and innovative low power ADC architecture using signals' frequency and amplitude features [5, 18, 35]. However, there are a few ADC designs that considered achieving low power at system level. In other words, few designs had focused on relaxing or removing

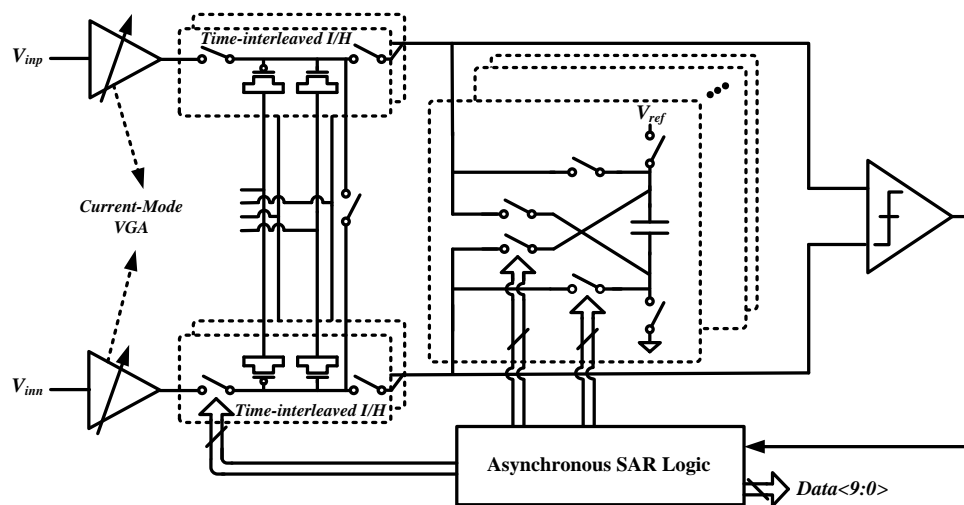


Fig. 2.18. Top-level current-integrating SAR ADC architecture.

the blocks that provide inputs to the ADC, i.e., the input signal [42], voltage reference [43] and clock source [44].

In [42], a current-integrating SAR ADC was described to save on power consumption for the circuits that provide input signal to the ADC. A power efficient variable-gain transconductor is used to replace the power hungry input voltage buffer in a charge-sharing SAR ADC to improve the overall power efficiency. The top architecture of the ADC with variable gain amplifier (VGA) is depicted in Fig. 2.18. The current-mode VGA converts input voltage to current and this current is converted to a charge on the MOS capacitors by the time-interleaved integrate-and-hold (I/H). Then, the MOS capacitors perform a voltage passive amplification by switching the capacitor from inversion to depletion mode, which relaxes the comparator noise requirement. After that, the

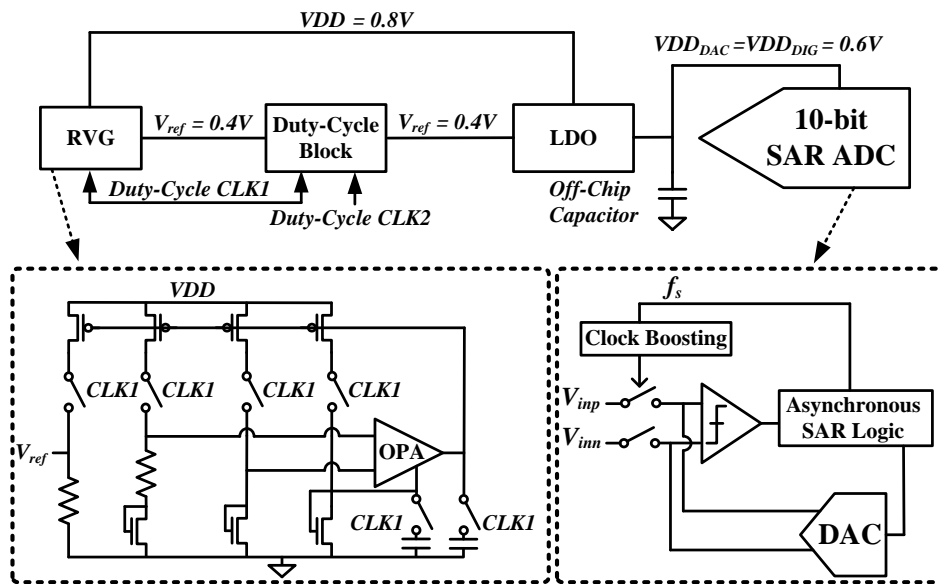


Fig. 2.19. ADC with integrated reference, circuit diagram of the RVG and architecture of the 10-bit SAR ADC.

ADC performs quantization as that of the charging-sharing SAR ADC [45].

[43, 46] proposed a SAR ADC with integrated reference voltage generator (RVG), as shown in Fig. 2.19. The RVG generates a reference voltage. A duty-cycle block is used to stabilize the reference voltage when RVG is turned off. A conventional low-dropout regulator (LDO) is adopted to power the ADC core. By applying the duty-cycle technique for the reference voltage generator, this SAR ADC can reduce the power consumption at system level. However, the always-on LDO leads to quiescent current and dropout voltage. Fig. 2.20 shows the power consumption of the ADC with RVG versus its duty-cycling rate. When the duty-cycling rate is lowered to 10%, the power consumption of the RVG becomes negligible. However, the power dissipated by the regulator is a constant and it accounts for more than 30% of the total power consumption of the SAR ADC. Besides, large decoupling capacitor is needed to maintain a stable operation of the regulator.

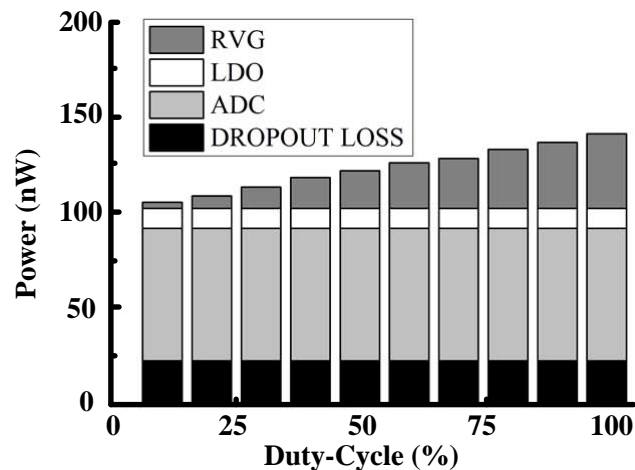


Fig. 2.20. Power consumption of the ADC with RVG versus duty-cycling rate.

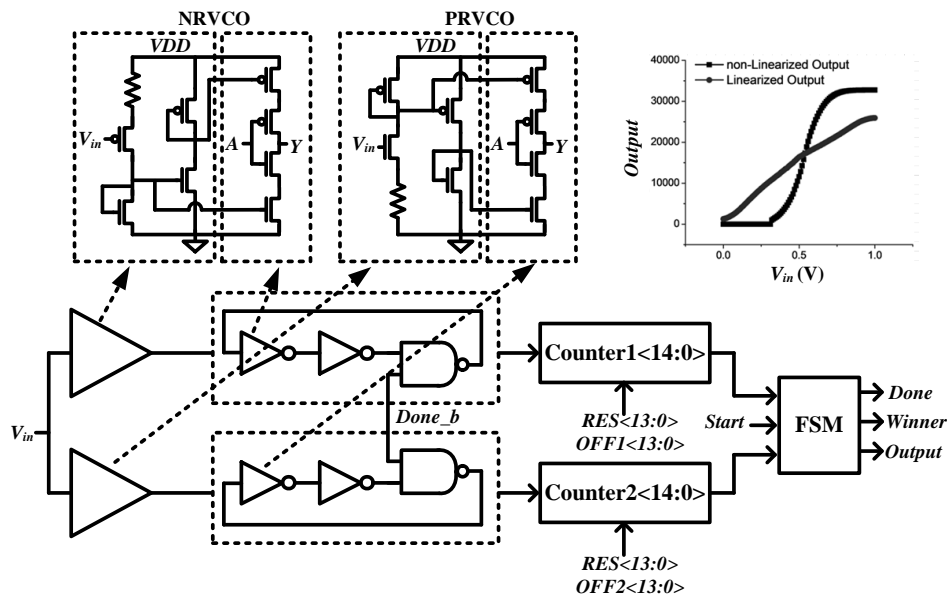


Fig. 2.21. Block diagram of the asynchronous VCO-based sensor interface.

An asynchronous VCO-based sensor interface of Fig. 2.21 was described in [44]. It is able to do away with the high accuracy voltage sources and low jitter timing references. The analog input signal is first converted into two frequencies using two VCOs, i.e., positive response VCO (PRVCO) and negative response VCO (NRVCO). Then, the outputs of these two VCOs are fed to counters for digitization. The digitization is self-timed and terminates when one of the two counters triggers an MSB transition. The finite state machine (FSM) is used to detect this MSB transition and hence stop the oscillation of the VCOs.

2.5 Calibration of Capacitor Mismatch in SAR ADC with Advanced CMOS Technology Node

The power dissipated by switching capacitor in the DAC is one of the dominate power consumed in the SAR ADCs [33, 39, 47-53]. Using smaller

unit capacitor, the power consumption of the switching capacitor can be reduced. However, small unit capacitor suffers from capacitor mismatch in modern CMOS technology. The capacitor mismatch limits the accuracy of the SAR ADC, especially for high resolution ADCs. Several works that address the issue of the capacitor mismatch in the SAR ADC had been reported [48, 50, 52, 54-59].

[48, 52] presented an on-chip digital calibration for the split-capacitor DAC by tuning the calibration capacitor DAC, as shown in Fig. 2.22. The offset of the comparator is calibrated prior to capacitor calibration. After that, the variable capacitor C_V is adjusted until the weights of the lower capacitor bank (C_5 - C_0 and parasitic capacitor) are identical to C_6 . Thus, the bridge capacitor C_B is compensated. Following which, the calibration capacitor DAC operating in parallel with the main capacitor DAC is used to correct the mismatch of C_7 - C_9 .

A digital-domain calibration of the split-capacitor DAC without additional analog circuits was proposed in [56, 58], as shown in Fig. 2.23. The corrected

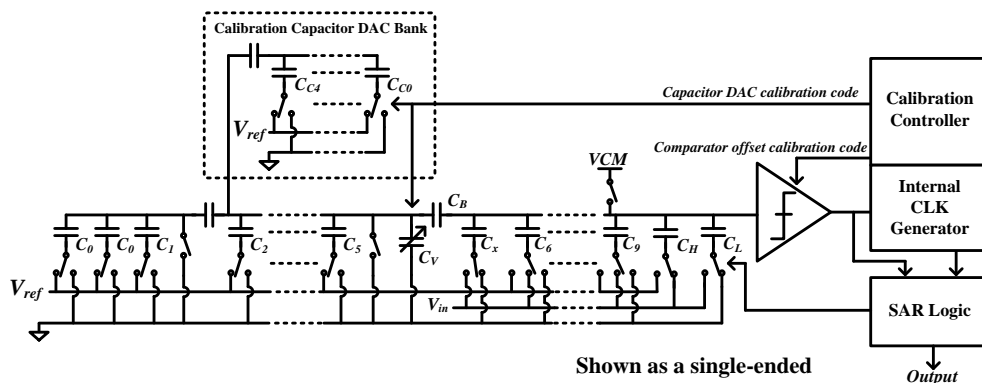


Fig. 2.22. On-chip digital calibration with additional calibration capacitor DAC bank.

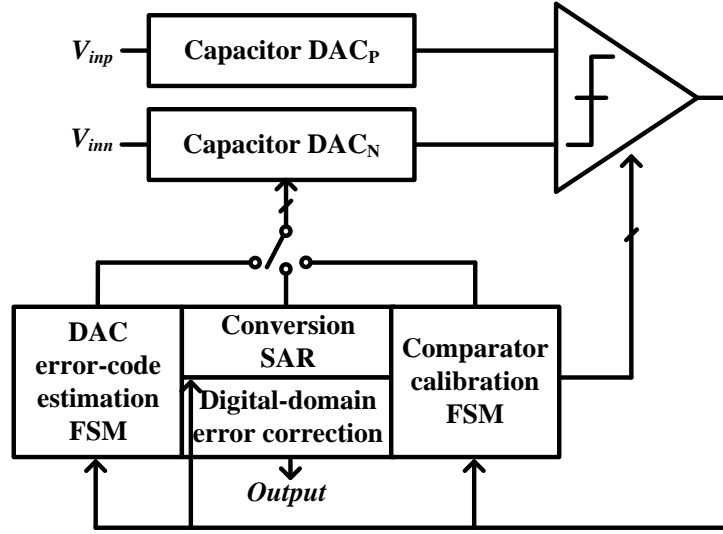


Fig. 2.23. Digital-domain calibration of split-capacitor DAC without additional analog circuits.

digital output code D_{OUT} can be expressed as:

$$D_{OUT} = \sum_{i=0}^{10} (2^i D_i) + \frac{1}{2} \sum_{i=0}^{10} ((D\mathcal{E}_{P,i} + D\mathcal{E}_{N,i}) D_i) \quad (2.9)$$

where D_i is the raw code of the ADC, and both $D\mathcal{E}_{P,i}$ and $D\mathcal{E}_{N,i}$ are the error codes. During the estimation of $D\mathcal{E}_{P,i}$ and $D\mathcal{E}_{N,i}$, the lower capacitors are assumed to have no mismatch (i.e., $D\mathcal{E}_{P,4} = \dots = D\mathcal{E}_{P,0} = 0$, $D\mathcal{E}_{N,4} = \dots = D\mathcal{E}_{N,0} = 0$). Take $D\mathcal{E}_{P,10}$ of the MSB capacitor DAC_P as an example of the error code estimation. First, the residual voltage is generated by the same switching scheme as that in the self-calibration technique [60, 61]. Then, the analog error voltage is digitalized by the LSB bank of the DAC_N . Thus, the digital error code $D\mathcal{E}_{P,10}$ can be expressed as:

$$D\mathcal{E}_{P,10} = \frac{1}{2} \left(LSB_bank_code - 2^4 - \frac{1}{2} \right) \quad (2.10)$$

This procedure is repeated for $D_{\mathcal{E}P,9} - D_{\mathcal{E}P,5}$ in DAC_P branch and $D_{\mathcal{E}N,9} - D_{\mathcal{E}N,5}$ in DAC_N branch, where all the error codes are stored in the memory. The final output code is calculated based on Equation (2.9) with the corresponding raw codes and the error codes.

The perturbation-based digital calibration technique of Fig. 2.24 is described in [50, 54, 55, 59]. The principle of this calibration technique is that when the capacitor mismatch is calibrated or the bit weights are optimized, the transfer curve of the ADC is linear. With two analog offsets (i.e., $+\Delta_a$ and $-\Delta_a$) added to the same sample, the SAR ADC digitalize these two analog signals and outputs two raw codes, i.e., D_+ and D_- . The calibration engine then calculates the weighted sums (i.e., d_+ and d_-) of these two raw codes using the same bit weights. A least mean square (LSM) algorithm is then applied to update the bit weights till the error between d_+ and d_- is zero. The details of this perturbation-based digital calibration technique will be discussed in Chapter 6 .

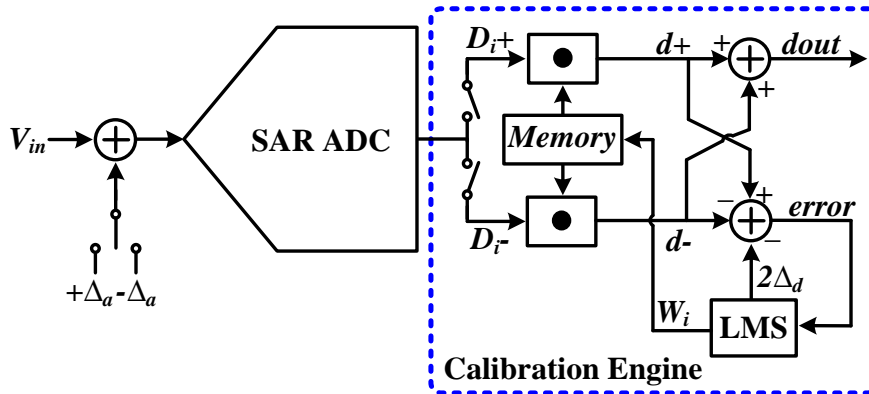


Fig. 2.24. Block diagram of perturbation-based digital calibration technique.

2.6 Conclusion

This chapter presents the background and literature review of SAR ADC. Several low power design considerations in conventional SAR ADC, including operating at ultra-low voltage, energy efficient switching method and low power comparator, have been discussed. Based on the conventional SAR ADC, some energy efficient ADC architectures for sparse signals acquisitions are also reviewed. These ADC architectures achieve low power consumption by utilizing some characteristics of the input signals. Following which, some ADC designs look with focusses on optimizing the peripheral circuits blocks that provide supply voltage and clock source to the ADC core are presented. Also, some calibration techniques for capacitor mismatch in high resolution SAR ADC are reviewed.

Chapter 3

Ultra-Low Power SAR ADC Design

As mentioned in Section 2.2 , the power consumption of a SAR ADC benefits from scaling down the operating voltage since most of its building blocks are digital circuits. Also, several design considerations are discussed in this chapter, including high linearity sampling switch, high energy efficient capacitor switching method, and reliable comparator. This chapter presents an ASIC design of an ultra-low power SAR ADC [62]. To achieve ultra-low power, the proposed ADC operates at ultra-low voltage, deploying a single-ended structure and top plate sampling technique. In order to improve the linearity of the sampling circuit at ultra-low supply voltage, clock boosting circuit is developed. A non-binary redundant algorithm is then applied to correct the inevitable decision errors in the first few conversion steps. The proposed ADC has been fabricated in a 0.18 μm CMOS process. From the measurement results, it consumes only 16 nW and achieves a SNDR of 50.4 dB, which is equivalent to an 8.08 ENOB, with 1 kS/s sampling rate at 0.5-V supply voltage. At the end of this chapter, two sensor node processors deploying this proposed ultra-low power SAR ADC are briefly described. One sensor node processor is a near-threshold cognitive multi-functional ECG processor for long-term cardiac monitoring, which consumes only 457 nW at 0.5 V for real-time ECG recording and diagnosis. Another is a sensor node processor with diverse hardware acceleration and cognitive sampling for intelligent sensing. It has been applied to neural spike classification and vehicle speed detection.

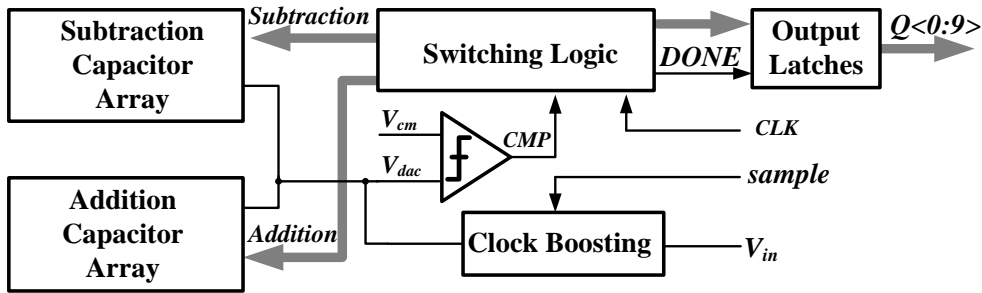


Fig. 3.1. Architecture of the proposed ultra-low power SAR ADC.

3.1 Proposed SAR ADC Architecture

The proposed 9-bit SAR ADC architecture is presented in Fig. 3.1 . It consists of clock boosting circuit, subtraction and addition capacitor array, a time-domain comparator, switching logic and output latches, and some buffers. To reduce power consumption and alleviate circuit complexity, the ADC utilizes single-ended structure. The sampling method adopted in this design is the top plate sampling technique, which is more power efficient than the bottom sampling technique since it contains only one sampling switch. The sampling switch connects the input signal to all capacitors' top plate terminals during the sampling phase, whereas the bottom sampling technique requires an array of sampling switches to connect all the capacitors' bottom plate to the input signal.

3.2 Proposed Clocking Boosting

As discussed in Section 2.2 static power consumption exists in the clock boosting circuits designed both in [29] and [30]. We proposed a simplified clock boosting circuit as depicted in Fig. 3.2. When sampling clock signal *Sample* is at low, the boosted sampling clock signal *Sample_b* is at low and the

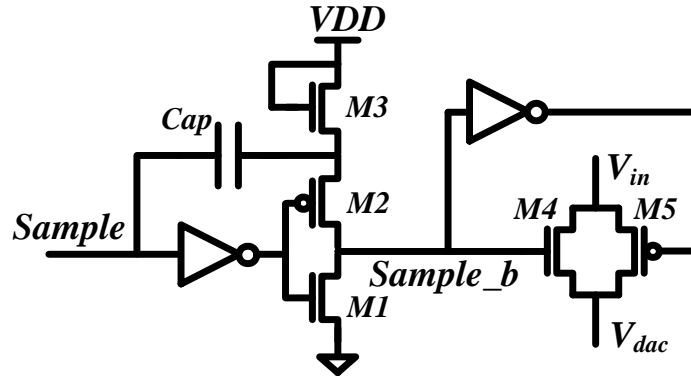


Fig. 3.2. Schematic of proposed clock boosting circuit.

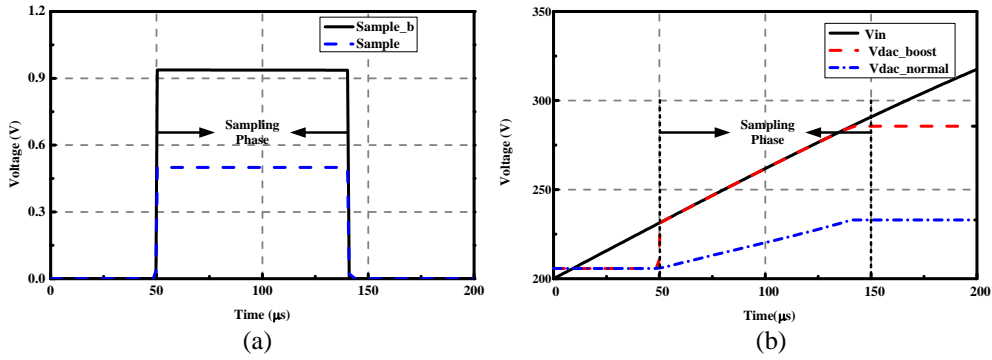


Fig. 3.3. (a) Simulation waveform of clock boosting circuit; (b) Input and output characteristics of transmission gate controlled by the normal and boosted voltage signals, respectively.

transmission gate turns off. During this phase, the charge pump capacitor Cap is charged to VDD through the diode-connect NMOS $M3$. During the next phase, when $Sample$ is high, Cap is charged with a potential difference, VDD . At the same time, $M2$ is on and $M1$ is off. As a result, the voltage of $Sample_b$ is ideally boosted to $2VDD$, as explained in Fig. 3.3(a). Fig. 3.3 (b) is the simulation result of the sampling circuit, both with and without the clock boosting circuit, illustrating the linearity of sampling switch being improved with clock boosting. The size of $M4$ and $M5$ are kept to its minimum, not just to

minimize the parasitic capacitance associated with V_{adc} , but to decrease the reversed-bias leakage.

3.3 Efficient Capacitor Array Design

As the switching of capacitor array is one of the dominant sources of power consumption in SAR ADC, it is important to implement a high efficient capacitor array circuit. Section 2.2.2 analyzed the power consumption of four capacitor switching methods, i.e., 1-step switching, 2-step switching, charge sharing, and capacitor splitting. These four capacitor switching methods consume the same power consumption when perform “up” transition. However, the capacitor splitting switching method dissipates the least power when performing “down” transition. Thus, we adopt capacitor splitting switching method in the capacitor array design. Besides, as the comparator operating at ultra-low voltage, some comparison errors may occur. Therefore, it is important to design a capacitor array that can tolerate these errors. A redundant algorithm is adopted to calibrate these comparison errors.

3.3.1 Redundant Algorithm

In a binary SAR ADC with no calibration block, any intermediate decision will not be recovered in the subsequent conversion steps. Non-binary SAR ADCs [47, 63, 64] with a radix of $2^{N/M}$ ($M > N$) show that mistakes of comparator decision can be digitally corrected; note that N is the ADC resolution and M is the number of conversion steps. [64] presented a generalized non-binary redundant algorithm with which SAR ADC can be faster. Fig. 3.4 is an example of a 5-bit 6 steps non-binary redundant algorithm

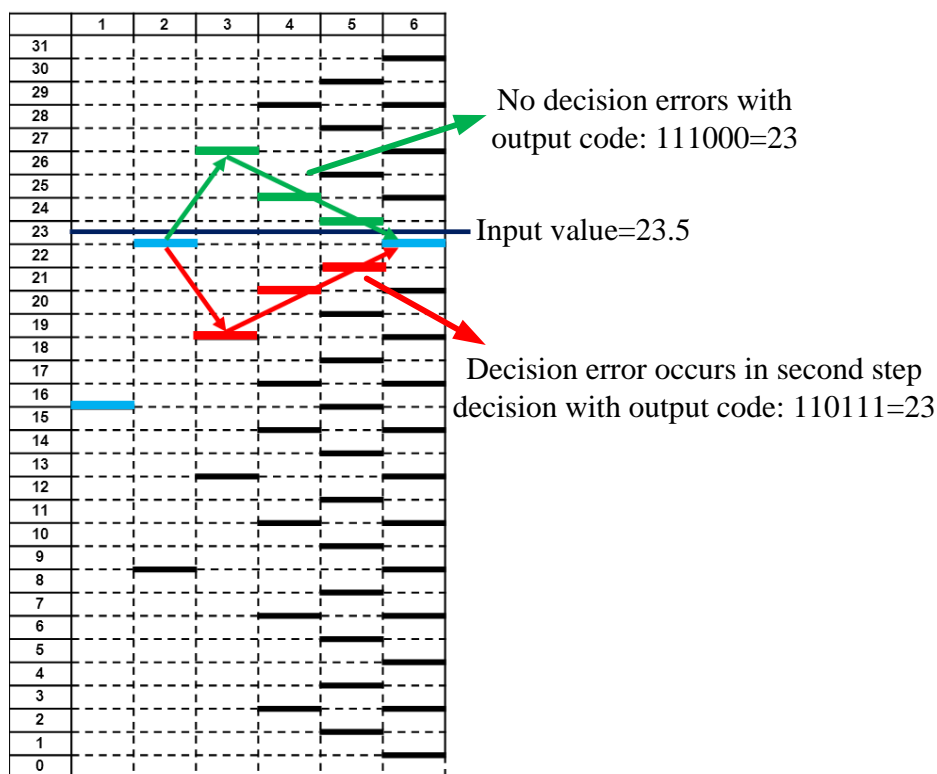


Fig. 3.4. Correction of decision error using redundant algorithm.

that corrects decision errors. In this example, the value for addition or subtraction in each step $p_i = \{16, 7, 4, 2, 1, 1\}$ where $i = 1:6$, and the input value is 22.5. The red path shows that the decision error occurs in the second conversion step but corrected in the subsequent steps. The value of output code 110111 and 111000 are both equal to 23, since $16+7-4+2+1+1=23$ and $16+7+4-2-1-1=23$.

The conversion time of SAR ADC with generalized non-binary redundant search algorithm can be less than that of the binary or conventional non-binary search algorithm: if we assume that the capacitor array is a first-order system with a time constant of τ , the settling time of each conversion step in a generalized non-binary redundant SAR ADC can be expressed as follows:

Table 3.1 Redundant Code Pattern for The 9-bit SAR ADC

<i>Step</i>	<i>p(i)</i>	<i>q(i)</i>
1	256	8
2	124	14
3	59	7
4	33	4
5	18	4
6	9	1
7	6	1
8	3	0
9	2	0
10	1	0

$$Settling\ time = \tau \times \ln\left(\frac{p}{q}\right) \quad (3.1)$$

where p is the step size of the reference voltage change from the previous step, and q is the redundancy in the corresponding step. The relationship between $p(i)$ and $q(i)$ is expressed in Equation (3.2). Through iterative simulation, and combining Equation (3.1) and (3.2), an optimum generalized non-binary redundant code pattern for the design of the 9-bit SAR ADC is obtained, and is shown in Table 3.1.

$$q(i) = -p(i+1) + 1 + \sum_{k=i+2}^M p(k) \quad (3.2)$$

3.3.2 Capacitor Array Implementation

The capacitor array of the proposed ADC employs generalized non-binary redundant algorithm and the capacitor splitting switching method. Non-binary redundant algorithm is engaged to correct the decision errors in the initial conversion steps, which allows slower settling for better power efficiency;

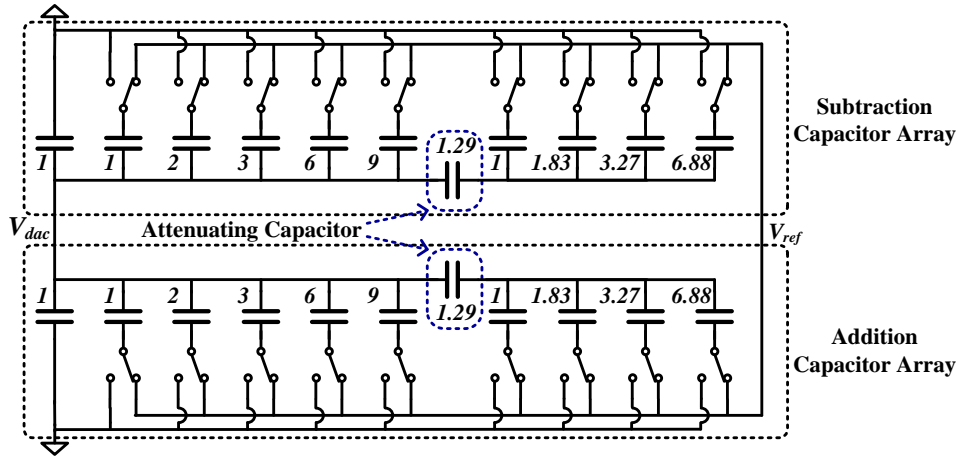


Fig. 3.5. Capacitor array of the proposed ADC.

but this is at the expense of additional redundant bit. A pair of capacitor arrays (see Fig. 3.5) has been designed according to the redundant algorithm code pattern in Table 3.1. The two split capacitor arrays are identical, to perform addition and subtraction. The linearity error due to the capacitor mismatching in the splitting capacitor DAC can be expressed as [65]:

$$\sigma_{INL} = 2^{\frac{N}{2}-1} \left(\frac{\sigma_0}{C_0} \right) LSB \quad (3.3)$$

$$\sigma_{DNL} = 2^{\frac{N-1}{2}} \left(\frac{\sigma_0}{C_0} \right) LSB \quad (3.4)$$

where σ_0 is the standard deviation of the unit capacitor. In order to achieve 3- δ capacitor matching at 9-bit level, the capacitor array uses 243 fF unit metal-insulator-metal (MIM) capacitor. An attenuation capacitor is inserted in between the MSB and LSB side of the array. Hence, the size of the MSB capacitors can be reduced without having to change the effective capacitor value. The attenuating capacitor C_c can be calculated as follows:

$$\begin{aligned}
C_c &= \frac{\sum \text{LSB Side Subarray Capacitors}}{C_{MSB_Least} - 1} C_0 \\
&= \frac{1+1+2+3+6+9}{18-1} C_0 = 1.29C_0
\end{aligned}
\tag{3.5}$$

where C_0 is the unit capacitor and C_{MSB_Least} is the smallest capacitor in the MSB capacitor subarray before attenuation, which is 18 in this design. The total capacitance value can be reduced from $511C_0$ to $35C_0$, and the area saving is about 14 times.

3.4 Time-Domain Comparator Design

The power consumption and accuracy of comparator very much determine the overall SAR ADC performance. In the ultra-low voltage SAR ADC design, the voltage of 1LSB decreases as the supply voltage decreases. The

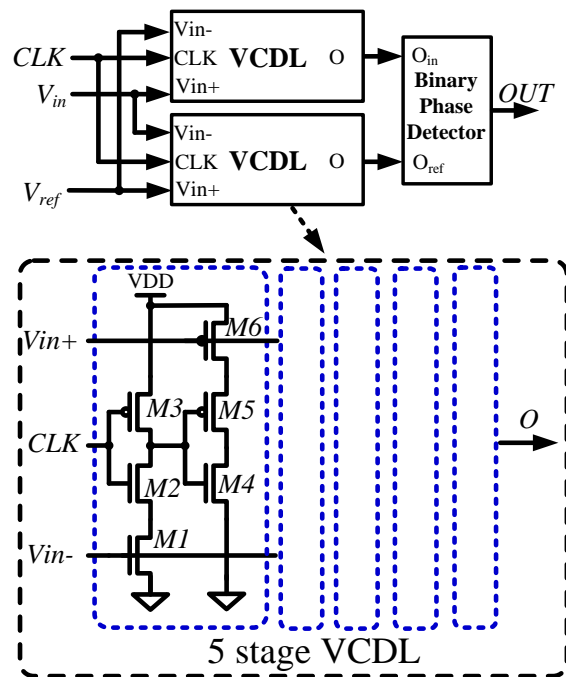


Fig. 3.6. Block diagram of the time-domain comparator, and the VCDL chain.

conventional voltage-based comparator is not suitable for ultra-low supply voltage in terms of power consumption and bandwidth. Time-domain comparator with highly digital architecture, benefits from lowing supply voltage and sampling rate [33, 34]. As mentioned in Section 2.2.3, time-domain comparator with flip-flop based phase detector is not suitable for ultra-low voltage operation. Because it is sensitive to the setup and hold time uncertainties of the flip-flop. The time-domain comparator developed in [34] can be used in SAR ADC operating at ultra-low voltage supply. Because it deploys highly digital differential VCDL and offset-free binary phase detector. The block diagram is reposted in chapter for convenience. Fig. 3.6 shows the block diagram of the time-domain comparator and the VCDL chain. When CLK is at active low, each stage output node of VCDL is discharged to ground. During CLK rising to active high, the current-starving transistors provide different currents due to unequal control voltages V_{in+} and V_{in-} . Therefore, the CLK propagation delay of these two differential VCDLs is different. This different CLK delay is detected by the binary phase detector as indicated in Fig. 3.7. When $IN1$ and $IN2$ are both low, $V1$ and $V2$ are both locked to V_{DD} . If the rising edge of $IN1$ arrives earlier than $IN2$, then $V1$ is first discharged to ground, resulting OUT set to high. If the rising edge of $IN2$ comes earlier than $IN1$, then OUT is low. With symmetrical racing paths from both inputs, this binary phase detector can be offset free.

3.5 Switching Logic Design

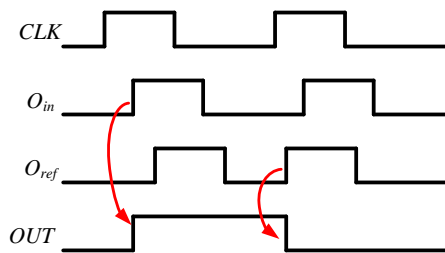
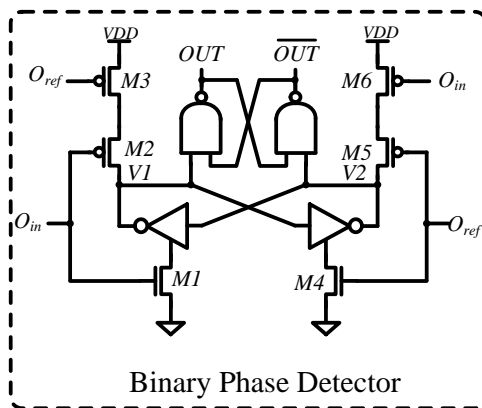


Fig. 3.7. Circuit and timing diagrams of the binary phase detector.

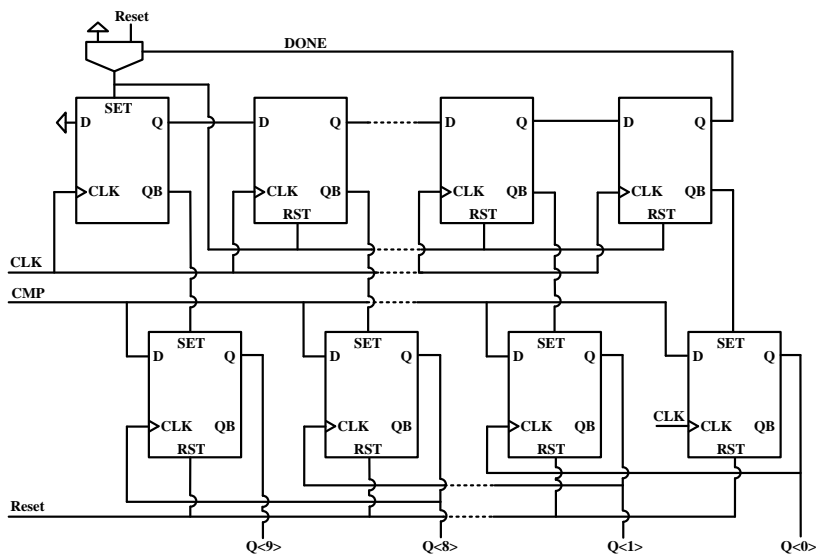


Fig. 3.8. Block diagram of SAR switching logic.

During the conversion phase, the switching logic (see Fig. 3.8) dictates the capacitor array to perform addition or subtraction depending on the comparator results. The logic circuit consists of nine logic blocks based on shift register, signal *DONE* generator, and other peripheral circuits. The comparison result is

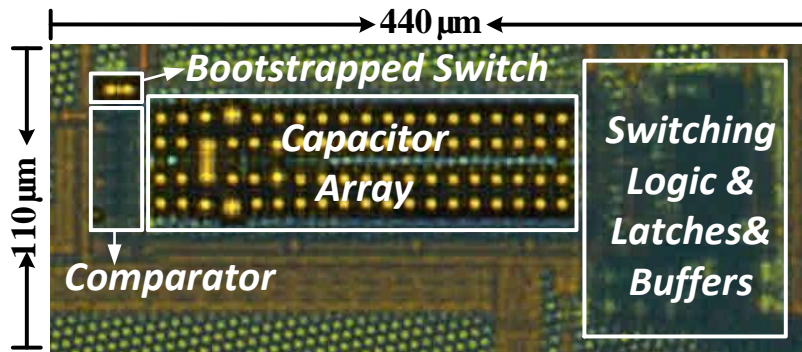


Fig. 3.9. Photo micrograph of the chip.

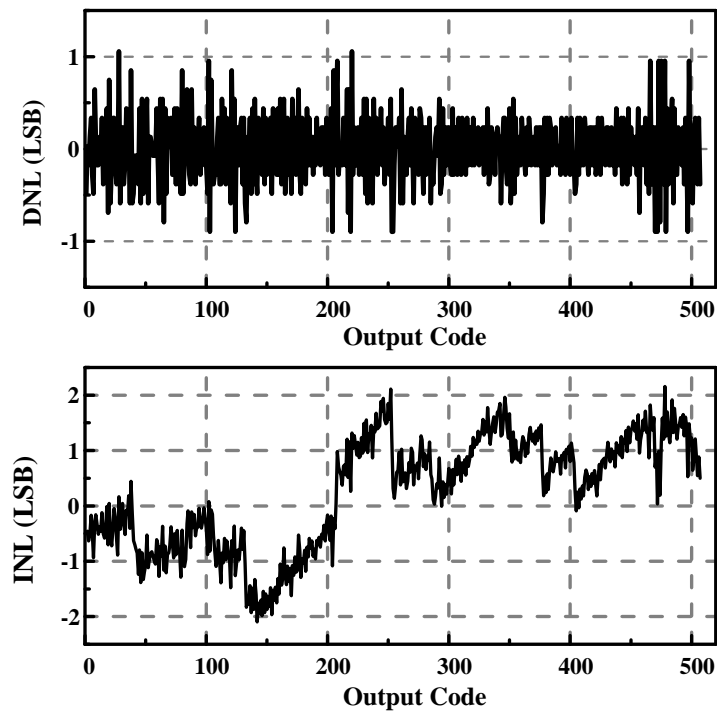


Fig. 3.10. DNL and INL measured at 1kS/s and 0.5 V supply

stored in respective D-flip-flop (DFF) in the logic circuit at each conversion step. At the end of conversion phase, the *DONE* generator creates the signal *DONE* to trigger the latches, to send the quantization data out in parallel.

3.6 Measurement Results

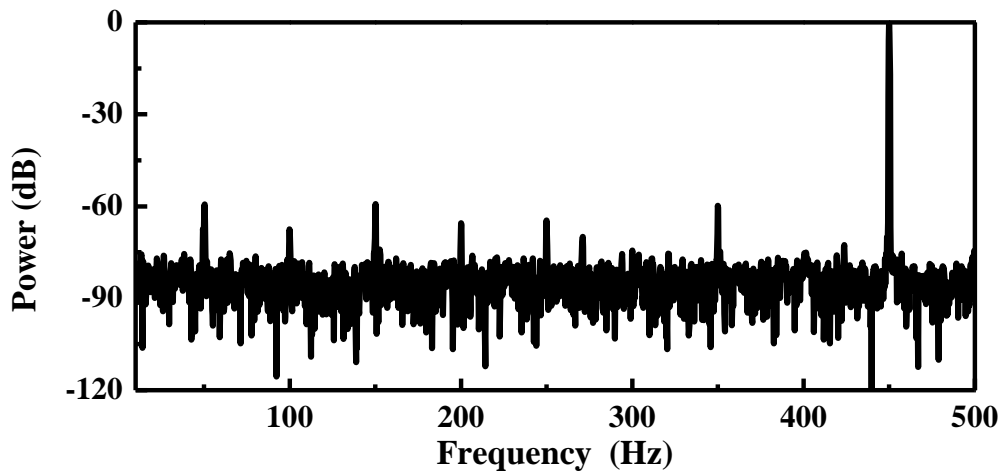


Fig. 3.11. Output spectrum with 449.95 Hz sinusoid input, operating at 1kS/s and 0.5 V supply voltage.

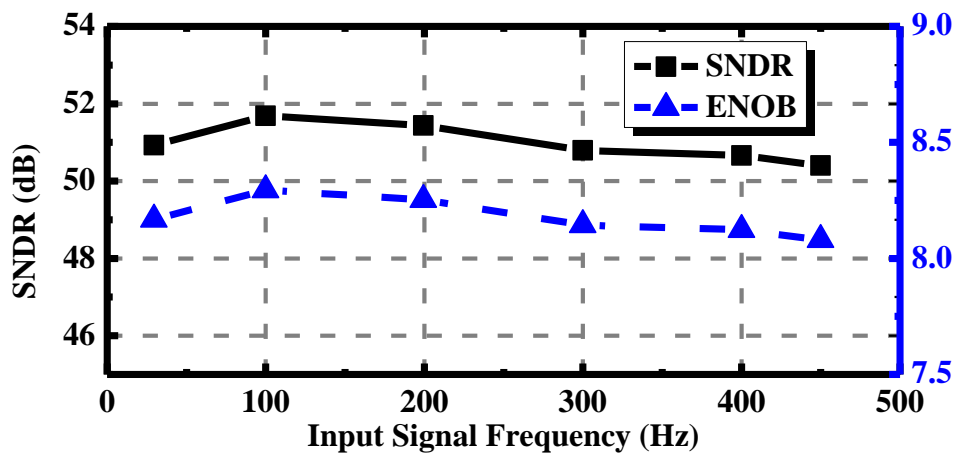


Fig. 3.12. SNDR and ENOB versus input signal frequency with 1 kS/s sampling rate 0.5 V supply voltage.

The designed 9-bit SAR ADC was fabricated in 0.18- μm CMOS process. Fig. 3.9 shows the die photo micrograph. The ADC core area occupies 0.048 mm^2 (110 μm \times 440 μm). Fig. 3.10 presents the measured linearity specifications at 1kS/s with a 0.5-V supply voltage. The integral nonlinearity (INL) and differential nonlinearity (DNL) are $\pm 2\text{LSB}$ and $\pm 1\text{LSB}$, respectively. As seen in Fig. 3.11, the ADC achieves a SNDR of 50.4 dB, which is equivalent

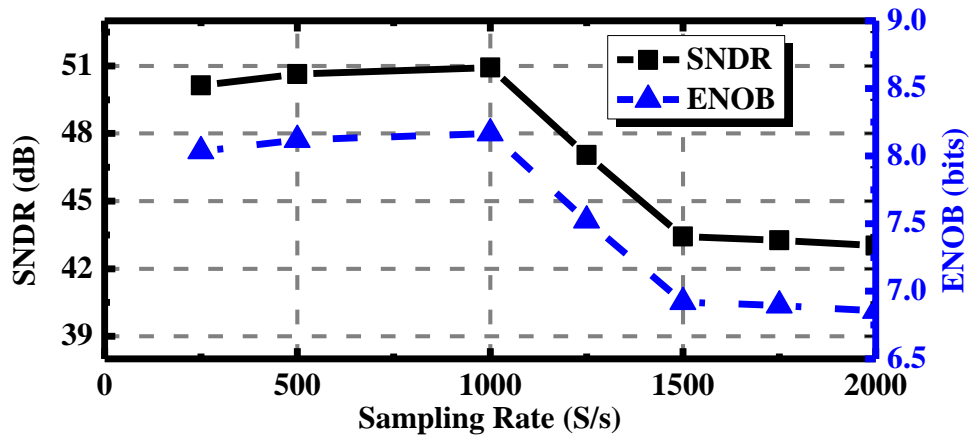


Fig. 3.13. SNDR and ENOB versus sampling rate with input signal frequency near 30 Hz.

to 8.08 effective number of bits (ENOB), with 449.95 Hz sinusoidal input at 1 kS/s and a 0.5-V supply voltage. In the SNDR and ENOB versus input signal frequency with 1 kS/s sampling rate plots of Fig. 3.12, the ADC clearly achieves the highest SNDR of 51.69 dB at 99.85 Hz input and 50.4 dB at near Nyquist input. As for Fig. 3.13 which is a plot of SNDR and ENOB versus sampling rate with input signal frequency near 30 Hz, it can be observed that the SNDR hits the highest at 1 kS/s sampling rate, and drops to 50.13 dB and 43.02 dB at 250 S/s and 2 kS/s sampling rate, respectively. At lower sampling rate, the node voltage V_{dac} suffers from circuits leakage with longer leaking time, resulting in much poorer SNDR.

Table 3.2 summarizes the measured performance of the ADC under different supply voltages. At a 0.5-V supply voltage, with 1 kS/s sampling rate, the ADC consumes a total power of 16 nW. The breakdown in power consumption for each circuit part (i.e. digital, analog, and cap array) is also provided in the Table 3.2. The figure of merit (FOM) is 59.1 fJ/conversion-step.

Table 3.2 ADC Performance Under Different Supply Voltages

Supply (V)		0.5	0.6	0.8	0.9
Sampling Rate (kS/s)		1	1.25	4	10
ENOB (bit)		8.08	8.15	7.97	7.98
Power (nW)	Total	16	20.8	85.1	221.4
	Digital	11	12	44.2	94.5
	Analog	1.6	2.8	13.4	36
	Cap Array	3.4	6	27.5	90.9
FOM (fJ/Conv.)		59.1	58.6	84.9	87.7

Table 3.3 ADC Performance Comparison

	[66]	[67]	[38]	[51]	This Work
Process (μm)	0.18	0.18	0.065	0.13	0.18
Supply (V)	0.5	0.5	0.55	1/0.4	0.5
Resolution (bit)	8	NA	9	10	9
Sampling Rate (kS/s)	4.1	0.4	20	1	1
ENOB (bit)	6.9	7.19	8.21	9.1	8.08
Power (nW)	850	6	159	53	16
Area (mm^2)	0.11	0.128	0.212	0.191	0.12
FOM (fJ/Conv.)	1700	102.7	26.8	94.5	59.1

The performance of this work has also been benchmarked with other related ultra-low voltage and low-sampling rate ADCs, and is summarized in Table 3.3. It can be concluded that the power consumption and FOM of our proposed design is collectively at the lowest among the existing designs discussed.

3.7 Sensor Node Processors Applications

Two sensor node processors deploying this proposed ultra-low power SAR ADC are briefly described in this section.

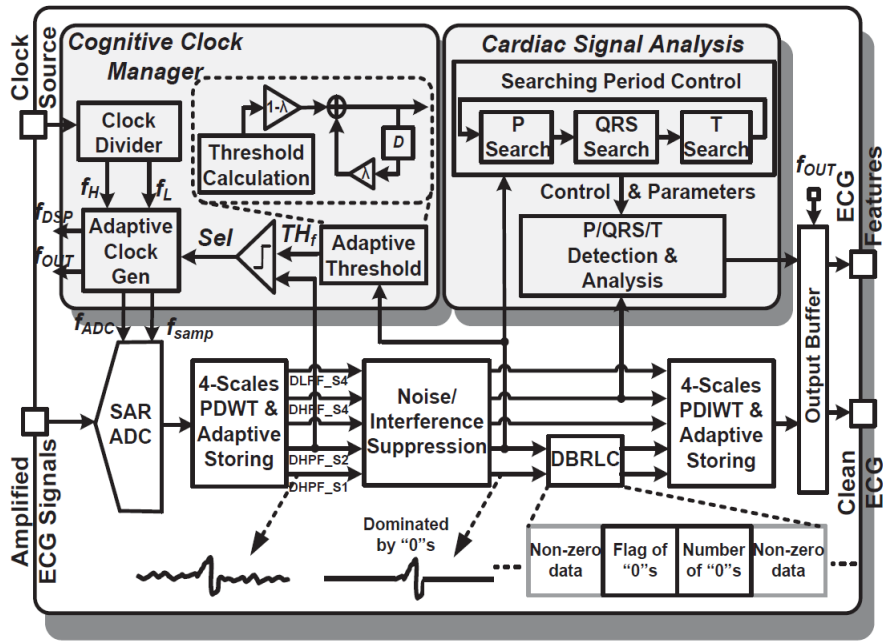


Fig. 3.14. System architecture of the proposed cognitive ECG processor.

3.7.1 Near-Threshold Cognitive Multi-Functional ECG Processor

Fig. 3.14 shows the system block diagram of the proposed ECG processor [6, 7]. The SAR ADC proposed in this section is adopted to digitize the acquired analog ECG signals in this ECG processor. An adaptive clock generator is used to switch the sampling rate of the SAR ADC. A digital signal processing engine (DSPE) performs noise/interference suppression, cardiac signal analysis, and clean ECG reconstruction, based on quadratic spline wavelet transform (WT) & inverse WT (IWT) [68]. Considering ECG signal characteristics and for achieving comparatively higher temporal resolution, the maximum sampling rate of the ECG signal is 500 Hz in our system, and thus 4 scales of WT is sufficient to perform the required signal processing. There are 4 types of WT filters: decomposition high-pass filter (DHPF), decomposition low-pass filter (DLPF), reconstruction high-pass filter (RHPF), and reconstruction low-pass filter (RLPF). A cardiac signal analysis module

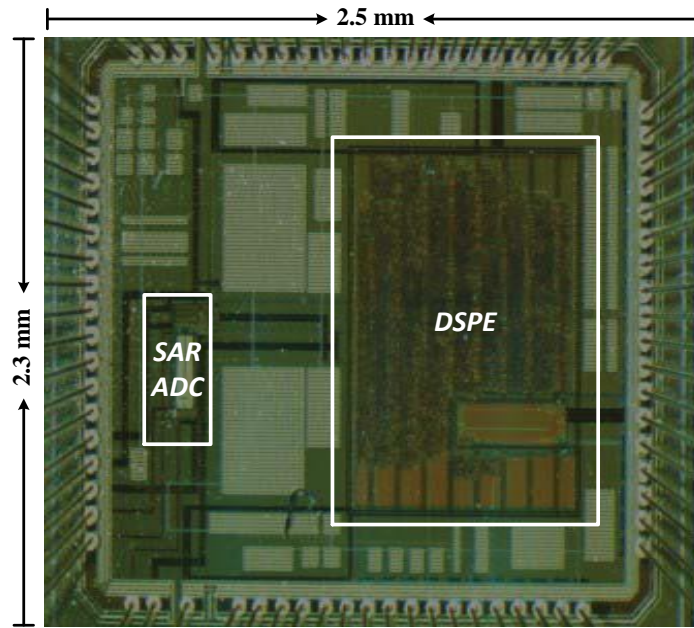


Fig. 3.15. Chip micrograph of the proposed cognitive ECG processor.

performs P/QRS/T detection and analysis using DHPF outputs. To achieve significant power reduction, the overall system operates at adaptive clock frequencies depending on the required temporal resolutions. A cognitive clock manager tracks the input signal characteristic and generates adaptive operation clocks accordingly for different modules.

The proposed ECG processor has been fabricated using 0.18 μm CMOS process and the die photo micrograph is shown in Fig. 3.15. When operating at 0.5 V supply voltage, the ECG processor consumes only 457 nW including both ADC and DSPE. The total power consumption can be reduced by 63% using the proposed architecture-level power-saving techniques (i.e. global cognitive clocking, PDWT & PDIWT, adaptive storing, and DBRLC), compared to the conventional design. Measurement results using a logic analyzer are shown in Fig. 3.16. The input ECG signal is distorted by noise. It can be observed that the clean ECG is reconstructed after noise/interference suppression. P/QRS/T

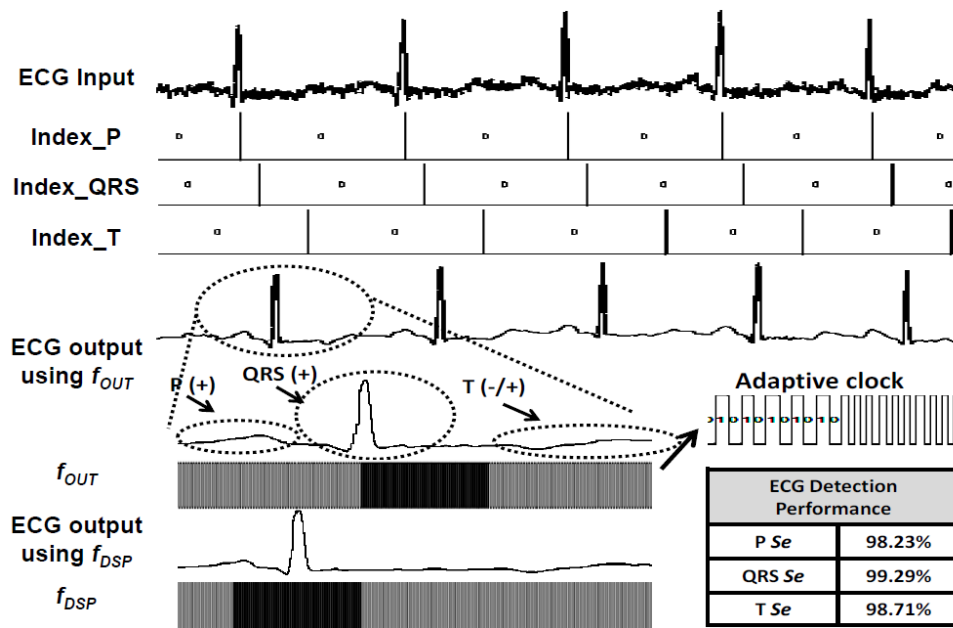


Fig. 3.16. Measurement results of the proposed cognitive ECG processor.

identification and morphology detection can be correctly obtained (i.e., $index_P$, $index_QRS$, $index_T$). The detection performance in terms of sensitivity (Se) based on MIT-BIH database is presented in Fig. 3.16, which is fairly good considering the low complexity and low power consumption achieved.

3.7.2 Sensor Node Processor for Intelligent Sensing in IoT

The system architecture of the proposed sensor node processor is illustrated in Fig. 3.17 [21]. It incorporates a 32-bit ARM Cortex-M0 RISC core for programming flexibility. It can switch between active and sleep modes through dynamic clock gating. There are 4-KB data memory (DMEM) and 16-KB program memory (PMEM). Dual-bus architecture is developed to facilitate parallel processing. Diverse hardware accelerators are developed to speed up the commonly used signal processing tasks in intelligent sensing applications. The hardware accelerators include discrete wavelet packet transform (DWPT) engine, FIR filtering engine, FFT engine, and coordinate rotation digital

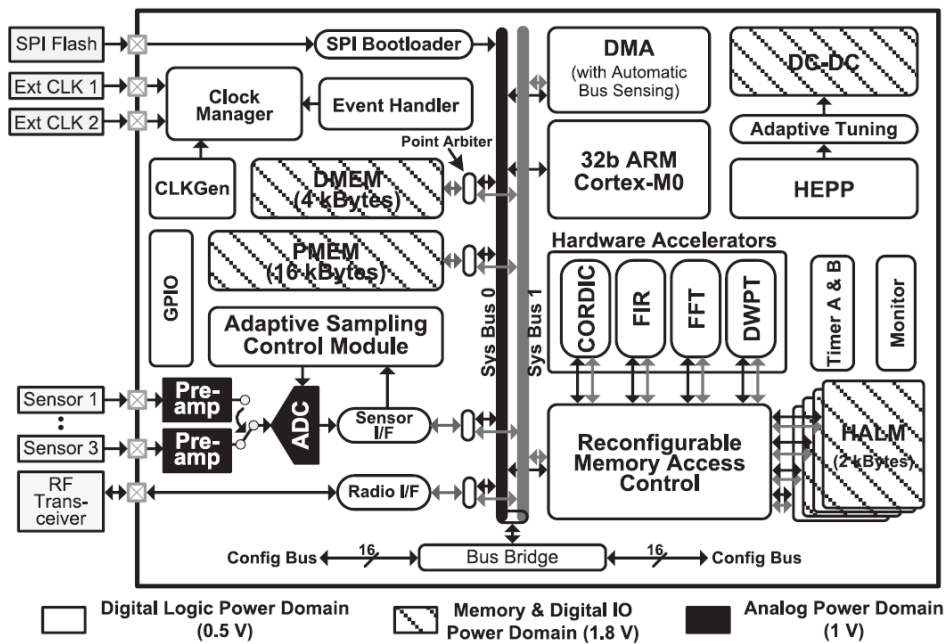


Fig. 3.17. System architecture of the proposed sensor node processor.

computer (CORDIC) engine. A radio interface module is developed to communicate with the external RF transceiver. To achieve high level of integration for system miniaturization, this SNP integrates multichannel analog front ends, analog-to-digital converters (ADCs), sensor interface, and dc–dc

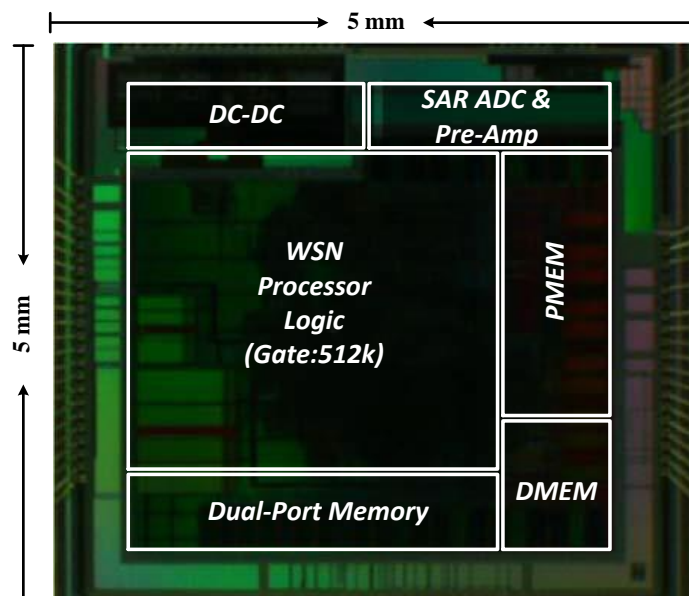


Fig. 3.18. Chip micrograph of the proposed sensor node processor.

converters (DC–DC). The 9-b SAR ADC is used to achieve satisfying performance and low power consumption. The DC–DC is a buck-converter-based design. In situ timing error monitoring technique with adaptive voltage and clock scaling is applied to reduce the design margin and enhance variation resilience for ULV operation.

A die photo of the proposed processor fabricated in 0.18 μm CMOS process is shown in Fig. 3.18. Two typical sensing applications are implemented for demonstration and the measurement results are also shown in Fig. 3.19. For neural spike classification, spike signals received from neural sensors are detected and classified by the proposed processor. The algorithm is executed

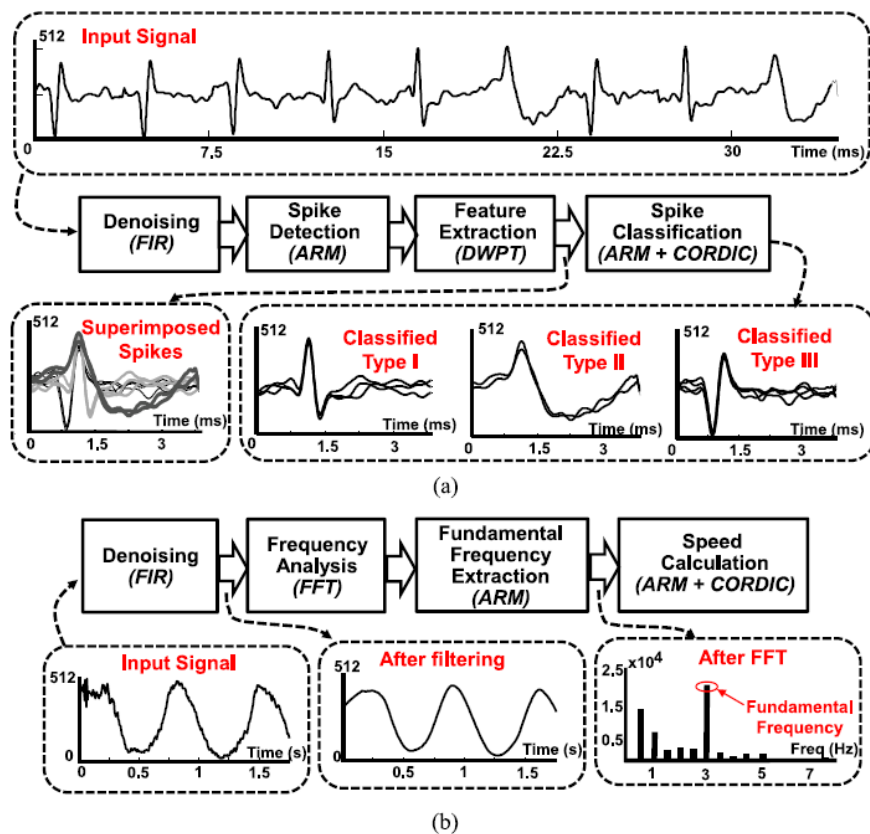


Fig. 3.19. Measurement results from two applications. (a) Neural spike classification. (b) Vehicle speed detection.

using the ARM core, FIR, DWPT and CORDIC engines with an average efficiency of 39 pJ/cycle at 500 kHz and 0.5 V. For car speed estimation, frequency analysis is performed for the data received from an accelerometer sensor placed in a tire. The algorithm is mapped to the ARM core, FIR FFT and CORDIC engines, consuming 29 pJ/cycle at 500 kHz and 0.5 V. The proposed processor provides a solution for low-to-medium-data-rate intelligent sensing applications requiring scalable performance and high energy efficiency.

3.8 Conclusion

This chapter presents an ultra-low power SAR ADC operating at 0.5 V supply voltage. Several design considerations of ultra-low power SAR ADC are discussed in this chapter, including high linearity sampling switch, high energy efficient capacitor switching method, and reliable comparator. To reduce the delay of the sampling circuit and improve on its linearity, we proposed a bootstrapped switch. The proposed ADC achieves 16 nW power consumption with 8.08-ENOB at 1 kS/s sampling rate. Two sensor node processors deploying this proposed ultra-low power SAR ADC are briefly described in this chapter. One sensor node processor is a near-threshold cognitive multi-functional ECG processor for long-term cardiac monitoring, which consumes only 457 nW at 0.5 V for real-time ECG recording and diagnosis. Another is a sensor node processor with diverse hardware acceleration and cognitive sampling for intelligent sensing.

Chapter 4

A 151-nW Adaptive Delta-Sampling

ADC Design

As mentioned in Section 2.3 , some energy-efficient ADC architectures had been reported to convert burst-like or sparse signals, such as neural spike, ECG and accelerometer waveforms [17, 18, 35]. [18] described a level crossing asynchronous ADC with adaptive resolution to achieve power reduction and data compression. However, complicated interface design is required to process the asynchronous samples prior to interfacing with the synchronous system. Also, level crossing asynchronous ADC is vulnerable to signal slope overload. A delta-modulated SAR ADC that converts only the voltage difference between two consecutive samples so as to reduce the number of conversion steps to achieve low power consumption is proposed by [17]. The circuit, however, needs to ensure oversampling at all time, which is not energy-efficient. In [35], the LSB-first SAR ADC makes use of its previous sample as an initial guess for its current sample. For full range input signal, the oversampling ratio should be larger than 32. Otherwise the LSB-first SAR ADC will require more conversion steps than the conventional SAR ADC. In this chapter, we propose a novel ADC with adaptive delta-sampling to reduce power consumption while meeting the required resolution and conversion range [69].

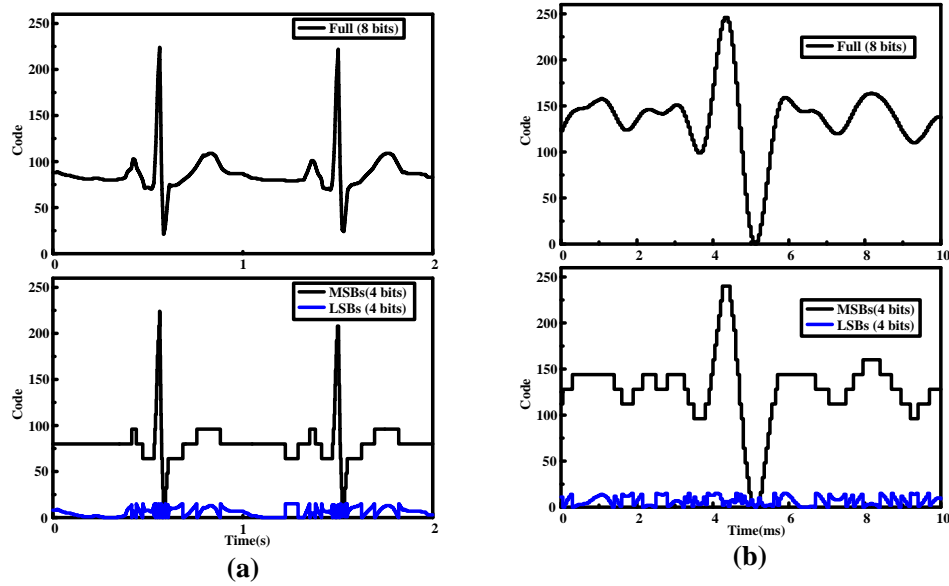


Fig. 4.1. Digitalized sparse signals with 8 bits, first 4 MSB bits and last 4 LSB bits: (a) ECG signal sampled with 1 kHz sampling rate, (b) neural signal sampled with 20 kHz sampling rate.

4.1 Input Signal Analysis

One important characteristic of burst-like or sparse signals is that the signals vary slowly during most of duty cycle. Fig. 4.1(a) shows the digitalized ECG and neural signals using an 8 bits ideal ADC, sampled with 1 kHz and 20 kHz sampling rate, respectively. It can be observed that the ECG signal varies slowly except the QRS region which is about 11%. For neural signal, it varies slowly except neural spike which is about only 0.85%. If we divide these 8 bits to the first 4 most significant bits (MSBs) and the last 4 least significant bits (LSBs), as the shown in Fig. 4.1(b), it can be observed that the first 4 MSBs remains the same during several consecutive samples both in ECG and neural signals. In these ECG monitoring and neural recording applications, the

conventional SAR ADC with binary search from MSB to LSB is not energy-efficient particularly for burst-like signals.

4.2 Proposed Adaptive Delta-Sampling Architecture

In the conventional N -bit SAR ADC, N number of conversion steps is required to complete the binary search from the MSB to LSB. If the difference between two consecutive samples is small, the conversion of the MSBs may not be necessary since their MSBs are the same. Hence, power is wasted if binary search is performed on every bit, from the MSB to LSB. Here we define the resolution of an N -bit ADC as V_{LSB} , which can be expressed as follows:

$$V_{LSB} = \frac{V_{range}}{2^N} \quad (4.1)$$

where V_{range} is the full conversion range of the ADC. In conventional ADC, V_{range} is equal to the full voltage range of the input signal. When the difference between two consecutive samples is small, only the difference between two consecutive samples needs to be converted. Therefore, instead of following the conventional approach, we convert only the increment of the input signal (we call it delta-sampling). By doing so, the binary search range can be reduced to achieve significant power reduction. An M -bit ADC ($M < N$) following this method is able to realize the same V_{LSB} resolution and the same conversion range as an N -bit conventional ADC. As a result, the ADC power consumption is reduced considerably. The concept will be further discussed in Section 4.5 .

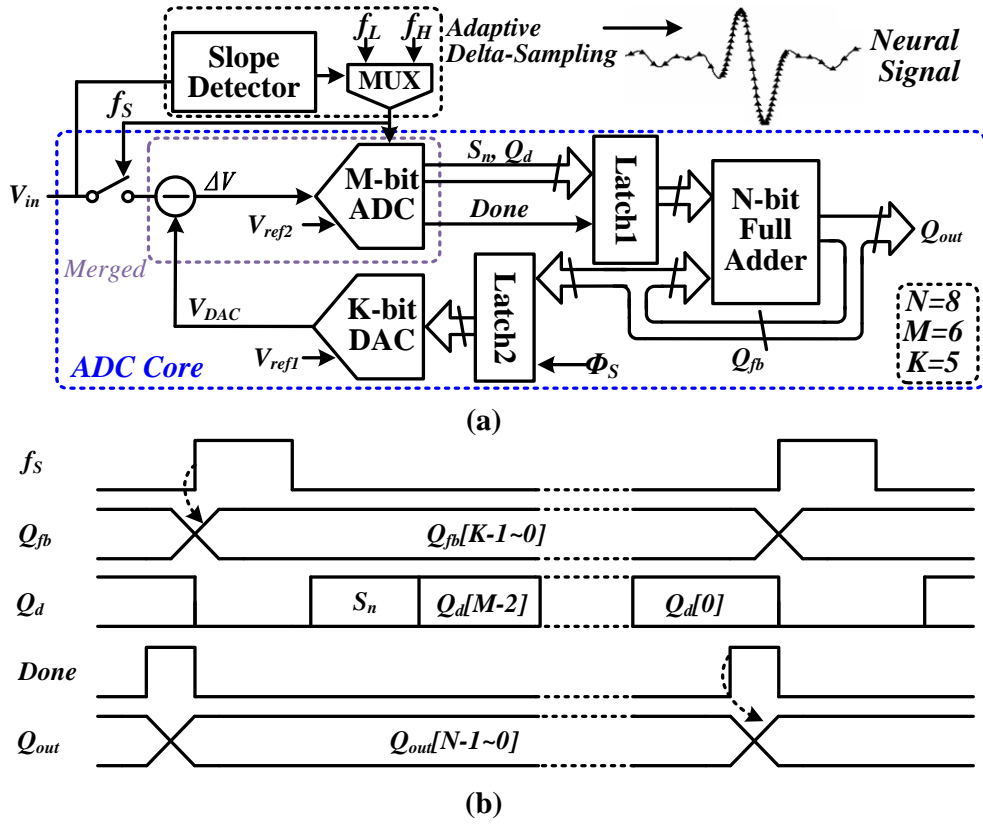


Fig. 4.2. Proposed ADC: (a) system architecture, (b) operation timing diagram.

Based on the idea described, a novel ADC is proposed as shown in Fig. 4.2. At the rising edge of the sampling clock signal f_s , the K -bit MSBs of previous sample, Q_{fb} , are feedback to the DAC to generate signal, V_{DAC} . During the sampling phase, only the difference, i.e., $\Delta V = V_{in} - V_{DAC}$, is sampled and sent to the M -bit ADC for digitization. Throughout the conversion phase, the M -bit ADC performs successive approximation and generates an M -bits code, Q_d , including one sign bit S_n . Once the conversion is completed, signal $Done$ rises to trigger the latch array, $Latch1$. This will also trigger the N -bit full adder to conduct addition or subtraction according to, S_n , and the ADC will output a digitized code, Q_{out} .

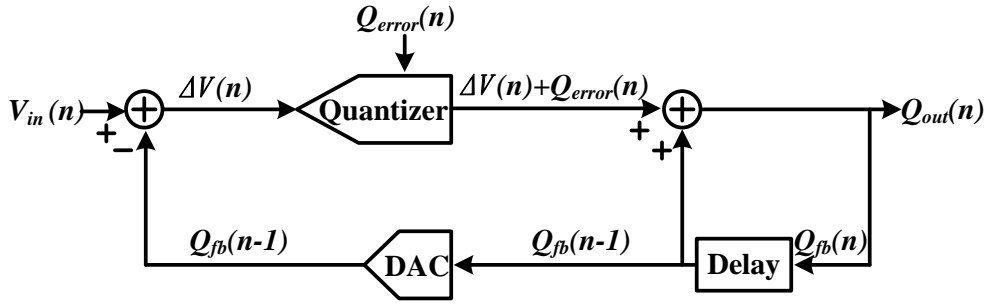


Fig. 4.3. Block diagram of proposed ADC for accumulated error analysis.

Different from the analog-front delta-sampling [70], which suffers from accumulated error, the proposed delta-sampling ADC does not have accumulated error even if there is error during data sampling/conversion. Fig. 4.3 shows a simplified block diagram of the proposed ADC, where the quantizer represents M -bit ADC along with a conversion error Q_{error} . The equations of voltage difference, ΔV , and digitized output code, Q_{out} , can be obtained as follows:

$$\Delta V(n) = V_{in}(n) - Q_{fb}(n-1) \quad (4.2)$$

$$Q_{out}(n) = \Delta V(n) + Q_{error}(n) + Q_{fb}(n-1) \quad (4.3)$$

Substituting Equation (4.2) into Equation (4.3),

$$Q_{out}(n) = V_{in}(n) + Q_{error}(n) \quad (4.4)$$

From Equation(4.4), we can conclude that the output error of the proposed ADC contains only the current sampling/conversion error, $Q_{error}(n)$, and there is no accumulated error during operation.

4.3 Adaptive Delta-Sampling

The proposed delta-sampling scheme is able to lessen the power consumption by reducing the binary search range. However, in the event of a

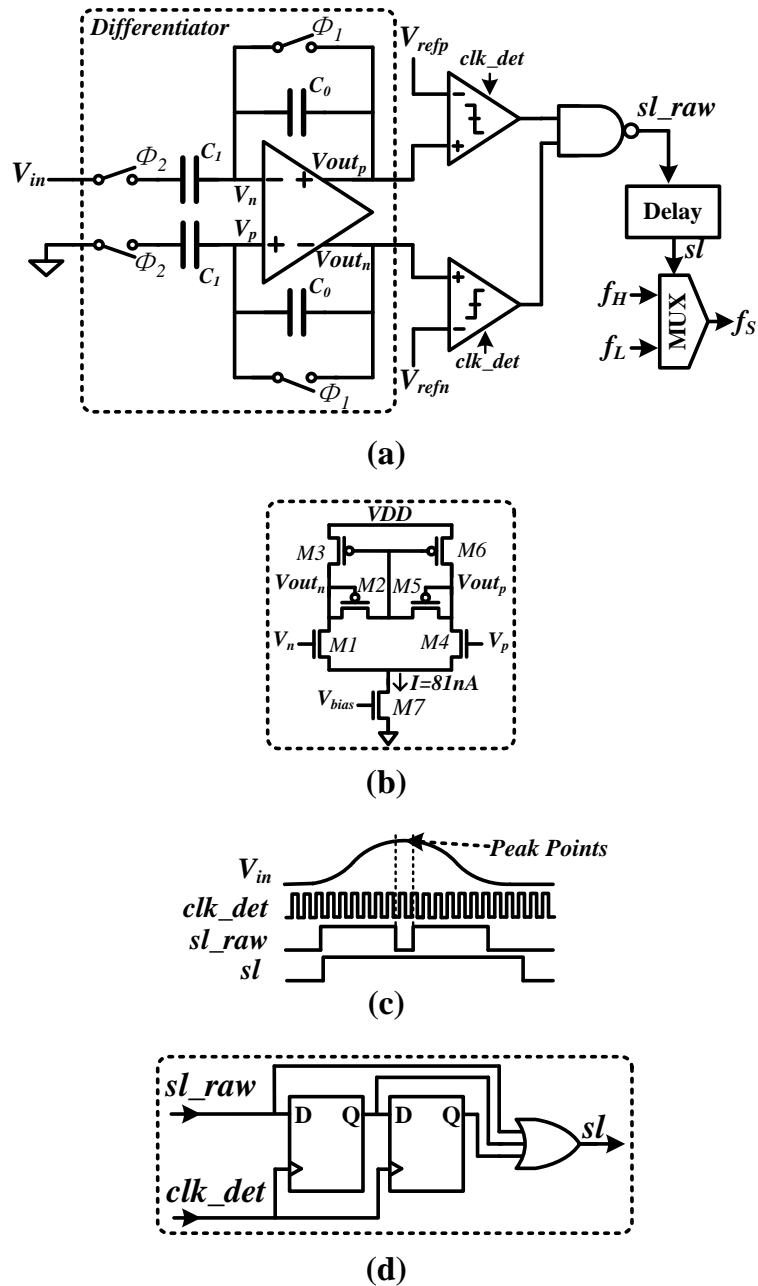


Fig. 4.4. Proposed analog-front slope detector: (a) block diagram, (b) fully differential amplifier, (c) peak points of input signal, (d) digital delay cell.

sudden change in input signal, the difference voltage, $|\Delta V|$, will also change abruptly. If $|\Delta V|$ is larger than the conversion range of the M -bit ADC, overload will occur in the ADC to cause conversion error. To address this issue, we propose an adaptive delta-sampling scheme using a slope detector, as illustrated in Fig. 4.2. Proposed ADC: (a) system architecture, (b) operation timing diagram.

Fig. 4.2. To illustrate the concept, the proposed adaptive delta-sampling ADC is used to convert a pre-recorded neural signal from an anesthetized rat [8]. During non-spike periods, the maximum amplitude of the neural signal is limited to $24/255$ of the full conversion range (i.e., 1 V) and its bandwidth is less than 1 kHz. This means that the M -bit ADC with $31/255$ V conversion range (i.e., $M = 5$) will not overload and the Nyquist sampling frequency (i.e., $f_L = 2$ kHz in our case) can be used. According to the literatures [8, 19, 20, 53], to conserve complete information of neural spikes, ADC needs to operate at higher than 14 kHz. Considering that the 20 kHz sampling frequency can achieve enough signal-to-noise and distortion ratio (SNDR)/ENOB (45.3 dB/7.2 bits) and lower power consumption is preferred in the neural recording system, we set the higher sampling frequency at 20 kHz (i.e., $f_H = 20$ kHz). Based on this sampling frequency and the maximum slope of the input signal (i.e., 1.7 mV/ μ s in this case, which is calculated by performing a differential of the neural signal reported in [8]), we are able to determine the resolution of M -bit ADC. The maximum voltage difference between two consecutive samples is 1.7 mV/ μ s \times 50 μ s = 85 mV, which is about $22/255$ of the full conversion range. As our target is 8 bits, i.e., $N = 8$, we select $M = 5$ so that the conversion range of the M -bit ADC is $31/255$ V (which is larger than $22/255$ V). As there is still a difference between $31/255$ V and $22/255$ V, which

is 9/255 V, we can use partial number of bits instead of having all the bits of the previous sample during the delta-sampling. In this case, the feedback bits, i.e., K , from the previous sample can be reduced from 8 to 5, which correspond to 9/255 V. This helps to reduce the complexity and power consumption of the K -bit DAC. In addition, a sign bit is needed in the M -bit ADC to indicate either signal rising or falling. Thus, we eventually settled with $M = 6$, $K = 5$.

The slope of the input signal is detected by the analog-front slope detector of Fig. 4.4. The switched-capacitor differentiator in [71] is employed in the proposed slope detector. A single stage fully differential amplifier (see Fig. 4.4(b)) with unity-gain bandwidth of 1.8 MHz is used in this differentiator, consuming 81 nA of current. The output of differentiator can be represented as [71]

$$V_{out_p} = \left(\frac{C_1}{C_0} \right) \times T \times (V_{in}(t+T) - V_{in}(t)) \quad (4.5)$$

where $C_1/C_0 = 8$, $T=50 \mu\text{s}$. V_{out_p} will be compared to a threshold voltage through a coarse time-domain comparator [34]. The sampling frequency will switch between a higher sampling frequency of $f_H = 20 \text{ kHz}$ and a lower sampling frequency of $f_L = 2 \text{ kHz}$ according to the comparison results. As shown in Fig. 4.4(c), the peak points of the input signal will cause a downward pulse in the raw selection signal, resulting in lower sampling frequency which is not desirable. To remove the downward pulse, we proposed a digital delay cell as illustrated in Fig. 4.4(d). sl_raw and the outputs of the D-flip-flops are fed to a OR gate to generate sl , which is then used to determine the sampling frequency. Since the proposed ADC is of moderate resolution (8 bits) and has low input signal bandwidth (1 kHz), the timing mismatch requirement between

fast and low clock is just 0.5 μs , which can be easily satisfied. The two clocks are generated from the same clock source by the FPGA. In the PCB and chip layout, the clock paths are routed in parallel and shielded by the ground plane to minimize the timing mismatch. The timing mismatch between the generated fast and slow sampling clocks is less than 50 ns, which fulfills the timing requirement. Fig. 4.5 shows the measured timing mismatch between the fast and slow sampling clocks.

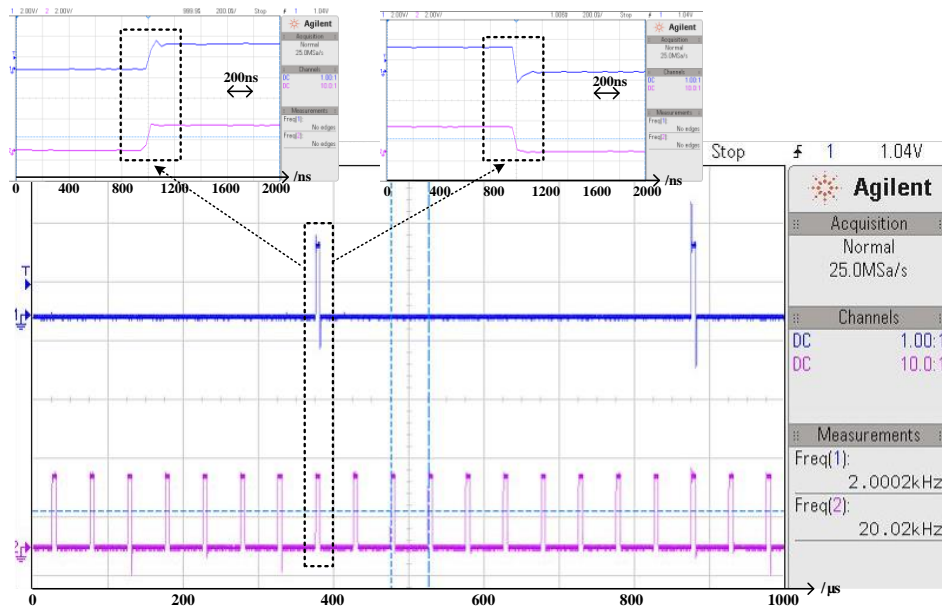


Fig. 4.5. Measured timing mismatch between fast and slow clocks.

Compared to using a digital slope detector, the analog-front slope detector is a better choice due to its fast response time. The delay of ADC conversion in a digital slope detector cannot be avoided and may cause the M -bit ADC to overload when changing from f_L to f_H . Although the proposed analog-front slope detector consumes additional power, the amount is much less than the power saving gained in the proposed ADC. Details of the measurement results are provided in Section 4.7

ADC are switched to a reference voltage or ground depending on the comparator result. During this procedure, the node voltage V_p will approximate to the node voltage V_n till the LSB is decided, as shown in Fig. 4.7(b). Without using operational amplifier, this merged subtractor can achieve low power. Energy efficient split-capacitor switching scheme is used in the 6-bit DAC design to further reduce power consumption. This is accomplished by splitting the MSB capacitor of the 6-bit DAC into a 6-bit DAC MSB sub-array that is identical in structure to the rest of the 6-bit DAC [38], as shown in Fig. 4.6. The unit capacitor used in both the 6-bit DAC and 5-bit DAC is 240 fF MIM capacitor, which satisfies the 8-bit linearity requirement.

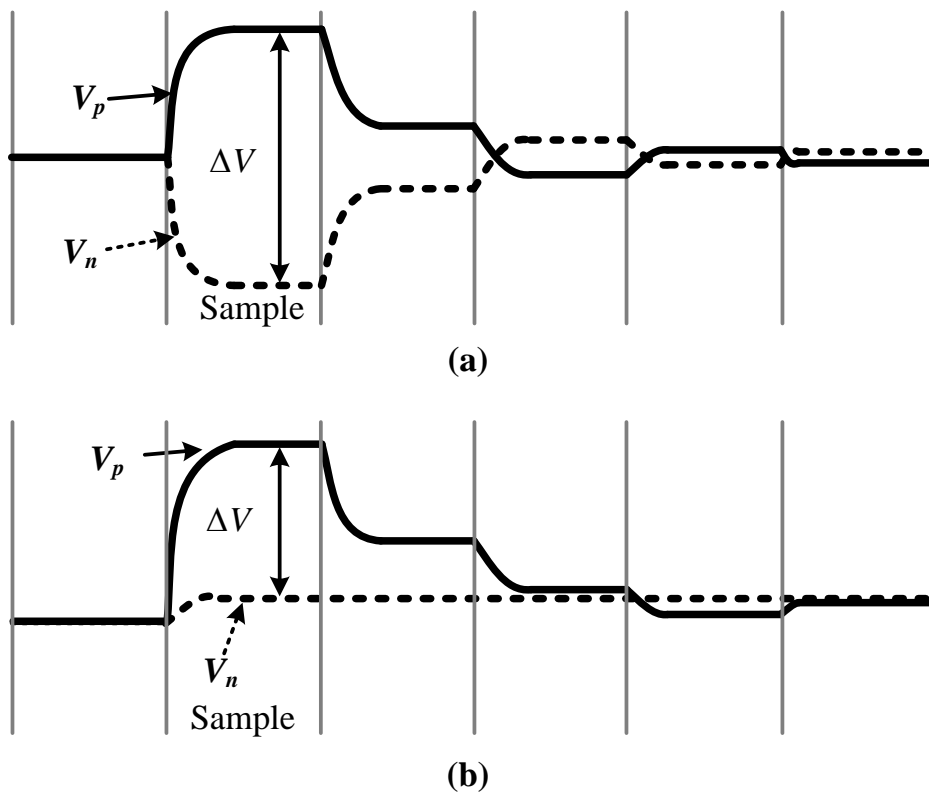


Fig. 4.7. Waveforms of: (a) conventional differential ADC switching procedure and (b) proposed switching procedure.

4.5 Power consumption analysis of proposed ADC

The advantages of the proposed ADC in terms of power consumption can be analyzed as follows: (1) The reference voltage is reduced from V_{ref} to $V_{ref}/4$ in the 6-bit ADC due to the reduced binary search range, and hence $16\times$ power reduction in the capacitor array; (2) the total capacitance of the capacitor array is reduced from $256C_0$ to $64C_0$, leading to a $4\times$ power reduction in the capacitor array; (3) the proposed ADC only requires six conversion steps as opposed to eight steps in a conventional ADC. The saving of two conversion steps results in substantial power reduction since each conversion step involves capacitor array switching, analog comparison and SAR logic switching. It is noted that the power consumption of the 5-bit capacitor array in the 5-bit DAC is low. The reason is that the digitized MSBs between consecutive samples change slowly or remain the same, and thus most of the capacitors in the 5-bit DAC do not

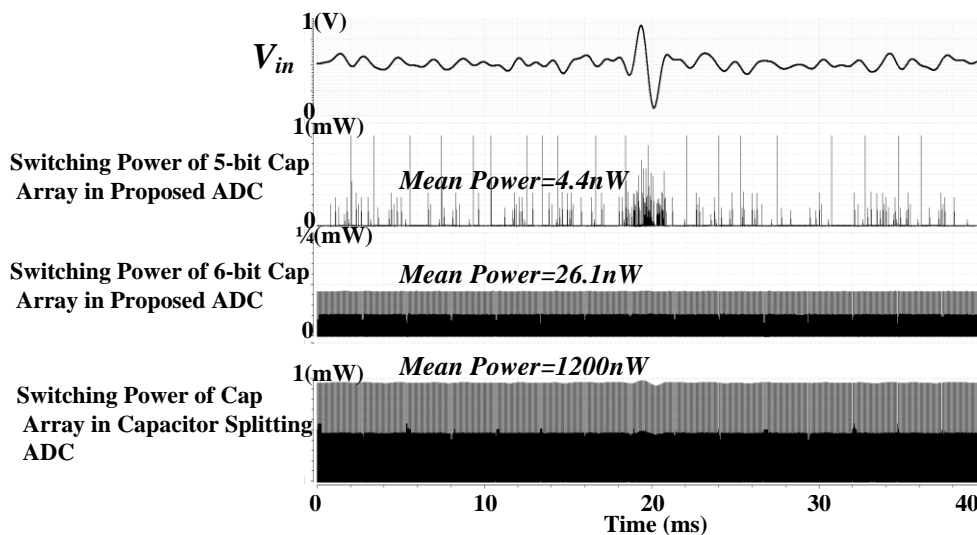


Fig. 4.8. Simulated power consumptions of the capacitor arrays in proposed ADC and the capacitor splitting ADC with neural signal input.

need to switch.

Fig. 4.8 shows the simulated power consumption of the capacitor arrays in the proposed ADC and a capacitor splitting ADC. The input of the ADCs is a neural signal with 20 kS/s sampling frequency and a 1-V power supply. The power consumed by the capacitor arrays of the proposed ADC and the capacitor splitting ADC are 30.5 nW and 1200 nW, respectively. A power reduction of 39× is achieved.

4.6 Wide Common-Mode Range Comparator

The common-mode voltage of the comparator input depends on the MSBs of previous sample in the proposed adaptive delta-sampling ADC, which can be from ground to V_{DD} . Therefore, a wide common-mode range comparator is required in this proposed SAR ADC. Two versions of comparator with wide input common-mode voltage range have been designed and will be presented in

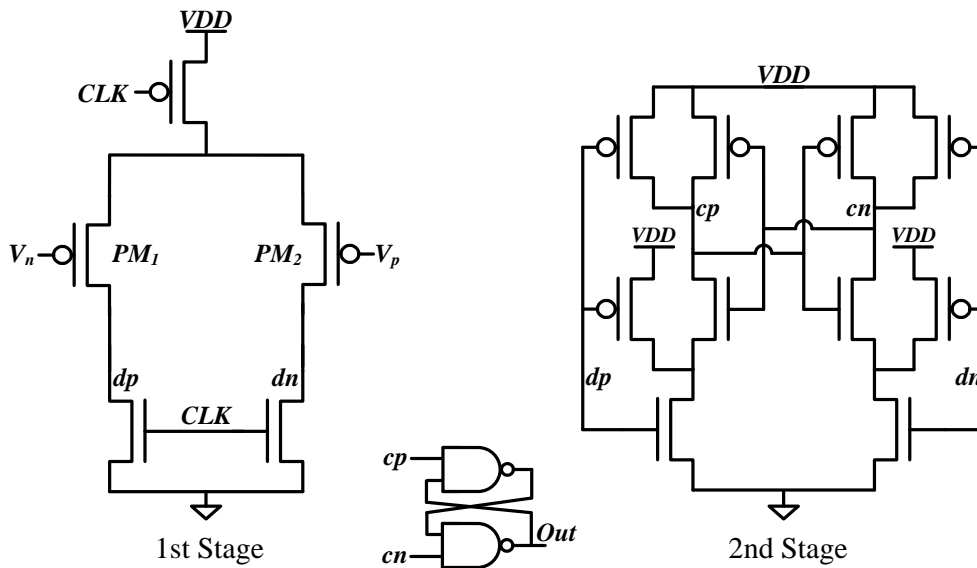


Fig. 4.9. Schematic of conventional two-stage dynamic comparator.

this section. Both of these two versions are modified from a two-stage dynamic comparator described in [41], as shown in Fig. 4.9. The input common-mode voltage range of two-stage dynamic comparator as shown in Fig. 4.9 cannot reach from ground to VDD . The comparator cannot work properly when the input common-mode voltage is near VDD because the PMOS input pair, i.e., $PM1$ and $PM2$, is switched off.

To widen the common-mode input range of the dynamic comparator, a pair of NMOS (i.e. $M1$ and $M2$) is added to the first stage, as depicted in Fig. 4.10. The operation of the proposed comparator is explained as follows. When clock CLK is high, dp and dn will be pulled down to ground through NMOS $M6$ and $M7$. Then, cp and cn will be pulled up to the supply voltage VDD through PMOS $M8$ and $M9$. On the falling edge of CLK , PMOS $M5$ in the first stage will be switched on. Therefore, comparator input voltage V_p and V_n are transformed

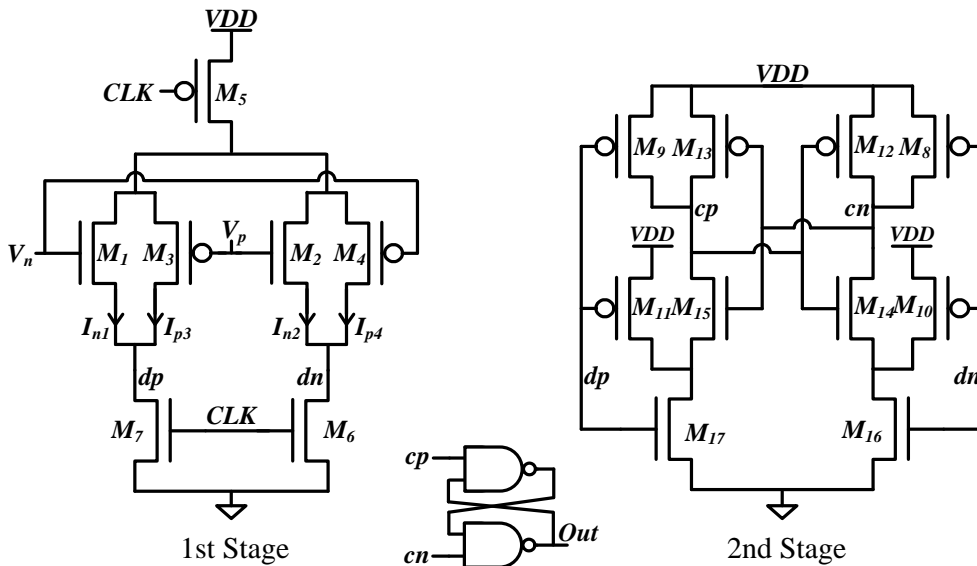


Fig. 4.10. Schematic of proposed two-stage dynamic comparator with PMOS and NMOS input pairs.

into two different current I_{dp} and I_{dn} , respectively. The voltage of dp and dn will also rise accordingly, which in turn trigger the regenerative latches in the second stage. The sum current I_{dp} and I_{dn} can be expressed as follows:

$$I_{dp} = I_{n1} + I_{p3} \quad (4.6)$$

$$I_{dn} = I_{n2} + I_{p4} \quad (4.7)$$

I_{n1} , I_{n2} , I_{p3} and I_{p4} are the currents of $M1 \sim M4$, and the mode of operation of these MOSFETs, i.e., saturation, triode or subthreshold, will depend on the input voltages. If the common-mode input is low, the current generated by the differential pair of PMOS (i.e. $M3$ and $M4$) will dominate the sum of the two currents. Oppositely, the currents generate by $M1$ and $M2$ will dominate I_{dp} and I_{dn} , respectively. To minimize the common-mode input dependent offset of our proposed comparator, the width and length of the input MOSFETs (i.e. $M1$, $M2$, $M3$ and $M4$) are designed to be large. Also, long transistor with small flowing current to $M5$ is used to reduce the comparator offset. In addition, the layout utilizes common-centroid technique along with dummy transistors to achieve better matching.

The second version of wide common-mode range comparator is shown in Fig. 4.11. It consists of a pair of two-stage dynamic comparators (i.e. $P_comparator$ and $N_comparator$), clock gating and selection circuit. When the input common-mode voltage is less than $V_{ref}/2$, the $P_comparator$ with PMOS input transistor is used; otherwise, the $N_comparator$ with NMOS input transistor will be engaged. The clock gates and comparator output selection circuit are controlled by the MSB Q_7 . As clock gating is adopted, only one of

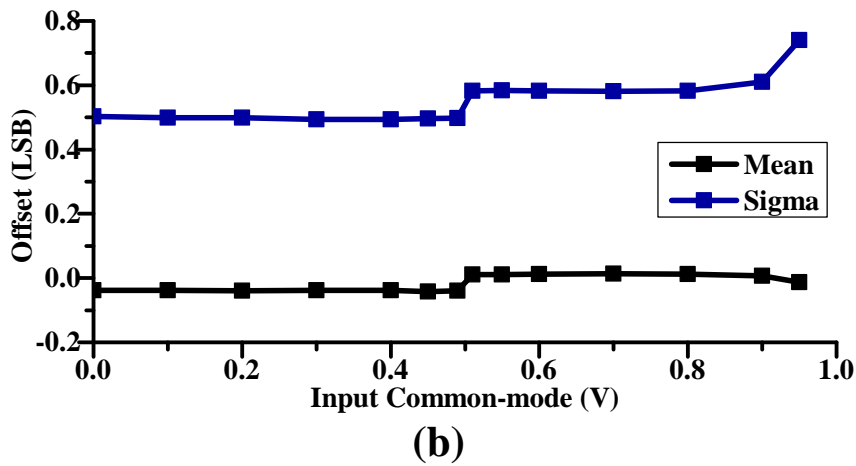
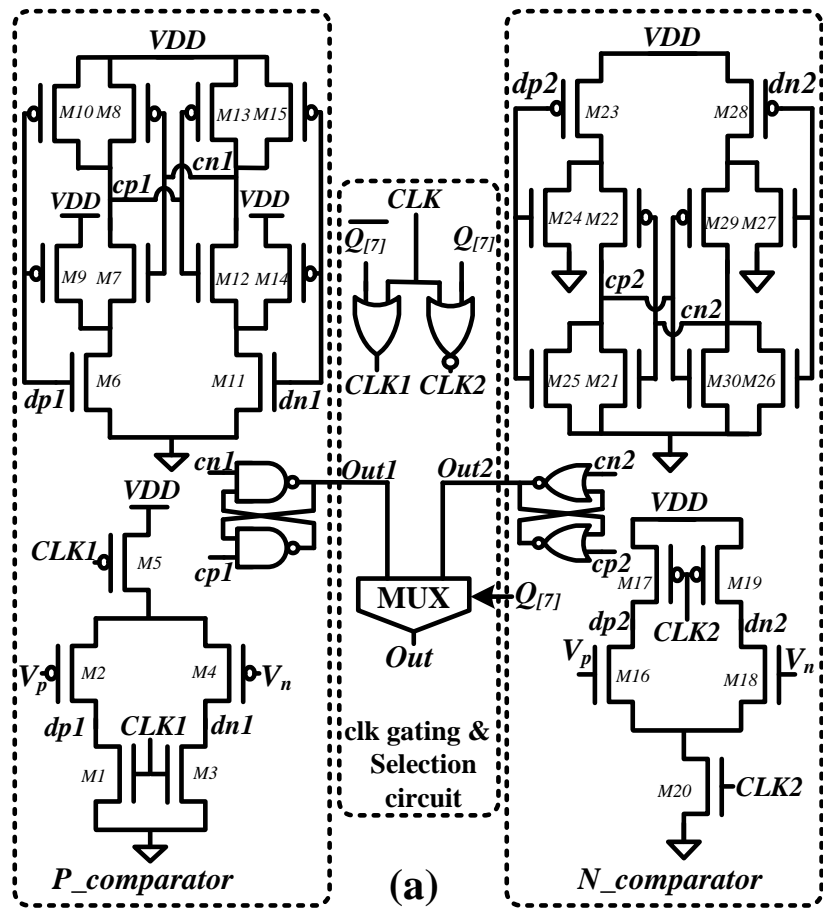


Fig. 4.11. Proposed comparator circuit consisting of *P_comparator* and *N_comparator* and (b) simulated offset (500 MC runs).

the two comparators will operate during each comparison. Thus, there is no additional power consumption when compared with the comparator in [41]. To minimize the common-mode input dependent offset, the width and length of

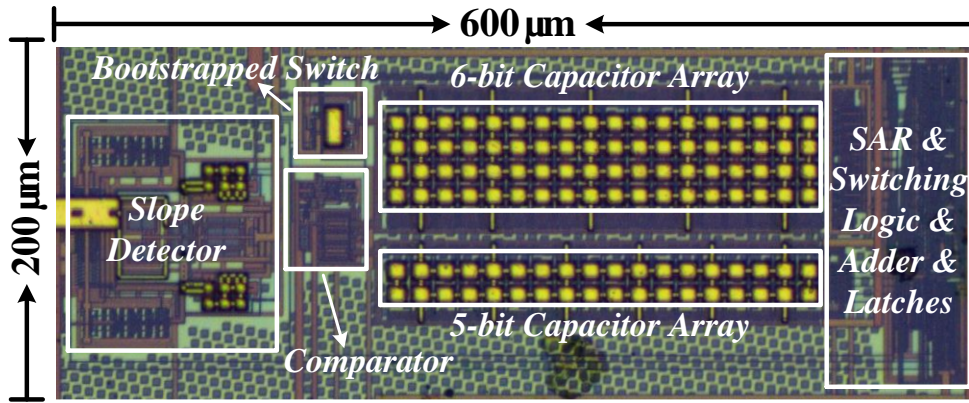


Fig. 4.12. Micrograph of the proposed ADC chip.

input transistors are designed to be large. Also, long transistor with small flowing current of the tail transistor is used to reduce comparator offset. The layout utilizes common-centroid technique along with dummy transistors to achieve better matching. Fig. 4.11(b) provides the Monte Carlo (MC) simulation result of the comparator offset against the input common-mode voltage. This comparator is used in the proposed adaptive delta-sampling SAR ADC.

4.7 Measurement Results

The proposed ADC is fabricated in 0.18-μm CMOS process, and its micrograph is given in Fig. 4.12. The core area occupies 0.12 mm² (600 μm × 200 μm).

To validate the proposed ADC, pre-recorded neural signal as mentioned in Section 4.3 is used as the input signal. Fig. 4.13 shows the measured transient response of the ADC with sampling frequencies of 20 kHz/2 kHz. Fig. 4.13(a) shows the input neural signal and a zoomed-in neural spike. Fig. 4.13(b) illustrates the sampling frequency selection signal sl and sampling frequency f_s

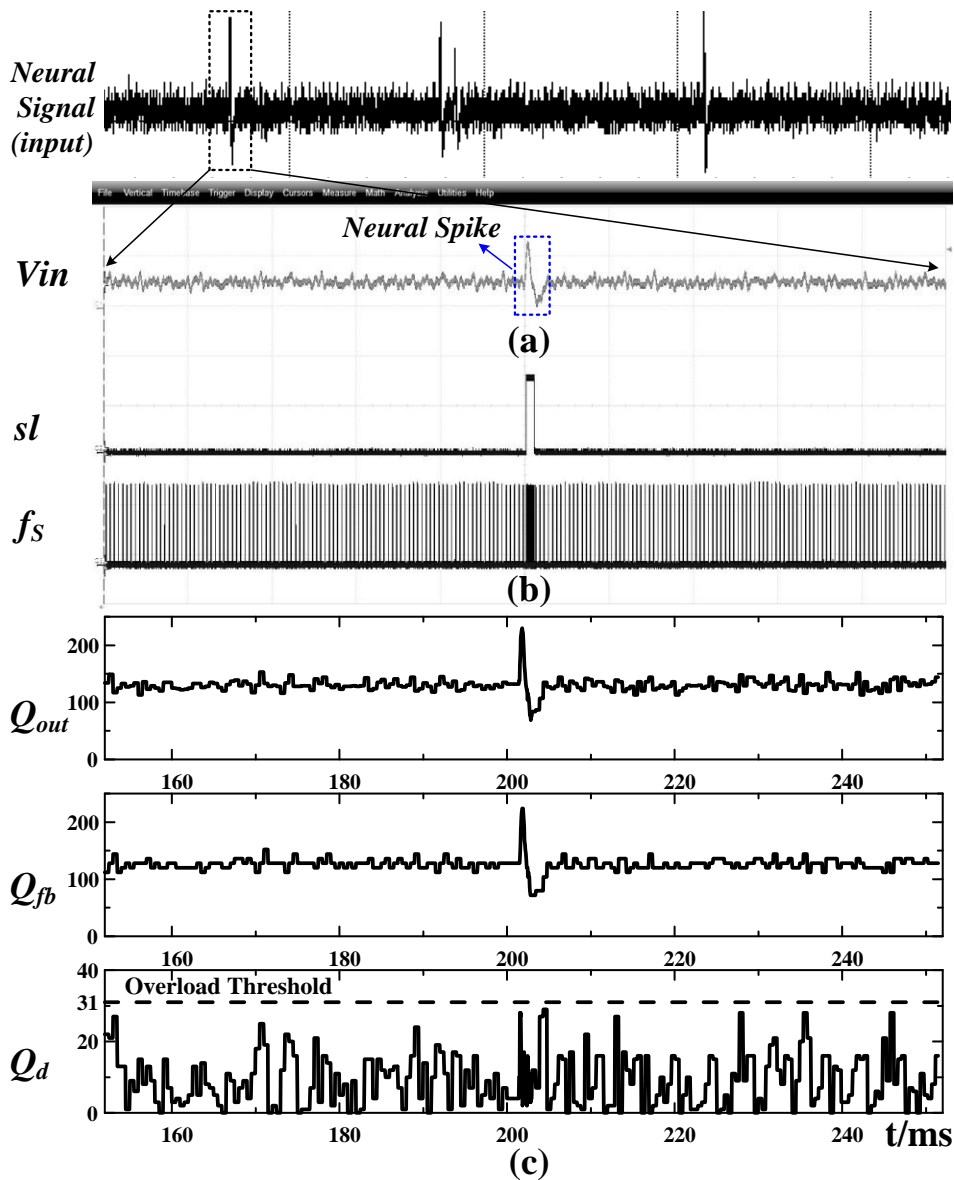


Fig. 4.13. Measured transient response of proposed ADC with neural signal input: (a) input neural signal and zoomed-in neural spike, (b) sampling frequency selection signal sl and adaptive sampling frequency f_s , (c) output of ADC Q_{out} , input of 5-bit DAC Q_{fb} and 6-bit ADC output Q_d (except S_n).

of the ADC. It can be observed that the proposed ADC is adaptively switched between 2 kHz and 20 kHz to prevent overload during instances of spikes. Fig. 4.13(c) shows the output data of the adaptive delta-sampling ADC. From the waveform of Q_d , we can see that the 6-bit ADC does not have an overload since Q_d is always less than 31.

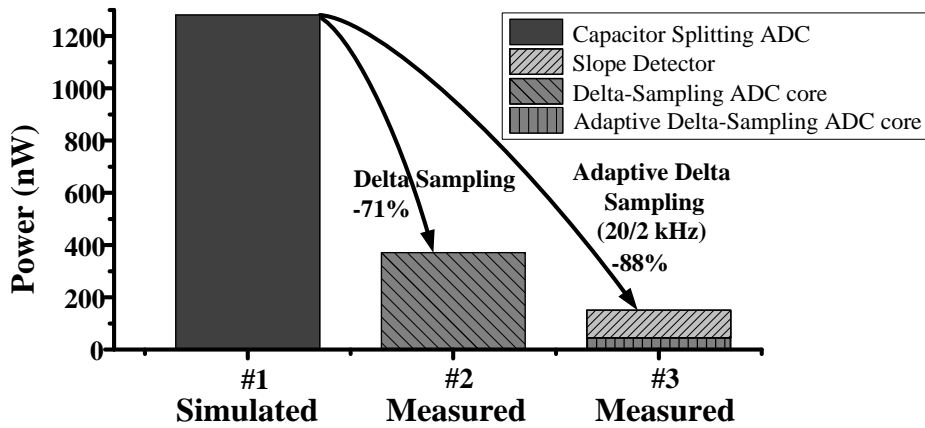


Fig. 4.14. Power reduction of proposed ADC. #1: Simulated power consumption of capacitor splitting SAR ADC. #2: Measured power consumption of proposed delta-sampling ADC. #3: Measured power consumption of proposed adaptive delta-sampling ADC.

Fig. 4.14 shows the power measurement results of the proposed ADC. For comparison, we provide also the simulated power consumption of a conventional capacitor splitting ADC in Fig. 4.14. The same dynamic comparator and SAR logic circuit are used in the conventional ADC for fair comparison. The input signal is the same neural signal as mentioned above. The details of the experimental case studies in Fig. 4.14 are described as follows: #1 is the simulated power consumption of conventional capacitor splitting ADC with a constant sampling frequency of 20 kHz, #2 is the measured power consumption of proposed ADC with 20 kHz sampling frequency (the adaptive control is turned off), #3 is the measured power consumption of proposed ADC with 20 kHz/2 kHz sampling frequency (the adaptive control is turned on). From Fig. 4.14, it can be observed that by using delta-sampling, the proposed design can achieve a power reduction of 71% when compared with the conventional capacitor splitting ADC, and an additional 17% power reduction is achieved if the adaptive delta-sampling is adopted. The measured total power

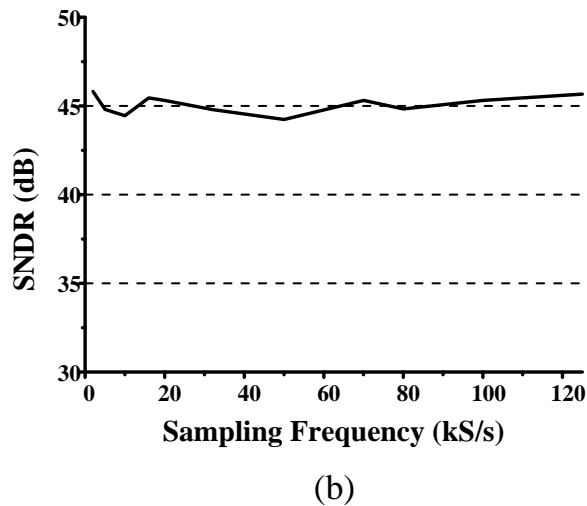
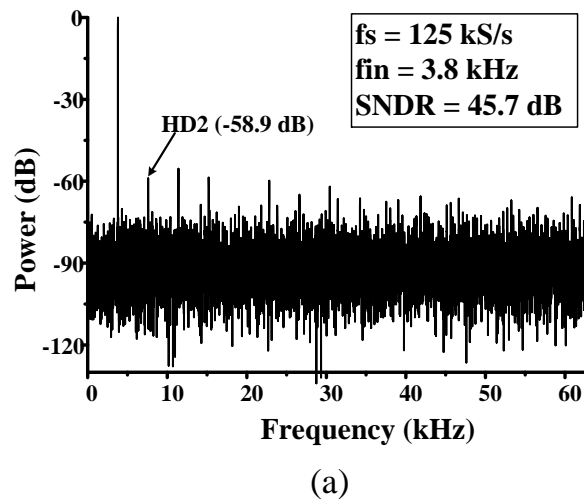


Fig. 4.15. Performance of proposed ADC: (a) output spectrum operating at 125 kS/s and (b) SNDR versus sampling frequency.

consumption of the proposed ADC is only 151 nW, including 106 nW consumed by the slope detector.

Fig. 4.15(a) shows the dynamic performance of the proposed ADC operating at 1-V supply voltage with 125 kS/s sampling frequency. The SNDR can achieve 45.7 dB, which is equivalent to 7.3 ENOB. The SNDR is around 45 dB for sampling frequency between 1 kHz to 125 kHz, as denoted in Fig. 4.15(b).

A comparison between the proposed design and other state-of-the-art SAR ADCs reported in year 2009 to 2015 is tabulated in Table 4.1. It can be seen that designs [15, 39, 49, 72-74] which were based on the advanced processes (e.g. 90 nm, 65 nm) with smaller unit capacitors and feature sizes are able to achieve better DC-FOM/AC-FOM than those implemented in the 0.18 μm process. Also, some of the 0.18 μm -based designs have better DC-FOM/AC-

Table 4.1 ADC Performance Comparison

Ref.	App.	Tech. (nm)	VDD (V)	Res. (bit)	Rate (kS/s)	Unit Cap. (fF)	SNDR (dB)	Power (nW)	DC-FOM (fJ/co.)	AC-FOM (fJ/co.)	DC-FOM _a (fJ/fF/co.)	AC-FOM _a (fJ/fF/co.)
[39]	--	40	0.45	10	200	1.5	55.7	84	0.85	0.85	0.56	0.56
[15]	ECG	65	0.6	10	1.1	0.25	57.3	1	1.7	1.7	6.8	6.8
[72]	--	65	0.6	12	40	0.25	62.5	97	2.2	2.2	8.8	8.8
[38]	--	65	0.55	8	20	65	47	146	40	40	0.61	0.61
[49]	--	90	0.4	10	500	5	54.3	500	2.37	2.37	0.47	0.47
[73]	--	90	0.35	10	100	--	56.3	170	3.2	3.2	--	--
[74]	--	90	0.4	10	250	--	53.7	200	2.02	2.02	--	--
[37]	--	180	1	10	10000	5	60	98000	11	11	2.2	2.2
[75]	--	180	0.6	9	100	150	54	1300	33	33	4.5	4.5
[70]	--	180	0.5	10	4	72	59.3	31	10.3	16	0.14	0.22
[16]	Neural	180	0.45	9	200	--	51.5	2430	39.4	39.4	--	--
[17]	iEEG	180	1.8	10	62.5	20	59.3	3000	63	547	3.15	27.3
[18]	Accel.	180	0.7	4-8	0.015~50	150	52.2	25000	1502	34140	10	227.6
[19]	Neural	180	1.2	10	20	--	57.1	2600	221	1169	--	--
[76]	--	250	--	8	31	--	45	87	18.9	18.9	--	--
[20]	Neural	350	3	8	14	--	40.9	2770	2186	3056	--	--
This Work	Neural	180	1	8	20/2	240	45.3/45.8	151	48	487	0.2	2.02

Notes: DC-FOM = Power / (2^{ENOB} × fs); *Maximum fs is used.

AC-FOM = Power / (2^{ENOB} × 2 × BW).

FOM than the proposed design and this is mainly due to the adoption of smaller unit capacitor (5 fF in [20]) or operating at ultra-low supply voltages (0.6-V in [75], 0.5-V in [36] and 0.45-V in [16]). Comparing with designs [17-19], which operate at the nominal supply voltage, the proposed design is able to attain a better DC-FOM/AC-FOM. To compare the ADC efficiency independent of the unit capacitor size, as introduced in [40], the DC-FOM/AC-FOM normalized to the unit capacitor, i.e., DC-FOM_a/AC-FOM_a, can be considered. It can be seen from Table 4.1 that the proposed design has a relative low DC-FOM_a/AC-FOM_a.

4.8 Conclusion

This chapter presents a novel ADC with adaptive delta-sampling for ultra-low power sensing applications. The characteristic of burst-like or sparse signals is analyzed and we find that that these signals vary slowly during most of duty cycle. It can be observed that the first 4 MSBs remain the same during several consecutive samples both in ECG and neural signals. By reducing the binary search range through delta-sampling, the power consumption of ADC is significantly reduced when applied for converting the sparse signals. In the meanwhile, the overload of the ADC is avoided by adaptively adjusting the sampling frequency according to the slope of the input signal. The ADC consumes only 151 nW while achieving 7.3 ENOB with adaptive sampling frequency of 20 kHz/2 kHz for a neural signal acquisition application.

Chapter 5

A 10-bit 300 kS/s Reference-Voltage Regulator Free Asynchronous SAR ADC

As one of the typical health monitoring applications, wireless implantable medical devices are powered via wireless power transfer, as shown in Fig. 5.1. A rectifier is mandatory to convert the coupled AC power into DC power. Even with advanced rectifiers such as the reconfigurable resonant regulating rectifier (R^3 rectifier), the ripple of the rectified voltage can still be in tens of mV [77, 78]. For conventional SAR ADCs adopted in such systems [16, 40, 43, 45, 79-82], a dedicated regulator is needed to stabilize the reference voltage to the ADC core. However, the regulator consumes significant power consumption [43, 79, 80]. Besides, decoupling capacitors of a few hundred pF or larger values are needed to maintain a stable operation of the regulator [83, 84]. As decoupling capacitors are preferred to be on chip in wireless implantable medical devices for system miniaturization, the increase in silicon area and hence cost are inevitable.

However, as mentioned in Section 2.4 , there are a few designs had looked at optimizing the reference-voltage regulator and clock source for the ADC. It has been found that if the power consumption of the reference-voltage regulator

SAR ADC can operate in fully asynchronous mode, where the ADC can function without any external clock source. The proposed design achieves good SNDR under supply voltage fluctuation.

5.1 Charge-Sharing SAR

The charge-sharing SAR ADC of Fig. 5.2 uses passive charge sharing instead of the active charge redistribution that is commonly deployed in conventional SAR ADCs [45]. During the sampling period, the input signal is sampled by sampling capacitors C_s . Meanwhile, the DAC capacitors are pre-charged with binary-scaled charges, i.e. $C_i \times V_{ref}$. Once the sampling period is completed, a comparator performs the first comparison and following the comparison result, the MSB charge is added or subtracted to the sampling capacitors, by turning on one of the pairs of switches S_p or S_n . By doing this, the differential charge stored in the sampling capacitors will converge to zero. This

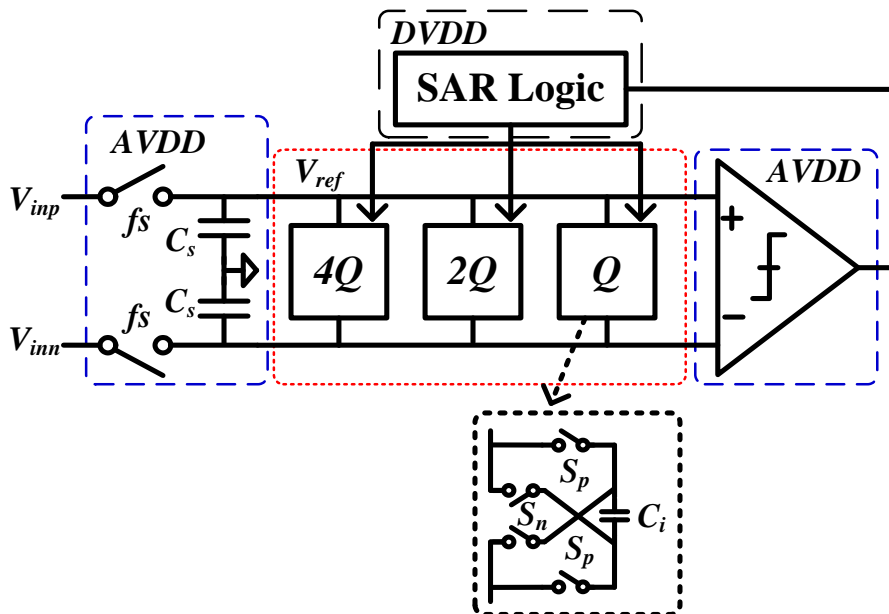


Fig. 5.2. 3-bit charge-sharing SAR ADC.

operation is repeated until the LSB decision is obtained, which also symbolizes that one conversion is completed.

In order to analyse the influence of power line ripples, we separate power supply of charge-sharing SAR ADC into three power domains, i.e. $AVDD$, $DVDD$ and V_{ref} . $AVDD$ is used to supply the dynamic comparator and sampling switch, while $DVDD$ is for the supply SAR logic circuit. DAC capacitors are powered from V_{ref} . For the dynamic comparators [85], the variation on $AVDD$ will cause a different delay. With smaller $AVDD$, the delay will be longer. In other words, if the minimum value of $AVDD$ can satisfy the speed requirement, a ripple of tens of mV will have minimum effects on the comparator to influence the final performance of the ADC. The effects on the sampling switch are the switch-on resistance and coupling effect. By using clock boosting technique, the effect on switch-on resistance is also reduced to a minimum. The coupling effect is lessened by using the minimum size of transistor to ensure minute coupling capacitor.

For the SAR logic circuit powered by $DVDD$, the ripple with tens of mV amplitude will affect only the delay of these digital circuits. If the minimum $DVDD$ satisfy the timing constrains, the output of the rectifier can be engaged directly. Basically, the $AVDD$ and $DVDD$ can both be powered by the output of the rectifier in the wireless implantable medical device. However, the output voltage of the rectifier with large ripples cannot be used directly as the power source, i.e. V_{ref} , for charging the DAC capacitor. This because the DAC capacitor are pre-charged with a charge which is $Q_i = C_i \times V_{ref}$. Any disturbance or error in the reference value V_{ref} will cause a deviation of charges, i.e. Q_i , pre-charged in DAC capacitors. Consequently, the digitized output codes deviate

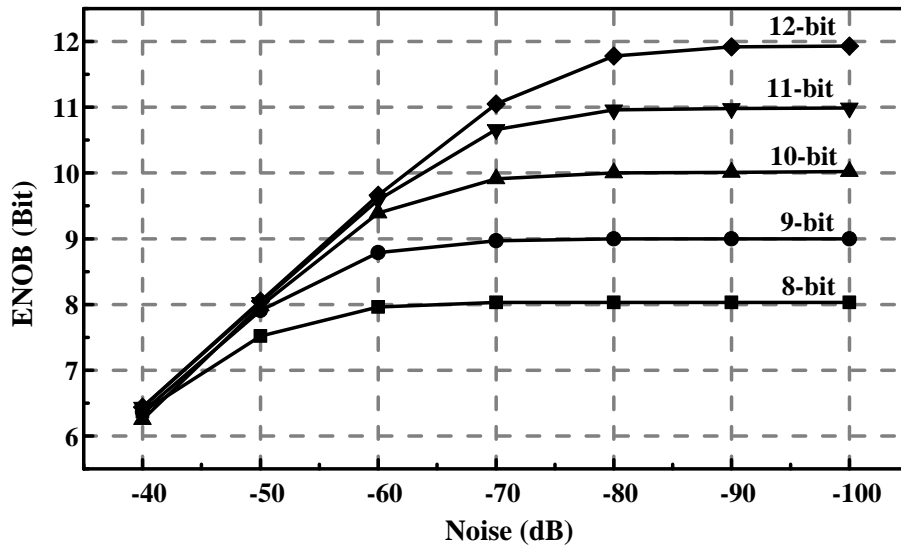


Fig. 5.3. Influence of reference voltage noise on ENOB for charge-sharing SAR ADC with different resolution.

from the correct value giving errors, which will introduce large noise in the charge-sharing SAR ADC and thus worsen the ENOB.

Matlab based simulation is performed to show the influence of V_{ref} noise on ENOB in charge-sharing SAR ADC, as demonstrated in Fig. 5.3. For example, in a 10-bit charge-sharing SAR ADC with 1-V V_{ref} , the noise of the voltage reference source should be lower than -60 dB or 1 mV, in order to achieve a larger than 9.5 ENOB. In the wireless power transformer, the ripple of the rectifier output voltage is tens of mV, which cannot satisfy this requirement. In conventional system, a power hungry voltage regulator is used to regulate this voltage to an acceptable level and with sufficient drivability. Also, the power dissipation is typically ignored in low power applications.

5.2 System Architecture of Proposed SAR ADC

As discussed previously, in wireless-powered implantable medical devices, the output voltage of the rectifier has large ripple and cannot be used directly as

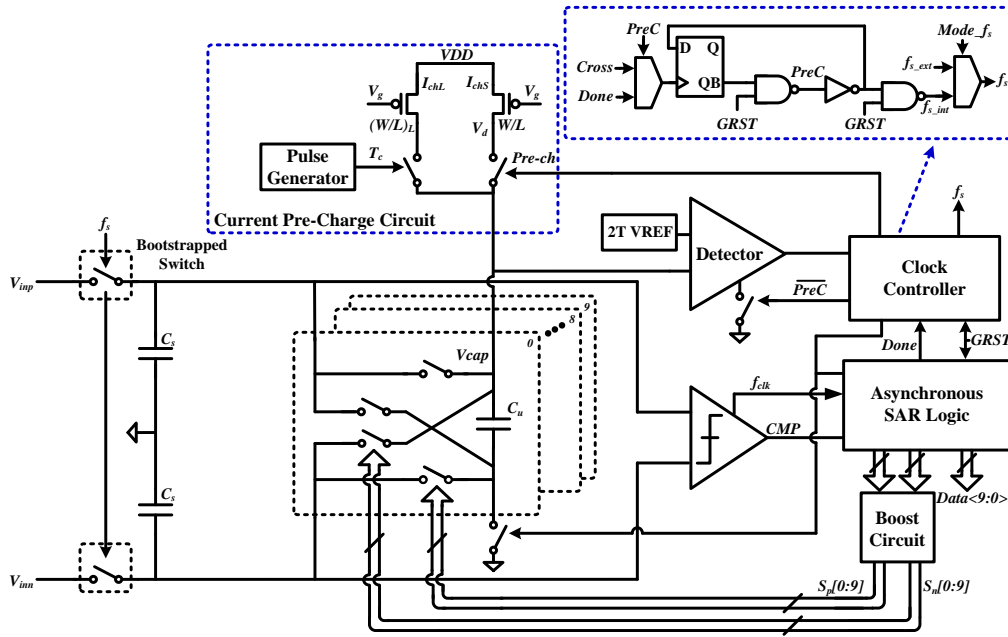


Fig. 5.4. Architecture of proposed reference-voltage regulator free SAR ADC with self-timed pre-charging.

a reference voltage in conventional SAR ADC. Therefore, a dedicated regulator with decoupling capacitor is engaged to provide a stable reference voltage to charge the DAC capacitors, causing large power and area consumption.

In order to eliminate the reference-voltage regulator as well as the decoupling capacitor, we propose a SAR ADC with self-timed pre-charging, as shown in Fig. 5.4. It consists of a current pre-charging circuit, a charge detector, and a 10-bit conventional charge-sharing SAR ADC [45] using asynchronous SAR logic. The sampling clock (i.e., f_s) can be selected between the external sampling clock (i.e., f_{s_ext}) and the internal sampling clock (i.e., f_{s_int}), both controlled by the same selection signal (i.e., $Mode_f_s$). The MSB uses 32 unit capacitors, while the 5 LSBs use 1 unit capacitor each. The unit capacitor used is a 49 fF MIM capacitor, which is the minimum-size capacitor for the given technology.

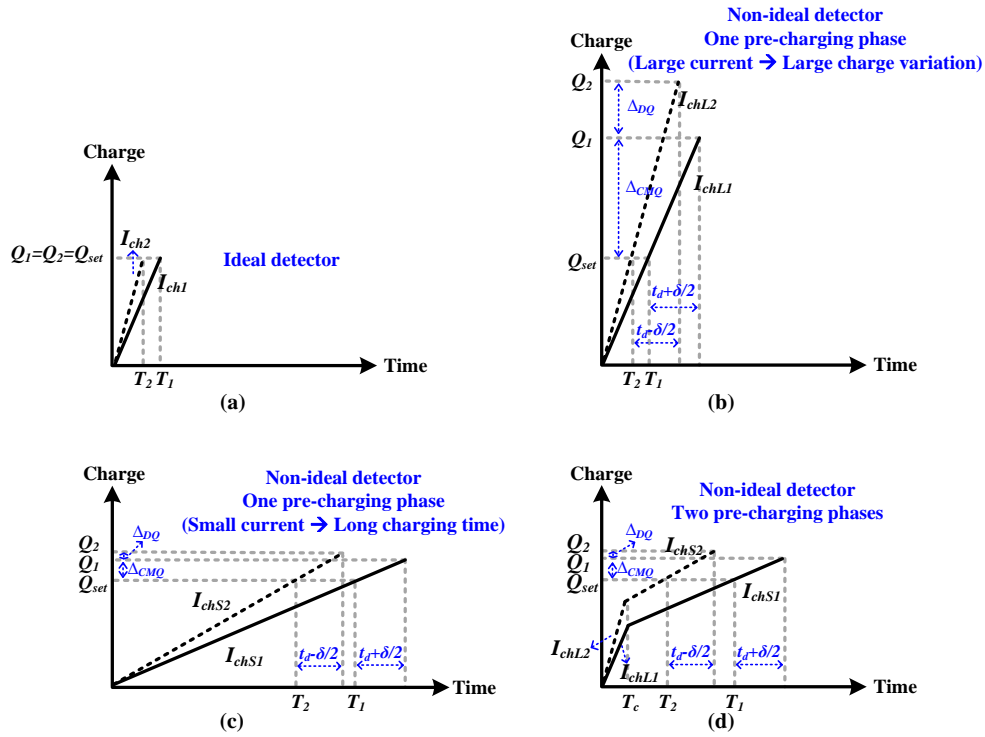


Fig. 5.5. Self-timed pre-charging (a) ideal detector, (b) non-ideal detector using one pre-charging phase with large current, (c) non-ideal detector using one pre-charging phase with small current, (d) non-ideal detector using two pre-charging phases.

During the sampling period, the input signal is sampled onto the sampling capacitors C_s . At the same time, the DAC capacitors are pre-charged with a current source. Controlled by a charge detector, the current source will be turned off when the charge reaches a pre-set value Q_{set} , which we call self-timed pre-charging. Fig. 5.5(a) shows the pre-charging process with different charging currents, i.e., I_{ch1} and I_{ch2} . In Fig. 5.5(a) we assume that the charge detector is ideal, i.e. the response time is zero. Although I_{ch1} and I_{ch2} are different, the same charge is obtained through different charging times (i.e., T_1 and T_2). However, in practice, the charge detector has a response time or delay. For wireless-powered medical devices, the delay is affected by the supply voltage fluctuation. As illustrated in Fig. 5.5(b), with a small difference in the supply voltage, the

delay will be $t_d + \delta/2$ and $t_d - \delta/2$, respectively. Here, t_d is the basic delay of the charge detector, and δ is a delay difference caused by the supply voltage fluctuation. The delay difference induces a difference in the charge, i.e., Δ_Q , which can be expressed as

$$\Delta_Q = Q_2 - Q_1 = \int_0^{t_d - \delta/2} I_{ch2} \times t - \int_0^{t_d + \delta/2} I_{ch1} \times t = \Delta_{CMQ} + \Delta_{DQ} \quad (5.1)$$

Here, Δ_{CMQ} is the common part of charge variation and Δ_{DQ} is the differential part. The common part of charge variation may cause a gain error but it can be removed by calibration as that in conventional ADC. However, the differential part is not constant and cannot be removed by calibration. For the pre-charging scheme, large pre-charging current is used to shorten the pre-charging time to achieve sufficient sampling rate. However, larger current is more sensitive to supply voltage fluctuation, thus causing large charge variation, as shown in Fig. 5.5(b). This can be explained as follow. With a current source as shown in Fig. 5.4, the charging current, i.e., I_{ch} , can be expressed as

$$I_{ch} = \frac{KW}{2L} (VDD - V_g - V_{th})^2 \text{ (active region)} \quad (5.2)$$

$$I_{ch} = \frac{KW}{L} \left[(VDD - V_g - V_{th}) \times (VDD - V_d) - \frac{(VDD - V_d)^2}{2} \right] \text{ (triode region)} \quad (5.3)$$

where K and V_{th} are the transconductance parameter and threshold voltage of the *PMOS*, respectively. To determine I_{ch} 's sensitivity to VDD , derivative of I_{ch} is performed with respect to VDD in Equation (5.2) and (5.3). This gives

$$\frac{\partial I_{ch}}{\partial VDD} = \frac{KW}{L} (VDD - V_g - V_{th}) \quad (5.4)$$

From Equation(5.4), it can be seen that with smaller ($VDD-V_g-V_{th}$) or current I_{ch} , the current's sensitivity to VDD is smaller, which results in smaller charge variation (see Fig. 5.5(c)). However, smaller pre-charging current needs longer charging time, and this limits the sampling rate of the ADC.

To achieve sufficient sampling rate while ensuring a small charge variation (less than 1 LSB charge), we proposed a pre-charging scheme with two charging phases, as shown in Fig. 5.5(d). During the first charging phase, the DAC capacitors are quickly charged with large charging current (i.e., I_{chL}) and constant charging time (i.e., T_c). In the second charging phase, small charging current (i.e., I_{chS}) is used to complete the rest of charging and is turned off when the charge reaches the pre-set value Q_{set} . By using the two-phase pre-charging scheme, the charge variation is reduced and the charging time is also shortened.

5.3 Fully Asynchronous Operation

To further improve on the overall energy-efficiency of the SAR ADC, the proposed SAR ADC is to operate without any external clock source. This can be achieved by assigning internal sampling clock (f_{s_int}) to f_s , as shown in Fig. 5.4. f_{s_int} is generated during the self-timed pre-charging process which acts as a relaxation oscillator. The binary search algorithm is controlled by the asynchronous SAR logic [85]. Fig. 5.6 shows the timing diagram of the proposed SAR ADC. The active low global reset signal ($GRST$), which is an off-chip signal, is used to reset all other signals in the SAR ADC. After the first conversion is completed, a pulse *Done* is generated, which changes the phase of the pre-charging signal *PreC* from low to high. During the pre-charging phase, the DAC capacitors are charged by the proposed self-timed pre-charging

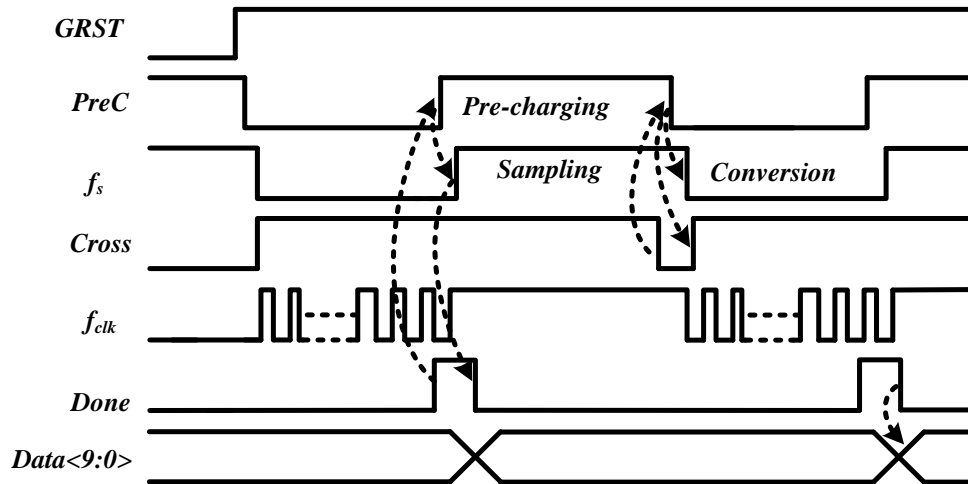


Fig. 5.6. Timing diagram when the proposed ADC is operating in fully asynchronous mode without external clocks.

approach. At the same time, *PreC* triggers *f_s* to sample the input signal. When the pre-charged charge reaches a pre-set value, the detector generates a down pulse *Cross*. This down pulse changes the phase of *PreC* from high to low, i.e., switching off the current source. Meanwhile, \overline{Prech} is triggered to a high level to shut down the detector to save on power consumption. Following which, the dynamic comparator begins to compare the voltages of the two terminals of the capacitor array. When the comparison is completed, the comparator will generate an internal clock *f_{clk}* for the asynchronous SAR logic. After ten cycles of successive approximation procedure, the conversion process ends and outputs ten bits of comparison results *Dataout<9:0>*. By combining pre-charging scheme and the asynchronous SAR logic, the proposed SAR ADC can function without any external clock.

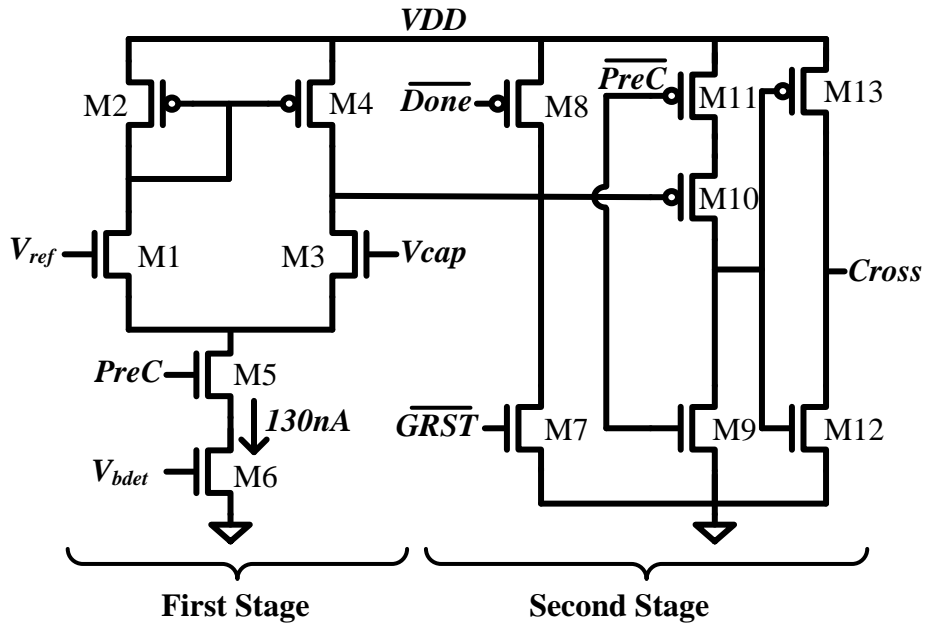


Fig. 5.7. Schematic of proposed charge detector.

5.4 Charge Detector, V_{ref} Generator and Current Source

Fig. 5.7 shows the schematic of the charge detector used for controlling the self-timed pre-charging. It consists of two stages. The first stage amplifies the input signals and converts the voltage difference between V_{cap} and V_{ref} to a single-ended output. The output of the first stage will trigger the second stage when V_{cap} crosses V_{ref} . To minimize the power consumption, the first stage operates only during the pre-charging phase, i.e., when $PreC$ is active high. Simulation shows that the delay of the charge detector varies from 418.3 ns to 410.8 ns when the supply voltage is changed from 0.775 V to 0.825 V.

The reference voltage V_{ref} of the charge detector is generated by a 2-Transistor (2T) voltage reference [86], as shown in Fig. 5.8(a). Because V_{ref} depends on the threshold voltage difference between the two transistors [86]

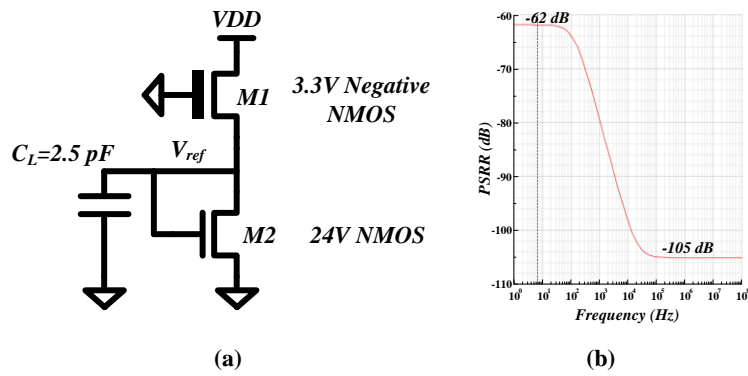


Fig. 5.8. 2T voltage reference (a) schematic, (b) PSRR.

and a large V_{ref} is preferred in the proposed SAR ADC, 3.3-V negative NMOS (smallest available threshold voltage in the chosen 0.18- μm process) and 24-V NMOS (largest available threshold voltage in the chosen 0.18- μm process) are deployed in this 2-T voltage reference design. A load capacitor, i.e., C_L , with a value of 2.5 pF is added to improve the PSRR of the output. Fig. 5.8(b) demonstrates that the PSRR of V_{ref} is -62 dB and -105 dB at 100 Hz and 10 MHz, respectively. Besides, the simulated output referred noise of this 2T

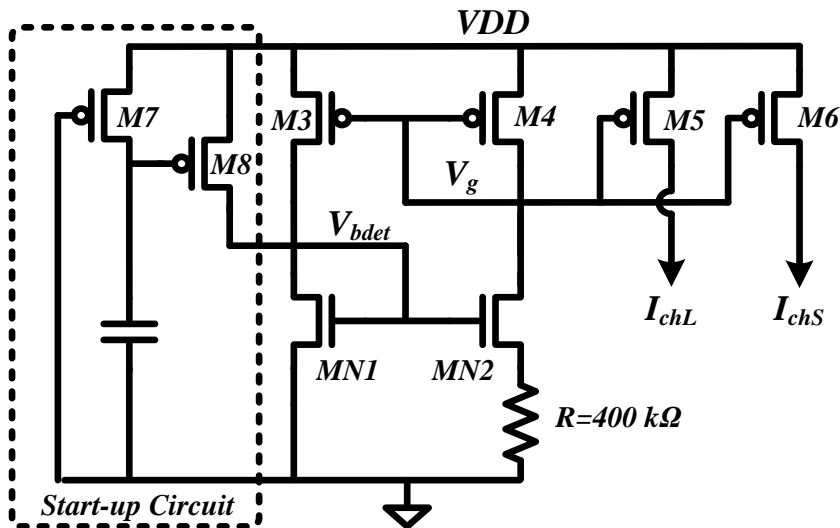


Fig. 5.9. Schematic of current source used for self-timed pre-charging.

voltage reference is $41 \mu\text{V}$, which is negligible as compared to the 1 LSB.

The schematic of the current source used for pre-charging is given in Fig. 5.9. The circuit consists of a beta-multiplier reference, a start-up circuit and a current mirror. The reference current, I_{ref} , is equal to the difference of the threshold voltage between $MN1$ and $MN2$ divided by the value of resistor R , which is supply independent. The output currents I_{chL} and I_{chS} , are generated from I_{ref} through current mirror. The I_{chL} is used as the first phase charging current and is about $14 \mu\text{A}$. The I_{chS} is used as the second phase charging current and is about 200 nA . The values of I_{chL} and I_{chS} are determined through extensive simulation by considering both the charge variation and pre-charging time. Fig. 5.10 shows that when VDD is larger than 0.6 V , the sensitivity of I_{chL} and I_{chS} to VDD are $19 \mu\text{A/V}$ and 36 nA/V , respectively. With smaller current, the sensitivity is much lower, which verified the previous analysis in Section 5.2. To save power and area, the beta-multiplier reference also generates V_{bdet} for the first stage amplifier in the charge detector.

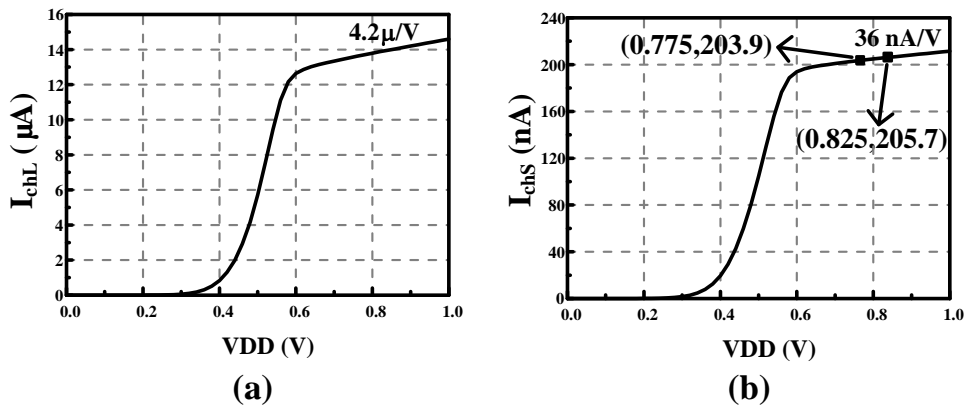


Fig. 5.10. Pre-charging currents, I_{chL} and I_{chS} , vary with VDD .

Simulation also shows that the I_{chS} varies from 203.9 nA to 205.7 nA when the supply voltage varies from 0.775 V to 0.825 V. Together with the delay variation (from 418.3 ns to 410.8 ns) or the input offset voltage of charge detector, the charge variation can be calculated from Equation (5.1). The calculated common part of the charge variation is 84.9 fC. Even though the common part is large, as discussed previously, it only causes a gain error and the error can be easily removed through calibration. Benefiting from the two-phase pre-charging scheme, the differential part is only 0.4 fC which is negligible as compared to the 1 LSB charge (~2.5 fC). Simulation shows that the two-phase pre-charging time varies from 1.1 μ s to 2.3 μ s, when supply voltage varies from 0.9 V to 0.7 V. This pre-charging time is short sufficiently for a 300 kS/s sampling rate.

5.5 Comparator

The two-stage dynamic comparator of Fig. 5.11 [87-89] is used in the proposed ADC. Monte Carlo simulation of the comparator offset showed a mean offset of -88 μ V and a standard deviation of 1.2 mV. In order to calibrate this offset, a 4-bit binary-scaled array of variable capacitors is added to the output nodes of the first stage. With different capacitor loads, the offset of the comparator is different [87]. NMOS transistors are used to implement the small variable capacitor. When the gate control signal ($CP<0:3>$ or $CN<0:3>$) are connected to VDD , a channel is created in the transistor and oxide capacitor is added to the output node of the first stage. When 0 V is applied to transistor gate, no channel is present. The calibration step is 0.15 mV with a total of 2.2 mV calibration range.

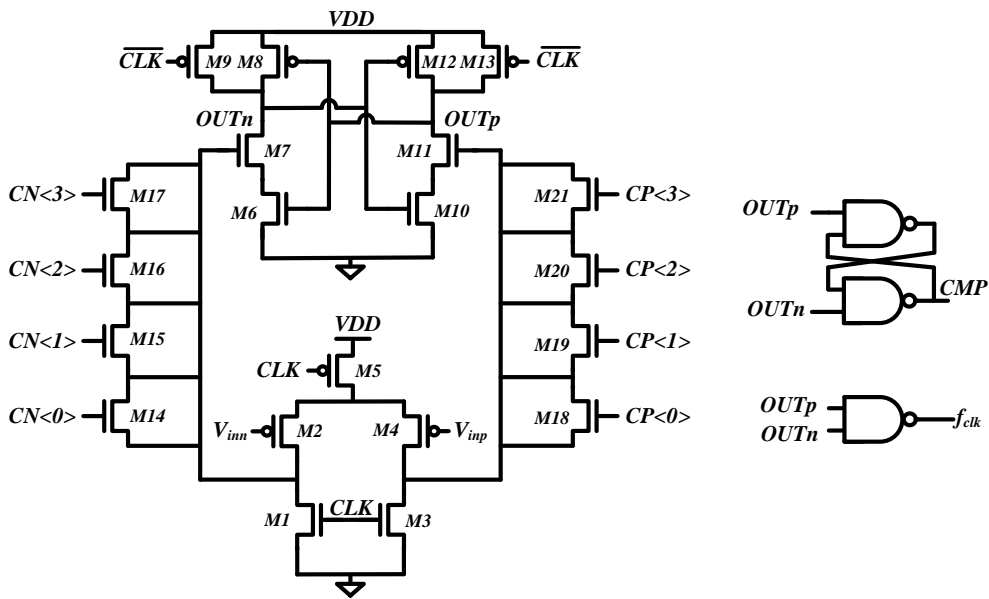


Fig. 5.11. Schematic of two-stage dynamic comparator.

The internal clock (i.e., f_{clk}) and comparator clock (i.e., CLK) are generated by the circuits shown in Fig. 5.12. The outputs ($OUTp$ and $OUTn$) of the first stage are reset to high. When the comparator completes its comparison, one of the two outputs will transit from high to low. This transition can be detected by the following NAND gate, generating an active-high clock, i.e., f_{clk} . f_{clk} will generate CLK for the comparator. The sampling clock f_s and end of conversion indication signal $Done$ are used to block the clocks to save on power consumption.

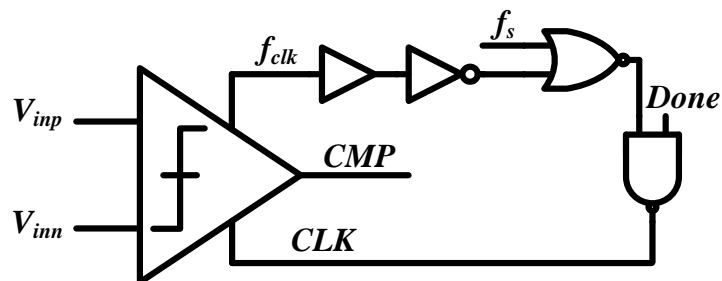


Fig. 5.12. Clock generator architecture.

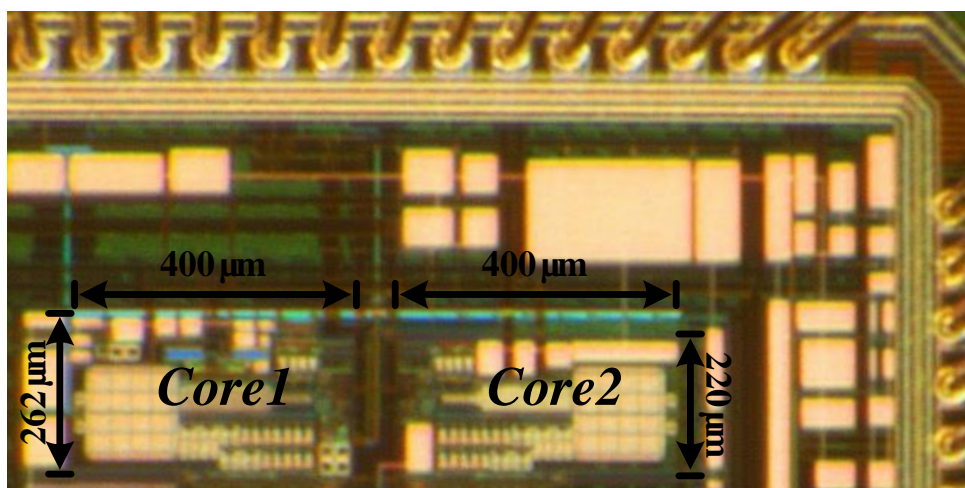
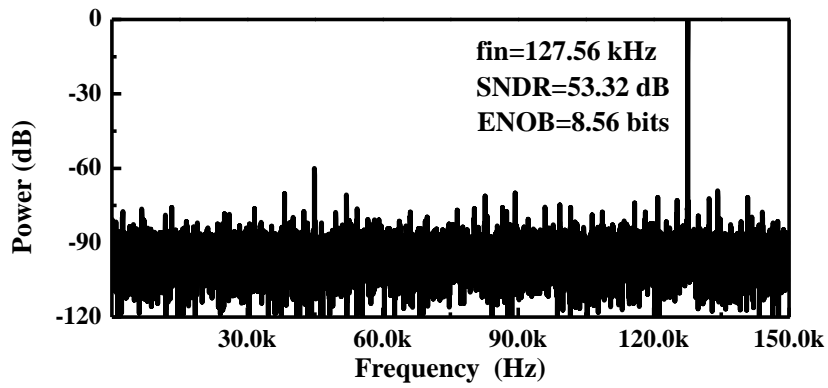


Fig. 5.13. Die photo of two SAR ADCs where Core1 is the proposed design and Core2 is a conventional design.

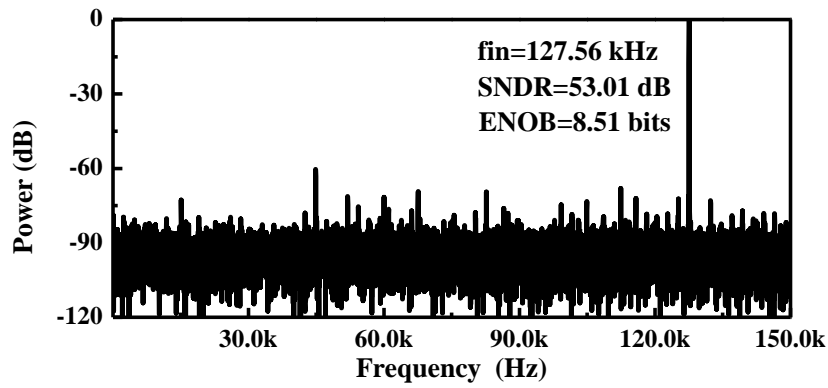
5.6 Measurement Results

The proposed reference-voltage regulator free SAR ADC has been implemented and fabricated with a 0.18- μm CMOS technology. The chip micrograph is shown in Fig. 5.13. *Core1* is the proposed SAR ADC with area of 0.105 mm². *Core2* is the conventional SAR ADC where all the circuits are the same as *Core1* except that the self-timed pre-charging circuits are not included and the reference voltage is directly from external supply. The *Core2* occupies 0.088 mm².

The proposed SAR ADC uses a single power supply of 0.8 V. To demonstrate its insensitivity to supply voltage fluctuation, a sinusoidal fluctuation with different amplitude from 0 to 200 mV_{pp} is added to the supply voltage. The following SNDR and linearity performances are measured using external sampling clock (i.e., f_{s_ext}). The frequencies of the sinusoidal fluctuation are set to 134.2 kHz and 13.56 MHz, which are widely used carrier frequencies



(a)



(b)

Fig. 5.14. Measured output spectrum operating at 300 kS/s, when a sinusoidal fluctuation of 50 mV_{pp} is added to the 0.8 V power supply (a) 134.2 kHz sinusoidal fluctuation, (b) 13.56 MHz sinusoidal fluctuation.

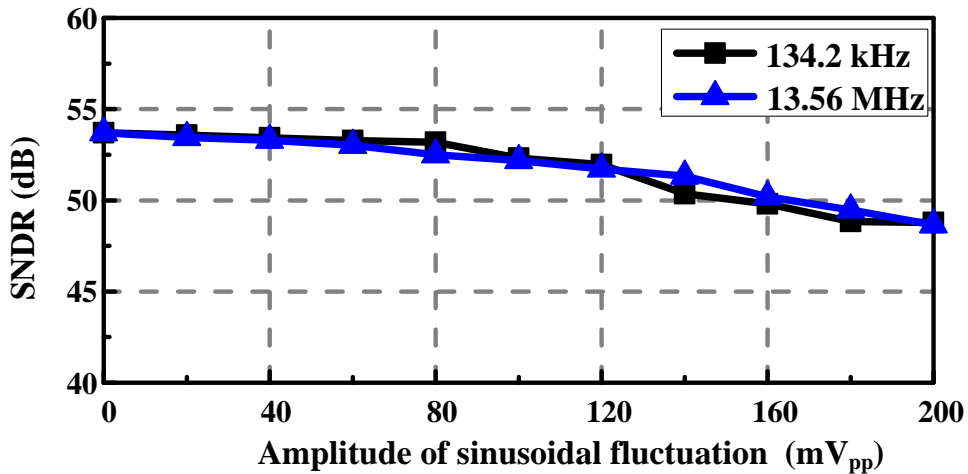


Fig. 5.15. The SNDR versus the amplitude of sinusoidal fluctuation added to the 0.8 V power supply.

in wireless power transfer [77, 78, 90-92]. Fig. 5.14 shows a 32768-point FFT plot for 127.56 kHz input signal sampled at 300 kS/s under sinusoidal

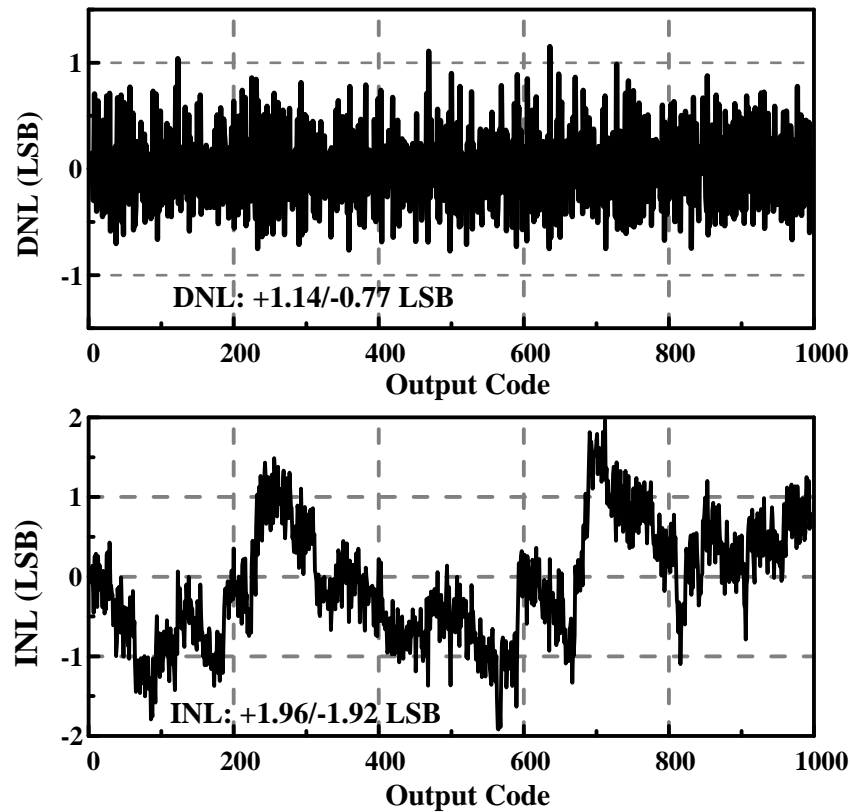


Fig. 5.16 The measured DNL and INL with 50 mV_{pp} sinusoidal fluctuation.

fluctuation of 50 mV_{pp}. The corresponding SNDR and ENOB for 134.2 kHz sinusoidal fluctuation are 53.32 dB and 8.56 bits, respectively. While the corresponding SNDR and ENOB for 13.56 MHz sinusoidal fluctuation are 53.01 dB and 8.51 bits, respectively. Fig. 5.15 shows the SNDR versus the amplitude of the sinusoidal fluctuation. When the amplitude of sinusoidal fluctuation increases from 0 to 200 mV_{pp}, the SNDR decreases by 4.91 dB and 5.05 dB for sinusoidal fluctuation of 134.2 kHz and 13.56 MHz, respectively. As indicated in Fig. 5.16, the measured DNL and INL are +1.14/-0.77 LSB and +1.96/-1.92 LSB, respectively.

The proposed ADC can operate with either the external sampling clock or the internal sampling clock (i.e., fully asynchronous mode). Fig. 5.17 shows the captured measured timing diagram on a logic analyzer, with 50 mV_{pp} sinusoidal

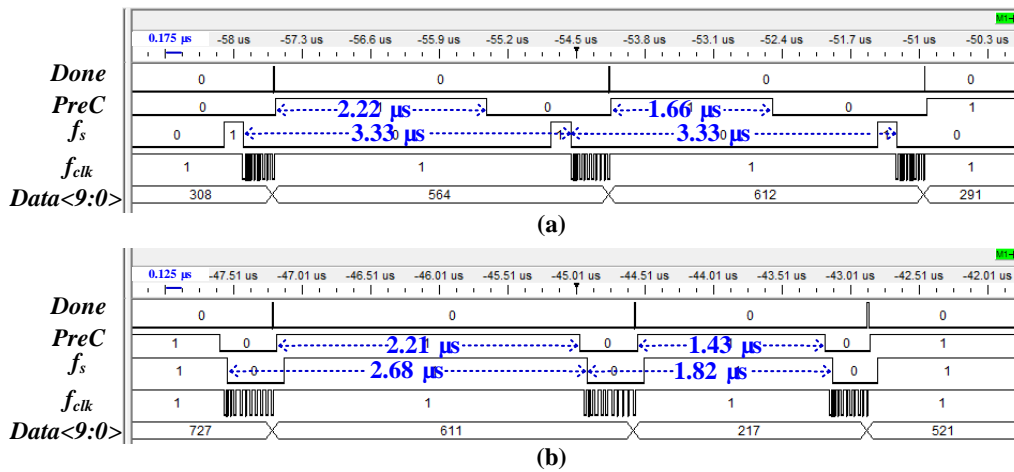


Fig. 5.17 Measured timing diagram (a) using external sampling clock, $f_{s_ext} \rightarrow f_s$, (b) using internal sampling clock, $f_{s_int} \rightarrow f_s$.

fluctuation. When an external sampling clock is applied to f_s , the sampling clock is kept constant while the pre-charging period (i.e., $PreC$) varies with the supply voltage fluctuation, as shown in Fig. 5.17 (a). When the internal sampling clock f_{s_int} is applied to f_s , i.e., operating in fully asynchronous mode, both the sampling clock and the pre-charging period vary with the supply voltage fluctuation (see Fig. 5.17 (b)). Without any external clock source, the proposed ADC can save the power consumption and chip area at system level.

The measured total power consumption of the proposed SAR ADC (i.e., *Core1*) including the self-timed pre-charging circuits is 2.72 μW at 300 kS/s and the corresponding FOM is 23.9 fJ/c-s. Under the same testing conditions, the measured power consumption of the conventional SAR ADC (i.e., *Core2*) is 2.52 μW . Therefore, the power dissipation of the self-timed pre-charging circuits is around 0.2 μW . This accounts for only 7.3% of the total power consumption of ADC, while a reference-voltage regulator typically consumes at least 30% [43] or even several times [79, 80] of the power consumption of ADC.

Table 5.1 ADC Performance Comparison

Performance Comparison	[16]	[81]	[40]	[82]	This work
Tech. (μm)	0.18	0.18	0.13	0.18	0.18
Area (mm^2)	--	0.151 (w/o Reg.)	0.872 (w/o Reg.)	0.118 (w/o Reg.)	0.088 (w/o STP*) 0.105 (w/ STP)
Supply (V)	0.45	0.9	0.5/1	1	0.8
Resolution	9	9	10	10	10
fs (kS/s)	200	100	1100	100	300
SNDR (dB)	51.54	50.1	54.6	58.83	53.32 w/50mV_{pp} Ripple
Power w/o V_{ref} Reg. (μW)	1.35	1.33	15.6	1.72	2.52 w/o STP
FOM w/o V_{ref} Reg. (fJ/c-s)	22.0	51.3	31.8	24.1	22.1 w/o STP
V_{ref} Reg. Power (μW)**	0.54	0.49	53.5	0.34	0
Power w/ V_{ref} Reg. (μW)	1.89	1.81	69.1	2.06	2.72 w/ STP
FOM w/ V_{ref} Reg. (fJ/c-s)	30.8	70.1	140.9	28.7	23.9 w/ STP

*STP stands for self-timed pre-charging.

**Power consumption of reference-voltage regulators needed in [16, 40, 81, 82] are estimated based on the regulator used in [43], with assumption that they have the same regulator FOM_{reg} defined in [83] and same dropout voltage.

Comparisons between the proposed SAR ADC and other existing SAR ADCs fabricated with similar technology nodes are provided in Table 5.1. With 50 mV_{pp} supply voltage fluctuation, the proposed design has similar SNDR as other designs. Noted that the power consumption of the ADC core reported in [16, 40, 81, 82] are without consideration of the reference-voltage regulator. Hence, for fair comparison, we had provided the estimated power consumed in these reference-voltage regulators in Table 5.1. The quiescent current of the regulators are estimated using the regulator FOM formula (i.e., FOM_{reg}) as defined in [83] ($\text{FOM}_{\text{reg}} = C_d * \Delta_{\text{vout}} * I_Q / I^2$, where C_d is the decoupling capacitor,

Δ_{vout} is 1 LSB, I_Q is the regulators' quiescent current and I is the current used to charge DAC capacitors). Assuming that all the designs have the same C_d and FOM_{reg} value as in [43], the quiescent current of the reference-voltage regulator for each design can be calculated using the above FOM_{reg} formula. Besides, we assume a dropout voltage of 0.2 V as in [43]. Based on the quiescent current and the dropout voltage, the total power consumption of regulator for each design can be calculated as shown in Table 5.1. The results show that the proposed self-timed pre-charging SAR ADC achieves a better FOM than the other designs when taking into account the reference-voltage regulator. Including the self-timed pre-charging circuits, the area of the proposed design is similar to that of the other designs without reference-voltage regulator. Moreover, decoupling capacitor is not required in our design, which helps further reduce the total area and cost.

5.7 Conclusion

In this chapter, we had looked at optimizing the reference-voltage regulator and clock source for the ADC. It has been found that if the power consumption of the reference-voltage regulator is included, the FOM of ADC degrades significantly. Therefore, a SAR ADC with self-timed pre-charging is proposed to eliminate power- and area-consuming reference-voltage regulator and decoupling capacitor for wireless-powered implantable medical devices. Fabricated with a 0.18- μm CMOS technology, the proposed self-timed pre-charging SAR ADC achieves a SNDR of 53.32 dB at 0.8 V with 50 mV_{pp} supply voltage fluctuation, while consuming a total power of 2.72 μW at 300

kS/s sampling rate. Including the self-timed pre-charging circuits, the total FOM is 23.9 fJ/c-s and the total area is 0.105 mm².

Chapter 6

Wide Input 12-bit SAR ADC with Digital Calibration

For a generic wireless sensor node or biomedical device, it includes the sensors/actuators, signal processing, communication and energy subsystem [44, 93-95], as shown in Fig. 6.1. The environmental or biopotential signals are sensed by various sensors. The sensor interface circuits convert these sensed signals into digital signals to be processed by the digital signal processing subsystem. Some of the processed results are transmitted to external network for deployment and some are used to control the actuators. To achieve the features of wireless sensor nodes such as long life and small volume, energy- and area- efficient electronic circuits have been popularly engaged, including sensor interface circuits [14, 44, 51, 53, 69], digital signal processing [6, 7, 21] and wireless communication subsystem [96-98]. On the other hand, an energy subsystem with high-energy density is desired to efficiently power the electronic circuitries in these size constrained systems. The Lithium ion (Li-ion) cell with high energy density (80~125 W•h/kg and 200~450 W•h/kg [99]) among the available commercial battery types is suitable for size constrained wireless sensor nodes. However, during charging and discharging, the voltage of the Li-ion cell has to stay within specific maximum and minimum limits due to its chemical properties. If the voltage limits are exceeded, the cycle life of the battery may be shortened and even incurs possible risk of explosion [100-104].

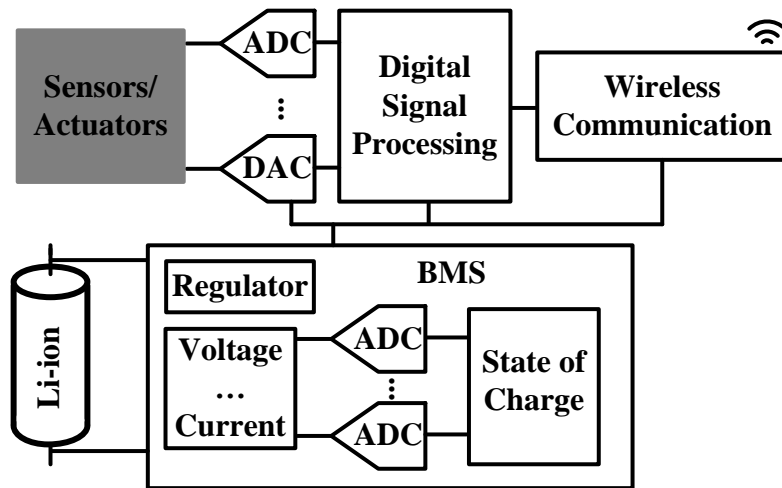


Fig. 6.1. Block diagram of a generic wireless sensor nodes powered by Li-ion battery.

For example, undercharging the Li-ion cell by 1.2% of its maximum voltage led to a 9% capacity loss [102]. It is therefore important to deploy a battery management system (BMS) to monitor the status of the Li-ion battery based on the measured battery voltage and current [94, 100-104]. Normally, a wide input range ADC is required to convert the Li-ion battery voltage, which can be as high as 4.2 V [44, 100-103].

Multiple ADCs are required to convert different analog signals in the wireless sensor node [44, 94, 95], as shown in Fig. 6.1, and it is not area- and energy- efficient. Thus, a low cost solution (see Fig. 6.2) that uses only one ADC with configurable input range to convert different analog signals, including the sensor signals and the Li-ion battery voltage is proposed in this chapter. The voltage of the Li-ion battery can be as high as 4.2 V [100-103] and the supply voltage of advanced CMOS process (e.g., 1.2 V for a 65 nm CMOS process) is much lower than 4.2 V. Therefore, it is important to design an ADC

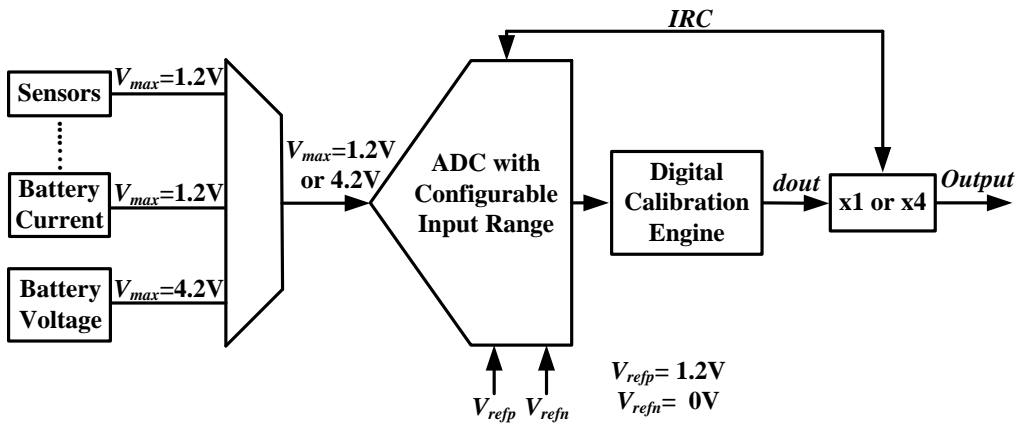


Fig. 6.2. The potential application of the ADC with configurable input range to convert analog signals with different range.

that can convert input signals with maximum voltage of 1.2 V or 4.2 V, while operating at 1.2 V supply.

This chapter presents a configurable input range (i.e., 1.2 V or 4.2 V) 12-bit SAR ADC with fast and low power digital background calibration. In conventional SAR ADC, the reference voltage has to be at least equal to the input range, i.e., the supply voltage should be at least 4.2 V to convert the 4.2-V

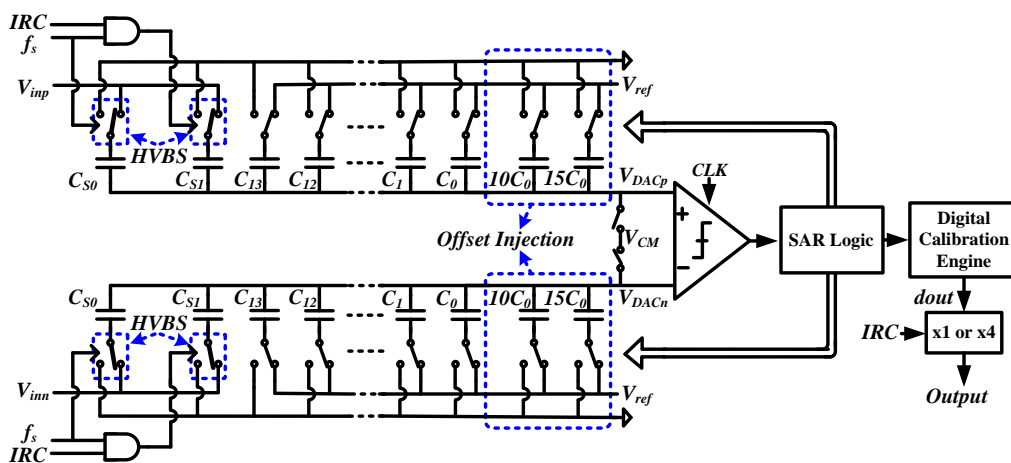


Fig. 6.3. The architecture of proposed differential SAR ADC.

Li-ion battery. However, in the proposed design, a supply voltage of 1.2 V can be used to convert the 4.2-V input signal. Therefore, the power consumption dissipated by the capacitor DAC and digital circuits in the ADC, which is proportional to square of the reference voltage, is significantly reduced. A high voltage bootstrapped switch (HVBS) is designed to sample the input signal that is higher than the supply voltage. Besides, a low power and fast convergence background digital calibration is used to moderate the capacitor mismatch in the capacitor DAC. By skipping the lower LSBs calibration, the number of multipliers used can be reduced, hence saving on power. By injecting different offsets to the input, the convergence time of the background digital calibration is shortened. This will be further discussed in Section 6.3.2.

6.1 Architecture of Proposed ADC with Configurable Input Range

The architecture of the proposed differential SAR ADC is given in Fig. 6.3. It is designed using the triple-well 65 nm CMOS process. It consists mainly of high voltage bootstrapped switch (HVBS), 14-bit SAR ADC (with 2 redundant bits for digital calibration) and a capacitor mismatch digital calibration engine. The input signal is sampled onto the sampling capacitors, C_{s0} and C_{s1} , where $C_{s1} = 3C_{s0}$. Following which, the sampled charge on the sampling capacitors is redistributed on the capacitor DAC. Thus, the internal nodes voltage, i.e., V_{DACp} and V_{DACn} , can be limited to less than the supply voltage, protecting the internal circuits from being exposed to high voltage. The sampled charge is adjusted by the signal IRC according to the range of the input signal. When $IRC = 1$, both C_{s0} and C_{s1} are used to sample the input signal, and the input range is

configured to 1.2 V. When $IRC = 0$, the switch controlling the C_{s1} is blocked by the AND gate. Only C_{s0} is used to sample the input signal, which implies that the input signal is attenuated by 4 due to the charge distribution between C_{s0} and C_{s1} ($C_{s1} = 3C_{s0}$). This allows the maximum input signal can be as large as 4.8 V, which covers the voltage of the Li-ion battery (i.e., 4.2 V). Using the proposed ADC to convert Li-ion battery voltage can significantly reduce the power consumption as compared to the conventional ADCs, which must be powered by a supply of at least 4.2 V. This is because the energy dissipated by the capacitor DAC and digital circuits in the ADC is proportional to the square of the supply voltage. When the conversion process ends, the output raw codes are sent to the digital calibration engine to calibrate the capacitor mismatch, i.e., the weights of some bits are calibrated. After digital calibration, the codes remain unchanged or will be multiplied by 4 before the final output, when IRC is set to 1 and 0, respectively.

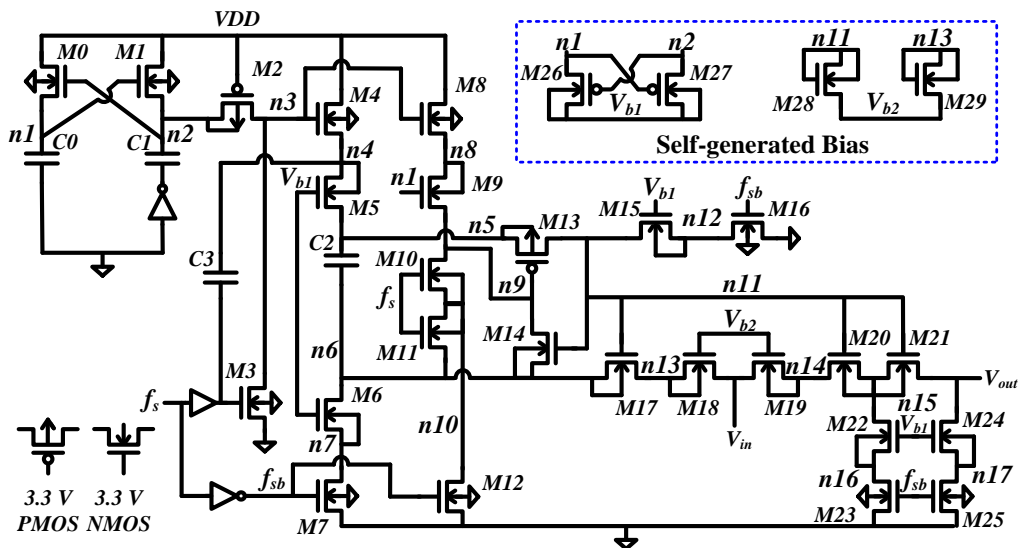


Fig. 6.4. The schematic of proposed HVBS.

6.2 High Voltage Bootstrapped Switch

Conventional high voltage bootstrapped switch utilizes drain-extended NMOS (DNMOS) transistors and the input range is limited by the drain terminal breakdown voltage [105, 106]. However, DNMOS is not available in the 65-nm CMOS process chosen for this work. The highest voltage transistors available in this process are 3.3-V IO triple well NMOS and 3.3-V PMOS. Therefore, some improvements based on the designs in [105, 106] have been made in the proposed high voltage bootstrapped switch (HVBS). Fig. 6.4 shows

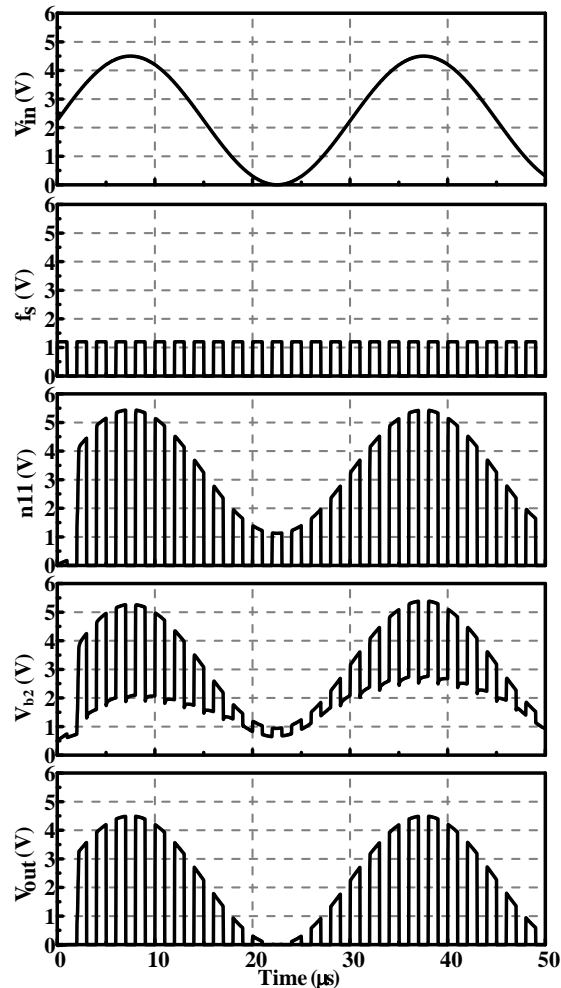


Fig. 6.5. Simulated waveforms of the proposed HVBS for a sinusoidal input with range of 0~4.5 V, operating at a supply voltage of 1.2 V and $f_s = 500$ kHz.

the schematic of the proposed HVBS, which deploys only 1.2-V and 3.3-V transistors, operating at 1.2 V and achieving an input swing of 0~4.5 V. Fig. 6.5 shows the simulated waveforms of the proposed HVBS for a sinusoidal input with range of 0~4.5 V, operating at 1.2 V and f_s is 500 kHz.

When f_s is active high, the voltage of $n5$ is $VDD+V_{in}$. Stacking a NMOS transistor $M5$ protects $M4$ from exposing to high voltage, i.e., $VDD+V_{in}$. The drain terminal of $M5$ (i.e., $n4$) is ideally boosted to $2VDD$ by the capacitor $C3$. The gate is biased by V_{b1} , which is $2VDD$. V_{b1} selects the higher voltage between $n1$ and $n2$ by alternatively turning on PMOS transistors $M26$ and $M27$. Similarly, $M7$ is protected by stacking a NMOS transistor $M6$. Stacking transistors $M22$ and $M2s4$ protect $M23$ and $M25$, respectively. Also, the added transistors $M22$ and $M24$ help to protect both $M23$ and $M25$ from the high input

Table 6.1 The Ideal Node Voltage of Each Node of The HVBS

Node	$f_s = 1$	$f_s = 0$
$n1$	$2VDD$	VDD
$n2$	VDD	$2VDD$
V_{b1}	$2VDD$	$2VDD$
$n3$	0	$2VDD$
$n4$	$2VDD$	VDD
$n5$	$VDD+V_{in}$	VDD
$n6$	V_{in}	0
$n7$	$\min(2VDD-V_{th}, V_{in})$	0
$n8$	$\min(2VDD-V_{th}, V_{in})$	VDD
$n9$	V_{in}	VDD
$n10$	$\min(VDD-V_{th}, V_{in})$	0
$n11$	$VDD+V_{in}$	0
$n12$	$\min(2VDD-V_{th}, VDD+V_{in})$	0
$n13$	V_{in}	$\min(V_{in}, 2VDD)$
V_{b2}	$VDD+V_{in}$	$\min(VDD+V_{in}, 2VDD)$
$n14$	V_{in}	$\min(V_{in}, 2VDD)$
$n15$	V_{in}	0
$n16$	$\min(2VDD-V_{th}, V_{in})$	0
$n17$	$\min(2VDD-V_{th}, V_{in})$	0
V_{out}	V_{in}	0

voltage. When f_s is active low, the voltage of $n11$ is zero. Therefore, $M18$ and $M19$ are added to protect $M17$ and $M22$ from the high voltage, i.e., V_{in} , which can be larger than the overdrive voltage of the 3.3-V transistors. The proposed HVBS is designed so that the maximum voltage between any two terminals of each transistor is less than 3.3 V. The ideal voltages on the nodes of the HVBS for both $f_s = 1$ and $f_s = 0$ are given in Table 6.1. The reliability of each transistor can also be referred from Table 6.1.

6.3 Fast Convergence and Low Power Digital Calibration

As discussed in Section 2.5, smaller unit size capacitor is preferred in capacitor DAC to achieve low power consumption. However, small unit size capacitor suffers from capacitor mismatch, which must therefore be calibrated for high resolution ADCs. Various calibration methods have been reported in [48, 50, 52, 54-59]. In this design, we proposed a low power and fast convergence digital background calibration scheme based on the perturbation-based calibration [50]. The low power is achieved by skipping the calibration for several LSBs. While the fast convergence is realised by injecting different analog offset values during calibration.

6.3.1 Principle of Perturbation-Based Calibration

In conventional binary (i.e., radix-2) SAR ADC, each analog input is mapped onto one unique digital code as shown in the transfer curve in Fig. 6.6(a). It is therefore not possible to correct the capacitor mismatch [50]. Fig. 6.6(b) and Fig. 6.6(c) present transfer curves of the super-radix-2 and sub-radix-

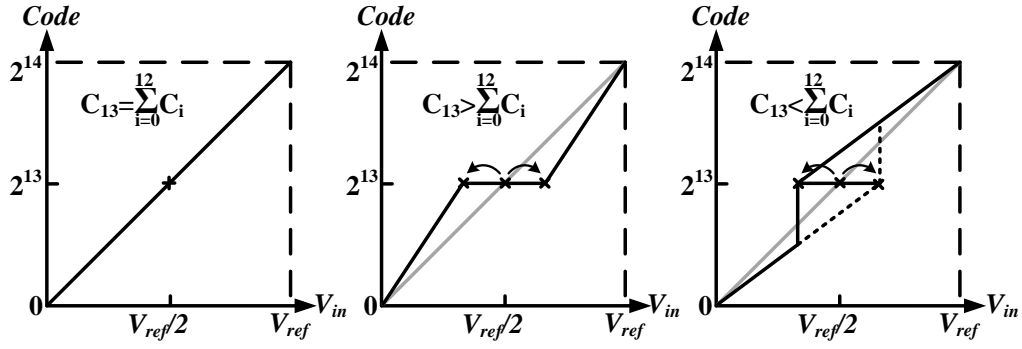


Fig. 6.6. Transfer curves of three ADCs: (a) radix-2, (b) super-radix-2, (c) sub-radix-2.

2 SAR ADCs, respectively, assuming only MSB capacitor suffers mismatch error. Since multiple analog inputs are mapped onto one digital code in the transfer curve of super-radix-2 SAR ADC, the analog information is lost and it is not digitally correctable. However, in the sub-radix-2 SAR ADC, one analog input can map onto multiple digital codes and some digital codes will not surfaced. Therefore, all information of the analog input is reserved and the capacitor mismatch is correctable in sub-radix-2 SAR ADC. A radix of 1.85 is chosen in our design, resulting in 14 conversion steps to achieve 12 bits.

In the absent of capacitor mismatch in the SAR ADC, the transfer curve can be modelled as a linear system, which follows the superposition principle. Fig. 6.7(a) shows shifting of transfer curve when an analog offset (i.e., Δ_a) is added to the input signal. Mathematically, the shifting of transfer curve can be expressed as:

$$Q(V_{in} \pm \Delta_a) = Q(V_{in}) \pm Q(\Delta_a) \quad (6.1)$$

If we denote $Q(\Delta_a) = \Delta_a$, then Equation (6.1) can be rewritten as:

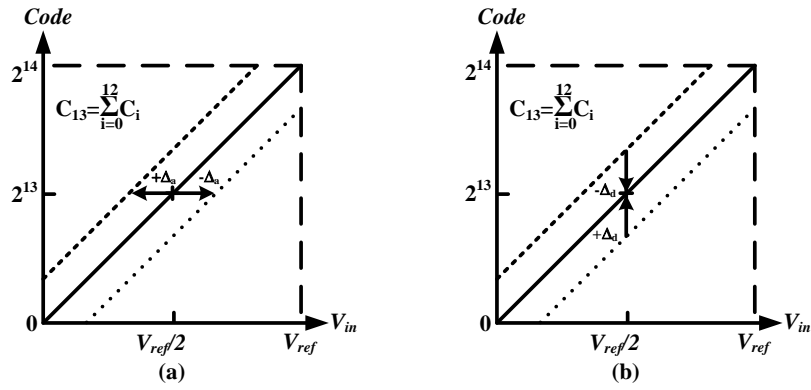


Fig. 6.7. Illustrations of perturbation in linear transfer curve of SAR ADC.

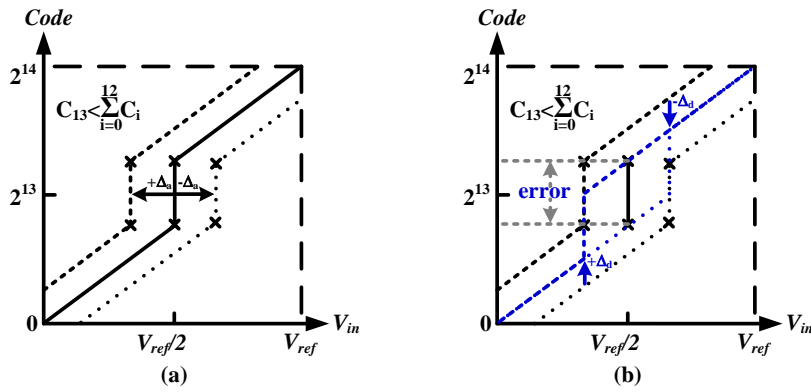


Fig. 6.8. Illustrations of perturbation of a transfer curve with capacitor mismatch in SAR ADC.

$$Q(V_{in}) = Q(V_{in} \pm \Delta_a) \mp \Delta_d \quad (6.2)$$

Equation (6.2) indicates that the analog offset Δ_a can be removed in digital domain, provided the transfer curve of the ADC is a linear system or $Q(\Delta_a) = \Delta_d$. Fig. 6.7(b) shows that the analog offset is precisely removed in digital domain. However, with capacitor mismatch as demonstrated in Fig. 6.8, the analog offset cannot be removed through simply shifting the transfer curve by Δ_d in the SAR ADC. The shifted lines forms a discrepancy window with an error which

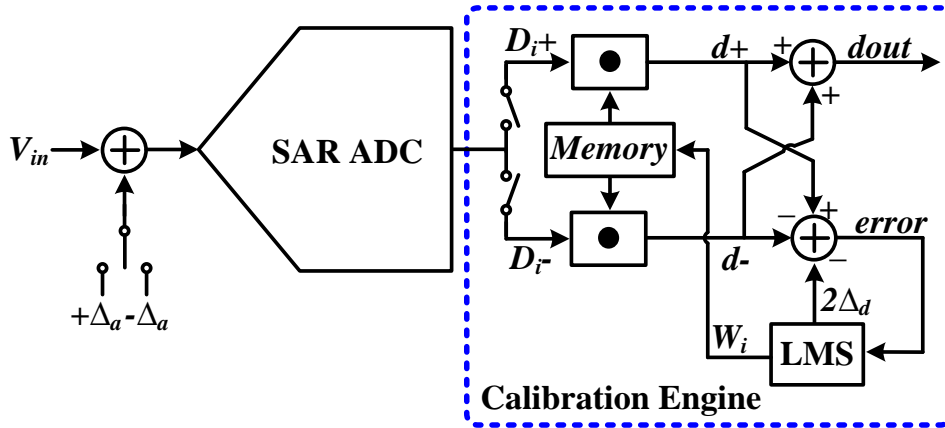


Fig. 6.9. Block diagram of perturbation-based digital calibration scheme.

is $2\Delta_d$. If the MSB mismatch is calibrated or the transfer curve is calibrated to be a linear system, the error will be zero.

Based on this, the perturbation-based background digital calibration was proposed in [50], which has been briefly introduced in Section 2.5. The block diagram of this calibration scheme is re-presented in Fig. 6.9 for convenience. The operation of this calibration scheme is described as follows. Two analog offsets (i.e., $+\Delta_a$ and $-\Delta_a$) with same amplitude are added to the same input signal V_{in} . Following which, the SAR ADC performs data conversion twice for each input signal with an opposite polarity offset signal value, resulting two 14-bits raw codes, i.e., D_{i+} and D_{i-} . These raw codes are sent to calibration engine to calibrate the weight of each bit. First, D_{i+} and D_{i-} are multiplied with the same weights W_i , and summed as d_+ and d_- , respectively. The error between these two conversion results is calculated by subtracting $2\Delta_d$ from the difference between d_+ and d_- . This error should be zero if the transfer curve of the ADC is linear or the optimal weights are obtained by the calibration engine. The weights W_i are updated through the least mean square (LMS) function till the

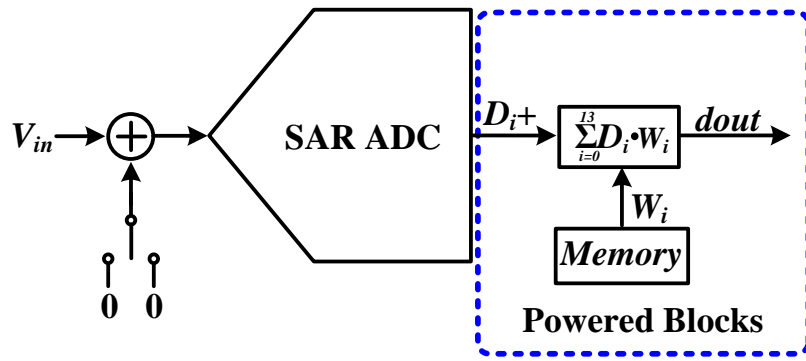


Fig. 6.10. Blocks of the ADC those are powered on after the optimal weights are obtained.

error is driven to zero. The update equations of the LMS learning procedure can be written as:

$$W_i[n+1] = W_i[n] - \mu_w \text{error}[n](b_{+i}[n] - b_{-i}[n]) \quad i = 0, 1, \dots, 13 \quad (6.3)$$

$$\Delta_d[n+1] = \Delta_d[n] + \mu_\Delta \text{error}[n] \quad (6.4)$$

where μ_w and μ_Δ are the step sizes of the above equations.

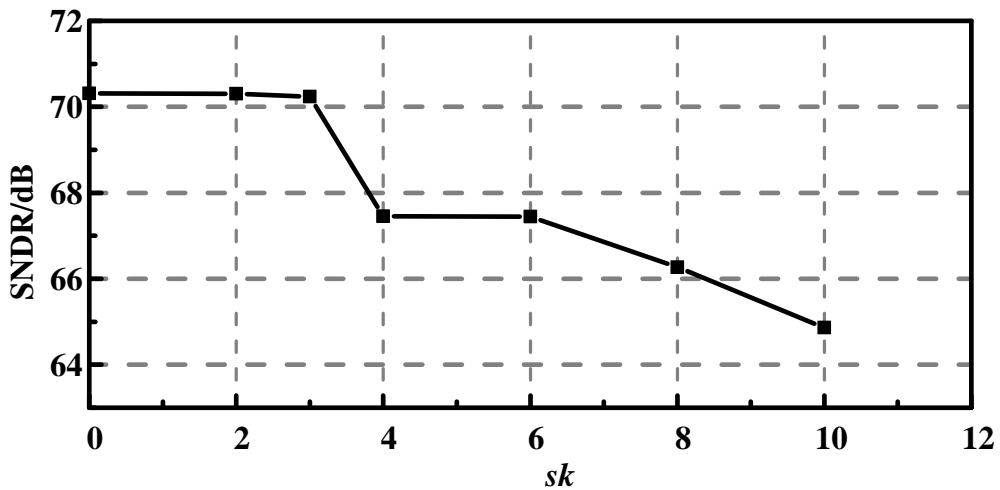


Fig. 6.11. SNDR of the ADC after calibration for different number of LSBs that are without weight calibration.

After the learning procedure is completed, the optimal weights are stored in the memory for further calculation. The capacitor mismatch only depends on the process mismatch and it only requires one time power-on calibration. Therefore, most of the circuit blocks of the calibration engine, except for the memory and the circuits that calculate the weighted sum of the raw code, can be powered off to save on power consumption, as shown in Fig. 6.10. On the other side, the optimal weights stored in the memory will be lost when it is powered off. The ADC needs calibration every time it is powered on. Therefore, a fast convergence calibration scheme is also preferred to obtain more conversion data with correct value.

6.3.2 Low Power and Fast Convergence Calibration Scheme

As discussed above, the power dissipated by the calibration engine during the optimization process of the weights is not significant. This is because the

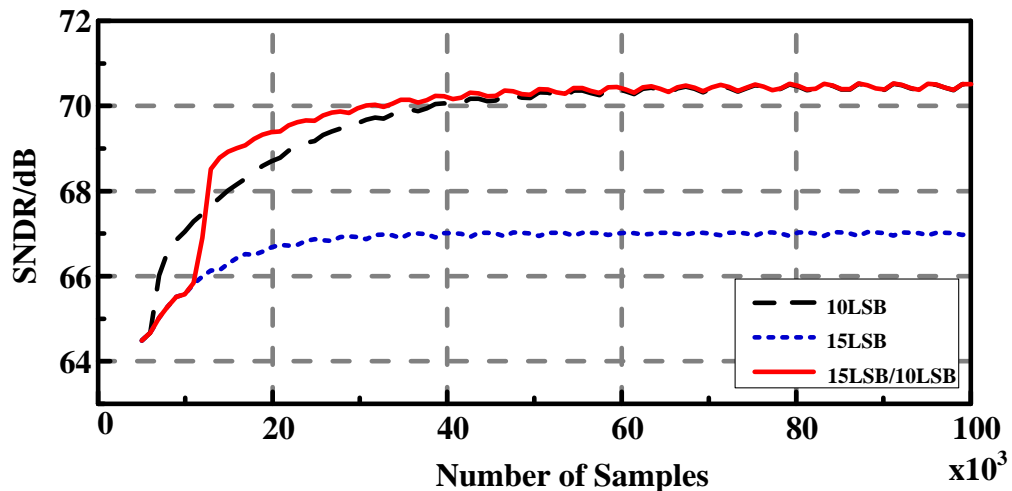


Fig. 6.12. SNDR of the ADC after calibration with 10 LSB, 15 LSB and 15 LSB/10 LSB analog offset.

ADC requires only one time power-on calibration. After the optimal weights are

presented in Fig. 6.11. It can be seen that the SNDR has a minimum reduction when sk is 3, i.e., the 3 LSBs skip weight calibration. Therefore, in our design we skip calibration for the 3 LSBs. By doing this, the required multiplications can be reduced from 14 to 11, saving power consumption after the optimal weights are obtained.

From the update equations of the LMS algorithm, i.e., Equation (6.5) and (6.6), it can be observed that with larger *error*, the convergence of the LMS is faster. In other words, with larger analog offset Δ_a in Fig. 6.9, the LMS converge sooner. However, the accuracy of the LMS is worsen when large analog offset or *error* is applied. In order to speed up the LMS convergence while maintaining the same accuracy, an adaptive analog offset perturbation approach is proposed. 15-LSB analog offset is applied to the first 10000 samples while the rest of the samples are injected with 10-LSB analog offset. The behavior of the adaptive analog offset perturbation is created in Matlab and the simulation result is shown in Fig. 6.12. It can be seen that the proposed

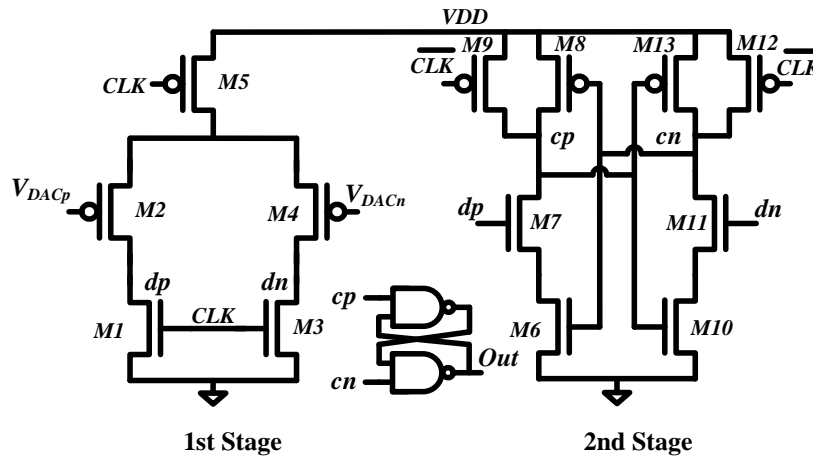


Fig. 6.14. Schematic of the two stage dynamic comparator.

Table 6.2 The Values of The Capacitors

	Ideal (fF)	Extracted (fF)	10% Mismatch (fF)		Ideal (fF)	Extracted (fF)	10% Mismatch (fF)
C_0	0.5	0.53	0.46	C_7	37	39.69	36.91
C_1	0.5	0.53	0.57	C_8	68.5	73.49	68.49
C_2	1.5	1.61	1.58	C_9	126.5	135.74	125.53
C_3	3	3.22	3.11	C_{10}	234.5	251.62	233.82
C_4	5.5	5.9	5.49	C_{11}	434	465.68	434.83
C_5	10.5	11.26	10.52	C_{12}	803.5	862.16	801.88
C_6	20	21.45	19.95	C_{13}	1486.5	1595.02	1487.31

adaptive offset perturbation scheme, i.e., 15-LSB/10-LSB, achieves a faster convergence than merely injecting a 10-LSB analog offset, while maintaining a similar SNDR.

The block diagram of the proposed low power and fast convergence digital background calibration scheme is given in Fig. 6.13. The weights of the 3 LSBs are not calibrated and they are kept constant, i.e., $W_0 = 1$, $W_1 = 1$, $W_2 = 3$. Therefore, the proposed calibration scheme is able to save three multiplication steps and hence power saving as compared to the conventional design [50]. A counter is used to control adding 15-LSB analog offset to the first 10000 input samples for fast convergence purpose.

6.4 Circuit Implementation

The capacitor DAC utilizes customized metal-oxide-metal (MOM) capacitors with minimum value of 0.5 fF. Table 6.2 lists the values of the ideal 1.85-radix capacitors, extracted layout value of the MOM capacitors and the capacitors that were engaged in the simulation which were randomly generated with 10% mismatch.

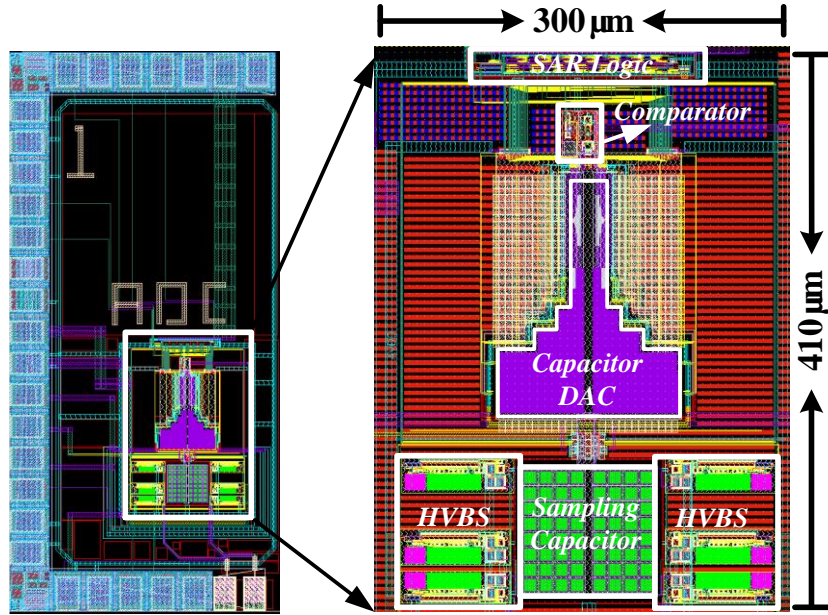


Fig. 6.15. Layout of the proposed SAR ADC.

A two-stage dynamic comparator [85] consisting of a dynamic preamp and a latch is deployed in this design, as shown in Fig. 6.14. The Monte Carlo simulation shows that the mean offset of the comparator is 0.5 mV with sigma equal to 3.1 mV. The offset can be calibrated in digital domain. And the input referred noise is of 65 μV , i.e., about one-fourth of the LSB.

6.5 Simulation Results

The proposed differential SAR ADC is implemented in a 1.2-V 65 nm process with an active area of $410 \times 300 \mu\text{m}^2$. The layout is as shown in Fig. 6.15. The following simulation results of the SAR ADC are obtained by schematic simulation using Cadence and the calibration engine is simulated on Matlab. The step sizes of LMS equations, i.e., μ_w and μ_A , are both optimized at $1/2^7$ by simulation.

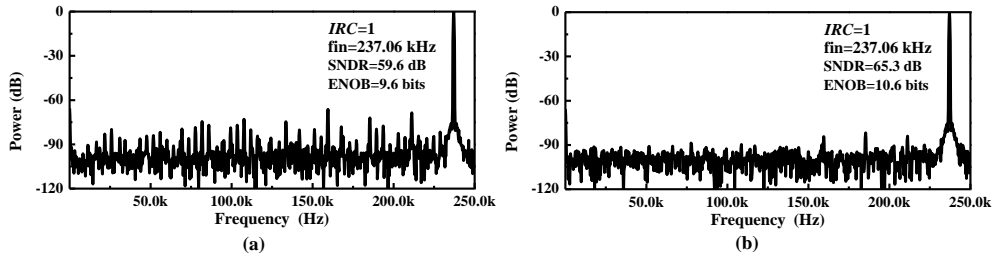


Fig. 6.16. Output spectrum of the ADC with an input range of $2.4 V_{pp}$ operating at 500 kS/s and 1.2 V: (a) before calibration, (b) after calibration.

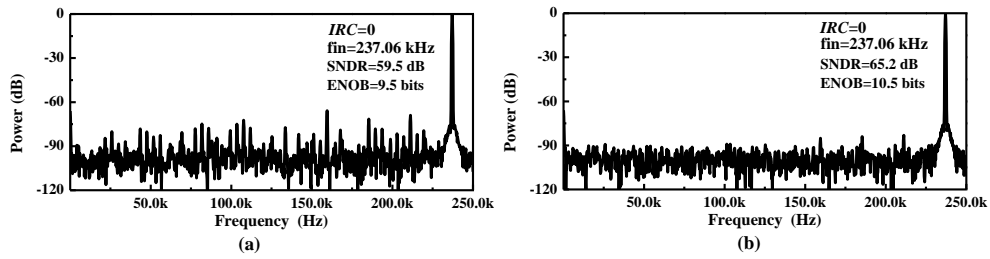


Fig. 6.17. Output spectrum of the ADC with an input range of $9.6 V_{pp}$ operating at 500 kS/s and 1.2 V: (a) before calibration, (b) after calibration.

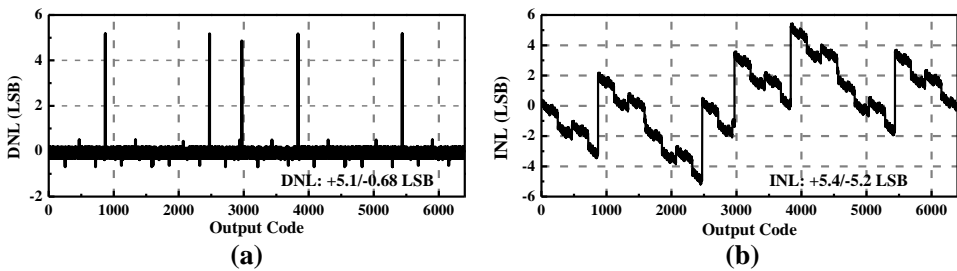


Fig. 6.18. Simulated DNL and INL before calibration.

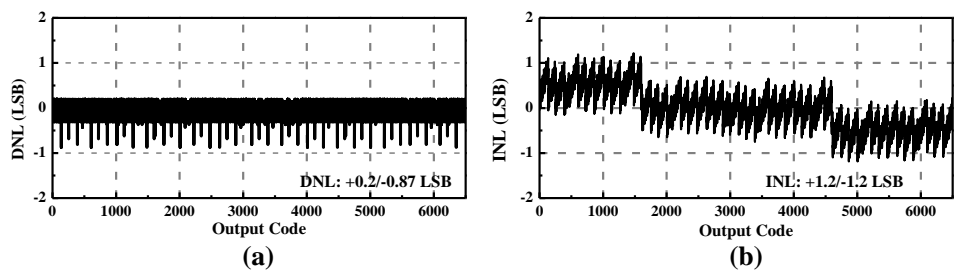


Fig. 6.19. Simulated DNL and INL after calibration.

Fig. 6.16 and Fig. 6.17 show the output spectrum of the proposed SAR ADC with input range of $2.4 V_{pp}$ ($IRC = 1$) and $9.6 V_{pp}$ ($IRC = 0$), respectively, operating at 500 kS/s and 1.2 V supply voltage. After calibration, the SNDR of

Table 6.3 ADC Performance Summary

Process (nm)	65	
Power Supply (V)	1.2	
Input Range (V)	0~1.2/0~4.8	
Sampling Rate (kS/s)	500	
SNDR (dB) ($f_{in}=237.06$ kHz)	65.3/65.2	
ENOB (bits)	10.6/10.5	
DNL (LSB)	+0.2/-0.87	
INL (LSB)	+1.2/-1.2	
Power (μW) (Except Calibration)	HVBS	1.2
	V_{ref}	5.28
	Comparator	1
	SAR Logic	0.91
	Total	8.39
Core Area (mm²)	0.123	

the ADC with input range of $2.4 V_{pp}$ and $9.6 V_{pp}$ are 65.3 dB (10.6 bits) and 65.2 dB (10.5 bits), respectively. The SNDR is improved by 5.7 dB using the proposed low power and fast convergence background digital calibration scheme. The linearity performance of the proposed ADC with input range of $9.6 V_{pp}$ was also simulated. Before calibration, the simulated DNL and INL are $+5.1/-0.68$ LSB and $+5.4/-5.2$ LSB, respectively, as shown in Fig. 6.18. After calibration, DNL and INL are improved to $+0.2/-0.87$ LSB and $+1.2/-1.2$ LSB (see Fig. 6.19), respectively. The performance of the proposed SAR ADC is summarized in Table 6.3.

6.6 Conclusion

This chapter presents a configurable input range 12-bit SAR ADC with fast and low power digital background calibration. The power consumption of the system can be reduced by utilizing only one ADC with configurable input range to convert different analog signals, including the sensor signals and the Li-ion battery voltage. We present a high voltage bootstrapped switch which operates

at 1.2 V and achieves an input swing of 0~4.5 V. Besides, a low power and fast convergence digital background calibration scheme based on the perturbation-based calibration is presented. The low power is achieved by skipping the calibration for several LSBs. While the fast convergence is realised by injecting different analog offset values during calibration. The simulation results show that the SNDR is improved by 5.7 dB using the proposed low power and fast convergence background digital calibration scheme.

Chapter 7

Conclusion and Future Work

7.1 Conclusion

Successive approximation register analog-to-digital converters with high energy efficiency have been widely used in the sensing applications. This thesis focuses on designing low power SAR ADCs with various energy efficient techniques. The first proposed technique is based on ultra-low supply voltage, i.e., operating at 0.5 V. Clock boosting circuit is also designed to improve the linearity of the sampling switch when powered by the ultra-low supply voltage. The power consumption of the novel ADC is significantly reduced due to the digital nature of the SAR ADC.

When the ADC is used to convert sparse signals, such as neural spike and ECG, some of the MSBs of the conversion results are left unchanged between two consecutive samples. By deploying this characteristic, we proposed a low power architecture which we named an adaptive delta-sampling SAR ADC. By sampling only the incremental value of the input signal and adaptively adjusting the sampling frequency, the ADC can achieve the same resolution and conversion range with less number of bits than the conventional ADC. Meanwhile, the power consumption is also very much reduced. To validate the proposed design, the SAR ADC has been used to convert pre-recorded neural signals. The measurement results showed that the proposed SAR ADC achieves

a power reduction of 88% when compared with the conventional capacitor splitting SAR ADC.

Even though the power consumption of the ADC itself is reduced both by operating at ultra-low supply voltage and by adopting the adaptive delta-sampling architecture, additional efforts to further reduce the power dissipated by the peripheral circuits that provide the reference voltage to the ADC were explored. A SAR ADC with self-timed pre-charging is proposed to eliminate the power- and area-consuming reference-voltage regulator and decoupling capacitor for wireless-powered implantable medical devices. The measurement results showed that the SNDR of the SAR ADC did not decrease when the supply voltage fluctuation is up to 50 mV_{pp}. In other words, the proposed SAR ADC is able to function without the reference-voltage regulator and decoupling capacitor. Hence, the proposed SAR ADC achieves high energy efficiency at the system level.

Lastly, a wide input 12-bit SAR ADC with low power and fast convergence background digital calibration is presented in this thesis. A high voltage bootstrapped switch is designed to sample the input signal with a voltage swing of 0~4.8 V, and operating at 1.2 V supply voltage. In wireless sensor nodes powered by Li-ion battery, the proposed ADC with configurable input range can be used to convert different analog signals, including the sensor signals and Li-ion battery voltage. For each input signal, the SAR ADC performs two rounds of data conversion, each with opposite polarity offset. Following which, the least mean square algorithm based calibration engine optimizes the weight of each bit till the error between the two conversion results is driven to zero. Optimization of the 3 LSBs is omitted in the proposed design. Hence, the

number of multiplication steps can be reduced by three to save on power consumption, and this is with minimum disturbance to the SNDR.

An adaptive offset perturbation scheme, i.e., 15-LSB/10-LSB, to achieve a faster convergence than merely injecting a 10-LSB analog offset while maintaining a similar SNDR has also been designed. The schematic of the SAR ADC is simulated on Cadence and the calibration engine is simulated on Matlab. After calibration, the SNDR of the ADC is improved by 5.7 dB assuming that the capacitor mismatch is 10%.

7.2 Future Work

Reducing the power consumption of the SAR ADC is one of the main challenges in wireless sensor node. Operating at ultra-low voltage along with minimally sufficient sampling rate is one of the circuit design approaches to reduce the power consumption. The deployment of even lower supply voltage (less than 0.5 V) can be explored to further reduce the power consumption. The cascaded voltage boosting circuit [30] is able to improve the linearity of the sampling switch even when it is operating at 160 mV supply voltage. Besides, when the ADC operating at lower sampling rate (less than 1 kS/s), some leakage control techniques would needed to be developed to reduce leakage of the charges stored on the capacitor arrays. With the lowering of supply voltage, both power gating and clock gating techniques can be adopted to minimize the foreseeable leakage current of the circuits. In advanced 65 nm process, power gating can use high threshold voltage transistors as switches to shut off power supplies to parts of the SAR ADC that are in standby mode.

The architecture of the adaptive-delta sampling ADC can incorporate ultra-low voltage design to further reduce the power consumption. The rail-to-rail comparator and the fully differential amplifier based slope detector will be the two challenging circuit blocks, when operating at ultra-low voltage. Low threshold voltage NMOS transistors (available in advanced process) can be used as the input transistors in the amplifier designs to enable the comparator and the slope detector to function at ultra-low voltage. The integration of reference-voltage regulator is also important to ensure that the adaptive-delta sampling SAR ADC is compatible with the sensor node systems. The drivability requirement of the reference-voltage regulator needed in the adaptive-delta sampling SAR ADC is more relaxable than that needed in the conventional SAR ADC. This is because the power consumed by the capacitor arrays of the adaptive-delta sampling SAR and the conventional SAR ADC are 30.5 nW and 1200 nW, respectively, where the power reduction is of 39 times.

The charge-sharing SAR ADC featured with reference-voltage regulator free is an attractive design with high energy efficiency at system level. Further research to reduce power consumption of the input buffer of the ADC is a potential approach to reduce the system power dissipation. A power efficient variable-gain transconductor is able to replace the power hungry input voltage buffer in a charge-sharing SAR ADC to improve the overall power efficiency [42]. Besides, MOSFET used as the unit capacitor (MOSCAP) can significantly reduce the power consumed by the capacitor DAC since the smallest available MIM capacitor value in the used 0.18- μm process is 39 fF, which is about ten times of that of the MOSCAP. [107] demonstrates a charge-sharing SAR ADC

that employs only MOSCAP in the capacitor DAC and achieves high energy efficiency.

The low power and fast convergence calibration scheme for the wide input 12-bit SAR ADC is necessary to be implemented on FPGA or ASIC to verify its performance. Because the 12-bit SAR ADC has a natural serial output, the multiplier used in the calibration scheme can be a folding structure as suggested in [50]. Besides, the tapeout of this 12-bit SAR ADC is important and the measurement of the reliability of the HVBS is also necessary. The proposed digital calibration is an effective method to calibrate the mismatch of the capacitors in the capacitor DAC and hence improve the SNDR of the ADC. Therefore, this calibration technique that is without additional analog circuits can be incorporated in the proposed low power ADC architectures, i.e., adaptive-delta sampling ADC and reference-voltage regulator-free ADC, to design 12-bit SAR ADCs that are with low power consumption.

Appendices

Table A.1 Transistors' size of Fig. 3.2

	W/L ($\mu\text{m}/\mu\text{m}$)		W/L ($\mu\text{m}/\mu\text{m}$)
M1	0.46/0.18	M4	0.46/0.18
M2	0.46/0.18	M5	0.46/0.18
M3	0.46/0.18		

Table A.2 Transistors' size of Fig. 3.6

	W/L ($\mu\text{m}/\mu\text{m}$)		W/L ($\mu\text{m}/\mu\text{m}$)
M1	0.36/0.18	M4	0.50/0.18
M2	0.50/0.18	M5	1.40/0.18
M3	1.40/0.18	M6	0.46/0.18

Table A.3 Transistors' size of Fig. 3.7

	W/L ($\mu\text{m}/\mu\text{m}$)		W/L ($\mu\text{m}/\mu\text{m}$)
M1	1.00/0.18	M4	1.00/0.18
M2	1.00/0.18	M5	1.00/0.18
M3	1.00/0.18	M6	1.00/0.18

Table A.4 Transistors' size of Fig. 4.4 (b)

	W/L ($\mu\text{m}/\mu\text{m}$)		W/L ($\mu\text{m}/\mu\text{m}$)
M1	20.0/5.00	M5	8.00/10.0
M2	8.00/10.0	M6	4.00/15.0
M3	4.00/15.0	M7	5.00/5.00
M4	20.0/5.00		

Table A.5 Transistors' size of Fig. 4.10

	W/L ($\mu\text{m}/\mu\text{m}$)		W/L ($\mu\text{m}/\mu\text{m}$)
M1	15.0/0.50	M10	3.00/1.00
M2	15.0/0.50	M11	0.50/0.30
M3	10.0/0.50	M12	0.50/0.30
M4	10.0/0.50	M13	5.00/1.00
M5	2.00/20.0	M14	0.50/0.30
M6	2.00/1.00	M15	3.00/1.00
M7	2.00/1.00	M16	3.00/1.00
M8	5.00/1.00	M17	3.00/1.00
M9	0.50/0.30		

Table A.6 Transistors' size of Fig. 4.11

	W/L ($\mu\text{m}/\mu\text{m}$)		W/L ($\mu\text{m}/\mu\text{m}$)
M1	2.00/1.00	M16	15.0/0.50
M2	10.0/0.50	M17	2.00/1.00
M3	2.00/1.00	M18	15.0/0.50
M4	10.0/0.50	M19	2.00/1.00
M5	2.00/10.0	M20	2.00/20.0
M6	3.00/1.00	M21	3.00/1.00
M7	3.00/1.00	M22	5.00/1.00
M8	5.00/1.00	M23	5.00/1.00
M9	0.50/0.30	M24	0.50/0.30
M10	0.50/0.30	M25	0.50/0.30
M11	3.00/1.00	M26	3.00/1.00
M12	3.00/1.00	M27	5.00/1.00
M13	5.00/1.00	M28	5.00/1.00
M14	0.50/0.30	M29	0.50/0.30
M15	0.50/0.30	M30	0.50/0.30

Table A.7 Transistors' size of Fig. 5.7

	W/L ($\mu\text{m}/\mu\text{m}$)		W/L ($\mu\text{m}/\mu\text{m}$)
M1	5.00/1.00	M8	0.46/0.18
M2	10.0/1.00	M9	0.46/0.18
M3	5.00/1.00	M10	0.46/0.18
M4	10.0/1.00	M11	0.46/0.18
M5	1.00/0.18	M12	0.46/0.18
M6	20.0/1.00	M13	0.46/0.18
M7	0.46/0.18		

Table A.8 Transistors' size of Fig. 5.8

	W/L ($\mu\text{m}/\mu\text{m}$)		W/L ($\mu\text{m}/\mu\text{m}$)
M1	0.46/20.0	M2	5.00/10.0

Table A.9 Transistors' size of Fig. 5.9

	W/L ($\mu\text{m}/\mu\text{m}$)		W/L ($\mu\text{m}/\mu\text{m}$)
MN1	10.0/5.00	M5	43.0/0.50
MN2	20.0/5.00	M6	4.00/10.0
M3	1.00/10.0	M7	0.46/20.0
M4	1.00/10.0	M8	0.46/0.18

Table A.10 Transistors' size of Fig. 5.11

	W/L ($\mu\text{m}/\mu\text{m}$)		W/L ($\mu\text{m}/\mu\text{m}$)
M1	1.00/0.30	M12	2.00/0.50
M2	10.0/1.00	M13	1.00/0.50
M3	1.00/0.30	M14	0.30/0.18
M4	10.0/1.00	M15	0.60/0.36
M5	5.00/1.00	M16	1.20/0.72
M6	2.50/1.00	M17	2.40/1.44
M7	2.00/0.50	M18	0.30/0.18
M8	2.00/0.50	M19	0.60/0.36
M9	1.00/0.50	M20	1.20/0.72
M10	2.50/1.00	M21	2.40/1.44
M11	2.00/0.50		

Table A.11 Transistors' size of Fig. 6.4

	W/L ($\mu\text{m}/\mu\text{m}$)		W/L ($\mu\text{m}/\mu\text{m}$)
M0	0.32/0.50	M15	0.32/0.50
M1	0.32/0.50	M16	0.32/0.50
M2	0.40/0.32	M17	0.32/0.50
M3	0.32/0.50	M18	1.00/0.50
M4	0.50/0.50	M19	10.0/0.50
M5	0.50/0.50	M20	10.0/0.50
M6	0.32/0.50	M21	10.0/0.50
M7	0.32/0.50	M22	0.32/0.50
M8	0.50/0.50	M23	0.32/0.50
M9	0.50/0.50	M24	5.00/0.50
M10	0.32/0.50	M25	5.00/0.50
M11	0.32/0.50	M26	0.50/0.50
M12	0.32/0.50	M27	0.50/0.50
M13	0.32/0.50	M28	1.00/0.50
M14	0.32/0.50	M29	10.0/0.50

Table A.12 Transistors' size of Fig. 6.14

	W/L ($\mu\text{m}/\mu\text{m}$)		W/L ($\mu\text{m}/\mu\text{m}$)
M1	1.00/1.00	M8	0.50/0.20
M2	5.00/0.25	M9	0.20/0.06
M3	1.00/1.00	M10	0.50/0.20
M4	5.00/0.25	M11	1.00/0.50
M5	1.00/0.50	M12	0.50/0.20
M6	0.50/0.20	M13	0.20/0.06
M7	1.00/0.50		

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Journal

1. **Y. Yang**, J. Zhou, X. Liu, J. H. Cheong and W. L. Goh, "A 151-nW Adaptive Delta-Sampling ADC for Ultra-Low Power Sensing Applications," *IEEE Transactions on Circuits and Systems II*, vol. 63, no. 7, pp. 638-642, 2016.
2. X. Liu, J. Zhou, C. Wang, K. H. Chang, J. Luo, J. Lan, L. Liao, Y. Lam, **Y. Yang**, B. Wang, X. Zhang, W. L. Goh, T. T. Kim and M. Je, "An Ultralow-Voltage Sensor Node Processor With Diverse Hardware Acceleration and Cognitive Sampling for Intelligent Sensing," *IEEE Transactions on Circuits and Systems II*, vol. 62, no. 12, pp. 1149-1153, 2015
3. X. Liu, J. Zhou, **Y. Yang**, B. Wang, J. Lan, C. Wang, J. Luo, W. L. Goh, T. T. Kim and M. Je, "A 457 nW Near-Threshold Cognitive Multi-Functional ECG Processor for Long-Term Cardiac Monitoring," *IEEE Journal of Solid-State Circuit*, vol. 49, no. 11, pp. 2422-2434, 2014.

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4. C. Wu, W. L. Goh, **Y. Yang**, A. Chang, X. Zhu and L. Wang, "A Start-Up Free 200 nW Bandgap Voltage Reference," in *New Circuits and Systems Conference (NEWCAS), 2016 IEEE 14th International*, 2016.
5. **Y. Yang**, W. L. Goh, J. Zhou, J. H. Cheong and X. Liu, "Ultra-Low Power Delta Sampling SAR ADC for Sensing Applications," in

Electron Devices and Solid-State Circuits (EDSSC), 2015 IEEE International Conference on, 2015, pp.213-216.

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8. X. Liu, J. Zhou, **Y. Yang**, B. Wang, J. Lan, C. Wang, J. Luo, W. L. Goh, T. T. Kim and M. Je, “A 457-nW Cognitive Multi-Functional ECG Processor,” in *Solid-State Circuits Conference (A-SSCC), 2013 IEEE Asian*, 2013, pp. 141-144.
9. H. F. Nurhuda, **Y. Yang** and W. L. Goh, “A three-topology based, wide input range switched-capacitor DC-DC converter with low-ripple and enhanced load line regulations,” in *2014 International Symposium on Integrated Circuits (ISIC)*, 2014, pp. 13-16.

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